Interfaces in nanoscale photovoltaics

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Interfaces in Nanoscale Photovoltaics

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INTERFACES IN NANOSCALE PHOTOVOLTAICS

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Introduction

1.1 Photovoltaics

Photovoltaics provide electricity in a clean, sustainable and often decentralized way by utilizing an abundant and virtually unlimited source of energy: the sun. 177 years after Alexandre Edmond Becquerel created the first photovoltaic device, the technology is on its way to become a major source for primary electrical energy production on earth.[1] In June 2014, solar energy was able to provide 23 GW power, more than half of the electricity demand in Germany at that time, rendering arguments about production capabilities limited to southern countries meaningless.[2] At the end of 2015, after growing for 20% three years in a row, the US solar energy industry alone employed more people than the upstream oil and gas sectors combined (exploration, drilling, extraction), continuing to pave the way for societal and political support from a wide spectrum.[3] Due to the continuing decrease in solar panel costs, financing costs and balance of system costs, by 2017 80% of countries in the world are expected to have reached grid parity according to a recent forecast by the Deutsche Bank.[4]. Currently, solar energy installations account for over 50% of newly installed electricity capacity, therefore outperforming not only gas, and oil but even coal as a primary source of electricity.[5] Alone in 2016, 65 GW solar power are expected to be installed, which would result in a total of roughly 300 GW cumulative installed solar power by the end of the year, an equivalent of 600 typical coal power plants (~ 500 MW). Per year, two billion tons of CO₂ emissions alone will be saved, not to mention the emission of hundreds of thousands of tons of other dangerous toxins.[6]

As a result, in 2050 renewable energies are predicted to provide between 50-90 % of the total energy demand, with wind and solar energy as the major contributors.[7] And these estimates don’t even take into consideration the looming invalidation of the free ticket of many technologies to unaccountably
dispose their waste into the environment. Such "externalities" have to be taken into account when calculating the true costs of energy conversion technologies.

To summarize, solar energy not only proved its technical feasibility and its potential for tackling climate change but also its capability as a major economic player by competing against fossil fuel-based technologies. As a result, even traditional economic fossil fuel strongholds such as the World Economic Forum in Davos have put renewable energy and climate change on their agenda.\[8\]

On the technological side, wafer-based silicon solar cells are the major driver (over 90%) of increased installations. Based on the maturity of the wafer-based silicon technology (over 62 years), the power conversion efficiency has entered a phase of logarithmic increase over time. Currently, the Kaneka IBC HIT cell is the record holder with an efficiency of 26.3%. In other words, 89.5% of the theoretical maximum efficiency of 29.4% has already been reached.\[9, 10\] Forecasts predict an ongoing market domination of this technology with improved module efficiencies, decreased production and decreased balance of system (BOS) costs (wiring, converter, mounts,...) as the major drivers for future cost reductions.

In general, attempts to lower the overall solar energy production costs ($/W$) further can broadly be divided into two classes. Either the fabrication costs are reduced while the efficiency is maintained or the efficiency is increased while the production costs are maintained (or slightly increased).

Besides economies of scale, reducing the fabrication costs while maintaining the conversion efficiency can be achieved by optimizing processes, replacing materials or device designs with more energy, work or material efficient options. These approaches are usually pursued in industrial research laboratories or in close collaborations between industrial and academic research centers. In those cases, the requirements and knowledge about the state of the art in the industrial production is clearly communicated to the researchers.\*  

The pursuit for higher power conversion efficiencies, on the other hand, falls directly into the field of expertise of fundamental researchers. More efficient solar cells generally require higher production costs, especially at initial stages before improved processes and economies of scale take place. However, since less solar module area is required to produce the same amount of energy as the existing technology, the effect on the other costs, such as installation, operational and legal (BOS) costs can be profound. Given that the costs of the solar module make up less than $\sim 30\%$ of the total costs, increasing the power conversion efficiency must be regarded as the more powerful and long-term strategy towards overall decreased solar energy production costs.\[11, 12\]

The tremendous impact of the power conversion efficiency on the overall energy production costs creates a great economic obstacle. Technologies that can

\*Without this close knowledge transfer between the two partners, fundamental researchers are generally badly positioned to tackle those applied and industrially relevant questions. Very often, they lack the knowledge of technical details and requirements about industrial large-scale and high through-put processes. Furthermore, current and forecasted costs of specific process steps are generally undisclosed due to industrial competition.
only provide low conversion efficiencies, even if at a low cost, are unlikely to succeed. Furthermore, looking back at many successful innovative technologies, it becomes apparent that market entry and adaptation are more likely to be successful when new substantial capabilities are being provided. The typewriter has not been replaced by the PC, the propeller by the turbine engine, or the horse carriage by the car because the later was produced cheaper.

Figure 1.1 shows a summary of the increase of certified power conversion efficiencies of different solar cell technologies over time, starting from the year 1975. Many of the more established technologies, such as single crystalline, multicrystalline and amorphous silicon show a clear logarithmic trend of conversion efficiency increases over time. This "learning curve" is very typical for many technologies. Initially, a new technology offers much room for improvements that can be achieved rather easily, while continuous developments narrow the phase space of opportunities progressively. Eventually, only a few increasingly challenging paths are left to explore. To prevent a standstill in performance improvements, new technologies have to be pursued that allow for steeper efficiency increases, because they exhibit relatively more unexplored opportunities. Among the new emerging technologies are those that aim at utilizing electric and optical effects that emerge by nanoscale patterning and fabrication. Among them are quantum dot and nanowire solar cells, the latter being a focus of this work. For nanowire array solar cells, the

Figure 1.1: Best research-cell efficiencies over time. Nanowire array solar cell efficiencies are shown as blue stars with black (InP) and red (GaAs) outlines. The original plot is courtesy of the National Renewable Energy Laboratory, Golden, CO.
efficiency records are 17.8 % for InP and 15.3 % for GaAs and are shown in Figure 1.1 as blue stars with black and red outlines, respectively.[13, 14]

It has to be noted, that Fig. 1.1 does not discriminate between technologies that are pursued industrially or purely in research laboratories; the only requirement is the existence of a certified efficiency measurement by one of the leading research laboratories. Many of the new emerging technologies hold great promise to allow an overall cheaper generation of solar power in the future. Due to their novelty, they often lack any proof of industrial applicability, especially in terms of large scale and high throughput fabrication. Additionally, the stable performance in ambient conditions is a major challenge for many of the emerging technologies. However, to realistically evaluate the potential of those technologies one has to see the current developments in a historic context. In 1941, R. S. Ohl reported the first silicon solar cell (a "Light-Sensitive Electrical Device"), which was below 1% and far from any industrial production.[15] "There were a great many enemies to this work with semiconductors; you have no idea how many people opposed that. Vacuum tube people said that there is nothing to it and it is all a lot of tommyrot, and that sort of thing." - Russell Ohl, January 6th 1975. Today, silicon solar cells are being industrially produced with an efficiency of up to 25.6% and are contributing to over 90% of the ever increasing installed solar power. The record efficiencies are approaching 50% for multi-junction concentrator solar cells, a technology that makes use of efficiency gains by concentrating sunlight onto a multi-layered absorber. Each one of those layers converts a certain part of the solar spectrum highly efficiently. Given the vastly increased knowledge and the far larger man-power involved into the topic, also tangential in other research fields, a higher efficiency growth rate over time can be expected. These emerging technologies hold enormous potential to realize industrially produced, high-performance solar cells with power conversion efficiencies far above current values. In fact, they are indispensable to reach the ambitious targets for a clean energy economy in the near future.[16]
1.2 The basics of a solar cell

Figure 1.2 schematically depicts the fundamental mechanisms taking place in a solar cell during the energy conversion process from photons into electrons.

Sunlight, with its broad spectrum (blue, green and red arrowheads), is incident on the solar cell with a solid angle (Ω_in) subtended by the sun (1).

For a single band gap semiconductor, high energy photons (blue arrowheads) excite charge carriers (e−, h+) over the band gap deep into high energy levels in the conduction and valence band (2a). Once excited, those high energy carriers lose a large part of their energy very rapidly (≈ 100 fs) by phonon scattering until they reach the conduction (E_C) and valence band (E_V) edges. They now have the same energy as carriers that have been excited by photons with an energy just above the band gap (2b). Photons with an energy below the band gap (red), cannot be absorbed and hence are lost altogether (2c). The same holds for photons of higher energy (blue and green) that are reflected from the surface or cannot be absorbed, because the semiconductor is too thin.

Once the electrons and holes are excited to the conduction and valence band, they have to be extracted at the electron and hole contact, respectively. However, on their path they can recombine radiatively from the conduction and valence band edges (3). This radiative recombination leads to light emission with a solid angle Ω_out which is larger than or equal to the angle of the incident beam Ω_in (1 vs. 3). In most solar cells, a substantial solid angle expansion can be observed. In other words, much more radiative recombination is taking place than is dictated by thermodynamic limits: in the ideal case, the solar cell would only emit light into the angle subtended by the sun (Ω_out = Ω_in ≈ 6.85 * 10^-5 sr).

Another important loss mechanism for the charge carriers on their way to the contacts is non-radiative Shockley-Read-Hall (SRH) recombination at bulk, interface and surface defects (4). Continuous work on defect passivation is necessary to reduce those detrimental processes. Due to the large surface-to-volume ratio of nanoscale structures, surface recombination and the mitigation thereof are among the main topics of this thesis. Besides SRH, non-radiative Auger recombination can take place (not shown in Fig 1.2). For this process, excited charge carriers recombine, but instead of emitting a photon they excite charge carriers in the conduction or valence band to higher laying energy levels. From there, the carriers relax again rapidly by phonon scattering, as in (2a).

Carrier selective contacts are another focus of this thesis. An electron selective contact must hinder the passage of holes, otherwise the carrier concentration will be reduced substantially by additional recombination (5).

Eventually, if the charge carriers do not recombine radiatively (3) or non-radiatively in the bulk (4) or at non-selective contacts (5), they can be extracted efficiently (6). Finally, a solar cell delivers voltage and current to an external load (7). For most solar cells, the current is mainly reduced by the processes (2c) and (4), while the voltage is mainly affected by (2c), (3), (4) and (5).
Figure 1.2: The basic solar cell processes. (1) Light with the sun’s spectrum (depicted with blue, green and red arrowheads) is incident on the solar cell with a solid angle \(d\Omega\) subtended by the sun. (2a) Photon absorption and fast thermalization of high energy charge carriers to the conduction \(E_C\) and valence band \(E_V\) edges. (2b) Efficient photon absorption and charge carrier excitation directly at the band gap. (2c) Optical losses due to imperfect absorption and reflection. (3) Radiative recombination of charge carriers at the band gap, leading to solid angle expansion due to imperfect optical properties. (4) Non-radiative recombination at defect traps deep inside the band gap. (5) Limited contact selectivity leads to movement of charge carriers into the wrong direction that are eventually lost due to non-radiative (Auger) or additional radiative recombination. (6) Efficient charge carrier extraction. (7) A solar cell delivers voltage and current to an external load. The current is mainly reduced by (2c) and (4), while the voltage is strongly affected by the processes (2c), (3), (4) and (5), as schematically shown on the right side (8).
On the right side of Fig. 1.2 the effect of recombination on the solar cell voltage is depicted (8). The photon excitation of charge carriers over the band gap (2a,b) changes the carrier concentrations vastly compared to thermal equilibrium (in the dark). The additional light-induced carrier concentrations in the conduction and in the valence band give rise to a difference in the free energies, the quasi-Fermi levels, for electrons ($E_{F_n}$) and holes ($E_{F_h}$). This quasi-Fermi level splitting is essentially a potential that can be used to perform work in a connected circuit. Consequently, every means to increase the light induced carrier concentration and to prevent recombination will result in a solar cell that delivers a higher voltage.

Different recombination processes take place after the excitation of charge carriers to the band edges ((2c), (3), (4) and (5)). The only recombination that is strictly dictated by thermodynamics is the small amount that is emitted into the solid angle of the sun ($\Omega_{out} = \Omega_{in}$). This solid angle is closely related to the entropy of the light, which according to the second law of thermodynamics can never decrease, only increase or stay constant. If the solid angle stays constant, that is in the absence of other radiative recombination channels, this small amount leads to a potential that is very close to the band gap ($E_G$). However, in general, enhanced radiative recombination leads to light that is emitted into directions other than the direct incident light ($\Omega_{out} > \Omega_{in}$), which substantially lowers the internal carrier concentration. The effect of those radiative processes is captured in the radiative open-circuit voltage $V_{oc}^{rad}$. Unless those processes are controlled, e.g. via dielectric thin-layer coatings that limit $\Omega_{out}$, this value sets a practical upper limit; $V_{oc}^{rad}$ is the maximum open-circuit voltage that can be extracted in the absence of non-radiative recombination.

In the presence of non-radiative recombination (4), the voltage is reduced to the implied open-circuit voltage, $V_{oc}^{imp}$. With an increasing defect density that increases non-radiative channels, the gap between $V_{oc}^{imp}$ and the upper limit, $V_{oc}^{rad}$, widens. In general, $V_{oc}^{imp}$ refers to the spatially averaged carrier concentration.

Non-radiative (Auger) and radiative recombination close to the contacts (5) are particularly detrimental. If an electron contact is not selective enough, holes enter the region of high intrinsic electron concentration and recombine with electrons. Thereby, not only the hole but also the electron concentration, and hence their free energy, is reduced. However, because the recombination takes place just before the electron extraction, the extracted free energy of the electron will be strongly limited to its locally reduced value. This is in strong contrast to recombination far away from the contacts. For such a spatially separated recombination the free energy can still be higher in the region where the carrier extraction eventually takes place. This localized recombination due to non-ideal contacts results in a $V_{oc}$ which deviates from the spatially averaged $V_{oc}^{imp}$.

To summarize, the extracted $V_{oc}$ strongly deviates from the $E_g$ and for the vast majority of absorbers even from $V_{oc}^{rad}$. Because non-radiative recombination and non-ideal contacts cause such widely encountered practical limitations, especially for nanowire solar cells, they stand in the focus of this thesis.
1.3 Nanowire photovoltaics

Semiconductor nanowires are among the most promising candidates for next generation photovoltaics. This is due to their outstanding optical and electrical properties which profoundly impact the energy conversion process.

An efficient solar cell needs to absorb all of the incident light. The inefficient absorption of photons with energies far above and below the band gap is a large loss in the overall energy conversion process. One way to overcome this loss, is the utilization of multiple materials with different band gaps, so called tandem solar cells, which absorb several parts of the solar spectrum highly efficiently.[18]

However, photon absorption is inherently a stochastic process, therefore it does not occur instantaneously upon entrance into the semiconductor. The photons encounter a certain absorption probability for each incremental distance they pass through the material. This probability increases with increasing photon energy but depends on the exact material properties. For example, direct band gap semiconductors have a higher absorption probability than semiconductors with an indirect band gap, because the latter require the additional interaction with a phonon.[19] Therefore, to ensure that close to all of the light is absorbed, a certain absorption length is required. If the semiconductor is for example too thin, not only low energy photons but even photons with high energies cannot be absorbed completely, together with photons that have been reflected off the surface (Fig.1.2(2c)). As a result, for an indirect band gap semiconductor with a relatively low absorption coefficient, such as silicon, a hundreds of micrometer thick wafer-based geometry has to be chosen for complete absorption. If a direct band gap semiconductor, such as GaAs, is employed, the high absorption coefficient translates into a vastly reduced absorber thickness, down to a few micrometers (Fig.1.3(a)). To ensure that the incident light enters the absorber, an anti-reflection texture and coating have to be employed (Fig.1.3(b)).

![Figure 1.3: Benefits of the nanowire geometry for photovoltaics.](image)

(a) Volume requirements for indirect and direct band gap semiconductors to reach full absorption. (b) Anti-reflection coatings and textures for indirect and direct band gap semiconductors. (c) A larger optical than geometrical cross section increases the short-circuit current density of a nanowire. (d) The optical properties lead to a substantial volume reduction for full absorption in nanowire array solar cells.
If the absorber is structured on the nanoscale, such as in the nanowire geometry, resonances can occur that result in optical cross sections that can exceed the physical material boundaries (Fig. 1.3(c)). As a result, the nanostructured semiconductor is able to absorb not only directly incident but also adjacent light. If arranged in a nanowire array geometry, additional beneficial effects, such as in-plane diffraction and scattering to nearby nanowires can occur. The large optical cross sections together with the array effects are a great benefit of nanowires compared to both thin-film and wafer-based solar cells; they lead to full light absorption and hence maximum short-circuit current densities even though much less material and no additional anti-reflection coatings are employed (Fig. 1.3(d)).

Besides the outstanding absorption properties, high short-circuit current densities are supported via the so called core-shell geometry (Fig.1.4). For wafer or thin-film geometries, the carrier extraction happens over the same length scale as the light absorption. The carriers need to be extracted up to hundreds of micrometers through the bulk of a potentially defect-rich material. In contrast, the nanowire geometry allows for radial charge carrier extraction, that is perpendicular to the incident light. The nanowire core consists of one carrier selective contact (e.g. for electrons), while the shell provides the second for the opposite carrier type (e.g. holes). Usually those two regions are composed of semiconductors with a different doping type, that is an n-doped region for the electron contact and a p-doped region for the hole contact. In this configuration, the separated charge carriers need to pass through the several \( \mu m \)-long core which increases the series resistance. In this thesis we show that the semiconductor core can be replaced by a metal; we realize the first metal-semiconductor core-shell nanowire solar cell. Such a structure potentially strongly reduces the series resistance due to the superior conductivity of the metal. In both core-shell geometries the carriers only need to be extracted over a short distance (\( \leq 100 \text{ nm} \)) which greatly reduces the probability of radiative and non-radiative recombination events ((2,3) in Fig.1.2); that is a lower carrier diffusion length is required (Fig. 1.4).

![Carrier extraction](image)

**Figure 1.4: Radial charge carrier extraction.** Another potential benefit is the charge carrier extraction perpendicular to the incident light, which leads to a reduction of the required minority carrier diffusion lengths. Yellow and white arrows represent the incident light and charge carrier extraction, respectively. The blue and orange regions represent the carrier selective contacts.
Nanowire solar cells lead to an expansion of the solid angle between the incident $\Omega_{\text{in}}$ and outgoing light $\Omega_{\text{out}}$ as do macroscopic solar cells. Therefore, the internal carrier concentration and hence radiative open-circuit voltage $V_{\text{oc}}^{\text{rad}}$ is substantially lower than the band gap energy.

However, to accurately evaluate the overall potential of nanowire solar cells, the effect on the open-circuit voltage has to be considered (right side of Fig.1.2). The nanowire geometry will not only affect the light absorption, but also the light emission. As is the case for macroscopic solar cells, nanowire (array) solar cells can emit light into a larger solid angle than the incident light, i.e. $\Omega_{\text{out}} > \Omega_{\text{in}}$ (Fig.1.5). As a result, the sustained carrier concentration inside the semiconductor is reduced, compared to the case for which the emission is limited into the direction of absorption ($\Omega_{\text{out}} = \Omega_{\text{in}}$). To determine the radiative open-circuit voltage limit of nanowire array solar cells accurately, the optical properties have to be studied closely, depending on the exact material parameters.[20, 21]

However, as for most macroscopic solar cells, a large gap exists between the practical $V_{\text{oc}}$ and the radiative limit $V_{\text{oc}}^{\text{rad}}$. Non-radiative recombination sets currently all practical limits for nanowire solar cells and the mitigation thereof is hence the focus of this thesis. This kind of recombination can happen at bulk or surface defects that are intrinsically linked to the material, such as interstitials, vacancies, dangling bonds, grain boundaries or dislocations. Additionally, unintended impurity incorporation during manufacturing, e.g. via incorporation of metal ions from a growth catalyst, can increase the defect density further.[22] Those impurity and crystal defects can lead to deep energy levels inside the band gap of the semiconductor, where the charge carriers rapidly recombine and transfer their energy into phonons or low-energy photons (Fig. 1.2). For nanowires, due to their high surface-to-volume ratio compared to macroscopic cells, surface recombination dominates. The discontinuous crystal lattice at the surface (dangling bonds) offers a high density of defects (Fig. 1.6).
1.3 Nanowire photovoltaics

Figure 1.6: Challenging interfaces. Due to the high surface-to-volume ratio of nanowires, surface recombination and Fermi level pinning can have a pronounced impact on the final device performance. Another important property is contact selectivity (right side). Traditionally, a solar cell employs n- or p-doped regions. However, other schemes hold great potential, especially for the nanowire geometry, with its particular challenges such as inhomogeneities in the radial and axial dopant profile.

Consequently the most efficient nanowire solar cells to date employ either materials with a relatively low intrinsic surface recombination, such as wurtzite InP nanowires, or use additional high quality surface passivation layers, such as GaAs nanowire solar cells.[13, 14, 23] Without proper surface passivation many materials, such as GaAs or Si, lead to highly depleted nanowires, i.e. almost all of the photogenerated charge carriers recombine at surface defects.

Furthermore, unpassivated interface defects can fix the free energy of the carriers at a defect level, irrespective of the doping type and density of the bulk material. This Fermi level pinning, which is often induced by the adjacent metal, inhibits the efficient extraction of charge carriers with a photo-induced potential (quasi-Fermi level splitting). Besides creating extraction barriers at contact interfaces, Fermi level pinning at surface defects can cause additional non-radiative recombination. If the Fermi level position at the defect inverts the conduction type of the bulk material in a region close to the surface, minority carriers can move freely from the bulk towards the surface (towards a lower free energy). The bulk minority carriers
encounter a newly increased conductivity, which provides new pathways towards surface defects and eventual non-radiative decay.

Besides non-radiative surface recombination and Fermi level pinning, carrier selective contacts deserve special consideration for the nanowire geometry (right side of Fig. 1.6). Nanowire solar cells, like most traditional solar cells, mainly rely on impurity doping to create the desired selectivity.[22] While impurity doping is widely established in the wafer-based semiconductor industry, it becomes increasingly difficult with decreasing dimensions. The precise doping control for nanowires in the sub-\(\mu\)m range is very challenging and generally strongly affected by the exact nanowire geometry and growth conditions. The doping profile of a nanowire can change unintentionally along the diameter, due to strain-effects of the crystal lattice and different dopant incorporation rates during the growth.[22, 24, 25] Furthermore, the highly doped contact regions are strongly affected by radiative and Auger recombination which only represent a small fraction in a wafer-based solar cell. For a nanowire device, this region can amount to a substantial fraction of the whole material and can strongly affect the overall performance (Fig.1.6). If the highly recombination active region directly points towards the incoming light, parasitic absorption strongly limits the overall efficiency.

For macroscopic solar cells, new generations of selective contacts have been developed that solely rely on carefully chosen surface layers.[26–28] In this thesis, we propose to extend their application to nanowires, because of the particular issues encountered for nanowire doping. We show that by applying the interfacial layer MoO\(_x\), together with an HF treatment, we are able to mitigate negative effects due to inhomogeneous and insufficient dopant incorporation during the growth. Using our insights from those selective contacts for single nanowire devices, we are able to propose a highly promising application. In the last chapter of this thesis, we propose a nanowire array solar cell manufacturing process centered around a reusable substrate and mechanical peel-off step. This fabrication process exploits the intrinsic advantages that emerge from the nanowire geometry compared to thin-films; fast and flexible growth, reduced material consumption, fast mechanical peel-off and intrinsic anti-reflection properties.

So far nanowire solar cells are limited to efficiencies < 20%. Improvements in the past have mainly been achieved by improving the optics, that is the absorption has been enhanced due to an optimized array design (width, length, tapering and array pitch), and because of improved nanowire fabrication methods (crystal growth, etching). By turning the attention towards the electronics, in particular novel selective contacts and passivation layers, nanowire solar cells have the chance to finally close the gap between their practical and thermodynamic efficiency limits.
1.4 Outline of this thesis

Surface passivation and highly-selective contacts are of prime importance for an efficient solar cell. Nanoscale photovoltaics have a very high surface-to-volume ratio, therefore the interface properties are of utmost importance. Furthermore, the high crystal quality (often monocrystallinity) of single nanowire devices reduces the density of crystal defects, such as grain boundaries and dislocations. In this thesis, nanowires are therefore chosen as a highly sensitive platform to study the impact of surface and contact interface properties on the overall photovoltaic performance and to propose device designs for more efficient nanowire array solar cells.

In Chapter 2, we study the photovoltaic performance of a new promising nanowire geometry; a metal-semiconductor core-shell nanowire. This type of nanowire has theoretically been predicted to provide outstanding optical absorption in the semiconductor shell and a short required minority carrier diffusion length. Furthermore, it benefits from direct carrier extraction via the metal core, potentially reducing the series resistance of the device as compared to core-shell geometries that consist solely of semiconductors. However, it is well known that the direct contact between a metal and a semiconductor can cause increased recombination, Fermi level pinning and charge carrier extraction barriers. Those issues are usually encountered for metal-semiconductor interfaces that are highly disordered on an atomic scale. We show, that even though the semiconductor shell grows epitaxially off of the metal core, that is the interface is highly ordered, charge carrier extraction barriers and enhanced interfacial recombination can still be observed.

In Chapter 3, we study a metal-insulator-semiconductor solar cell, that mitigates the direct and detrimental contact between a metal and a semiconductor by utilizing a thin passivating and insulating interlayer. We employ a metal nanowire network as front electrode on a silicon wafer-based solar cell, because of the potential for highly homogenous charge carrier extraction. We are able to fabricate devices with a power conversion efficiency of 11% (after correction, $V_{oc} = 560$ mV, $J_{sc} = 33$ mA/cm$^2$). For a metal-insulator-semiconductor solar cell, the $V_{oc}$ depends strongly on the work function difference between the metal and the semiconductor. Based on the employed materials (Au/Pd/Al$_2$O$_3$/Si) we conclude that a charge-neutrality-level at the metal-dielectric interface is likely to lower the metal work function from its vacuum value and hence negatively impacts the measured $V_{oc}$. A future change towards SiO$_2$ has the potential to increase the open-circuit voltage substantially. The short-circuit current density is strongly affected by reflection and parasitic absorption. Therefore, we introduce nanopyramids integrated in between the metal nanowire network, that substantially reduce reflection and hence increase the short-circuit current density.

In Chapter 4 we turn our focus back to semiconductor nanowires. Those nanoscale structures have a higher optical than geometrical cross section; they absorb not only light that is directly incident on the physical material boundaries but also adjacent light. While this property can be of great use, especially in
Introduction

terms of reduced material volume, it complicates the characterization of isolated nanoscale devices. A priori the absorption cross section is unknown and changing with wavelength. Hence, it is unclear how much of the incident light directly interacts with the single nanoscale device. This prevents quantification of the different conversion steps and loss mechanisms, but also the quantification of the absolute radiative limit $V_{oc}^{rad}$. For this thesis it is of great importance to quantify non-radiative recombination and non-ideal contacts. To that end, we focus on InP nanowires that have been used to reach the highest nanowire array solar cell efficiencies to date. We introduce a new measurement technique, integrating sphere microscopy, to accurately quantify the remaining loss mechanisms. We measure the internal quantum efficiency (IQE), the photoluminescence quantum yield (PLQY) and the nanoscale equivalent of the EQE (external quantum efficiency) of a single nanowire device for the first time. Using integrating sphere microscopy, we are able to quantify the impact of non-ideal contacts and non-radiative recombination in order to understand how much can be gained by reducing those loss mechanisms.

In Chapter 5 we focus on the surface properties of InP nanowires. We study the device performance of contacted and masked single nanowire devices before and after HF, MoO$_x$ and sulfur treatments. We show improved surface passivation and increased carrier selectivity with HF treatment. The limited contact selectivity we encountered in Chapter 4 is likely to be related to Fermi level pinning close to the conduction band due to the native oxide and the high diffusivity of the p-type dopant Zn. Therefore, we introduce the interfacial layer MoO$_x$ for nanowire solar cells, which allows us to increase the open-circuit voltage by up to 335 mV, from 500 mV to 835 mV. To electrically passivate the InP surface and protect it against oxidation, we study the influence of sulfurization. We show preliminary results that prove sulfurization can indeed increase the $V_{oc}$ by removing the native oxide and potentially even passivate the surface against reoxidation.

In Chapter 6, we explore valorization opportunities that emerge out of our insights from the preceding chapters. In the previous chapters we have shown how to contact single p-type InP nanowires for high performance devices, which has been an unsolved issue in the past. Translating those insights to array solar cells allows us to propose a process line which exploits the intrinsic advantages that emerge from the nanowire geometry compared to thin-films; faster growth speeds, reduced material consumption, fast mechanical peel-off and intrinsic anti-reflection properties. We perform a techno-economic analysis on our proposed fabrication process by comparing the technology to already existing and very similar manufacturing lines for thin-film GaAs solar cells. We include different nanowire growth methods that are promising approaches towards reducing the costs further. The ability to consider various growth methods points towards another characteristic: the process line is highly flexible and not limited to one growth method or semiconductor. We argue that this can have great impact on the rate of innovation in a hypothetical company invested in this process. Finally, we propose a roadmap for future developments and commercialization.
Au-Cu$_2$O core-shell nanowire photovoltaics

The electrical properties of semiconductor nanowires strongly depend on the realized junction and electrode geometry (axial vs. radial). For radial charge carrier extraction the required minority carrier diffusion length is on the order of 10-100 nm and therefore strongly relaxed compared to bulk solar cells. To this end, we study metal-semiconductor core-shell nanowires, which have been predicted to show even better optical absorption than solid semiconductor nanowires, with the additional advantage of a local metal core contact for radial charge carrier extraction. We fabricate and analyze such a geometry using a single Au-Cu$_2$O core-shell nanowire photovoltaic cell as a model system. Spatially-resolved photocurrent maps reveal that although the minority carrier diffusion length in the Cu$_2$O shell is less than 1 µm, the radial contact geometry with the incorporated metal electrode still allows for photogenerated carrier collection along an entire nanowire. Current-voltage measurements yield an open-circuit voltage of 600 mV under laser illumination and a dark diode turn-on voltage of around 1V. This study suggests the metal-semiconductor core-shell nanowire concept could be extended to low-cost, large-scale photovoltaic devices, but stresses the importance of careful interface engineering.
2 Au-Cu$_2$O core-shell nanowire photovoltaics

Figure 2.1: Schematic drawing of the metal-semiconductor core-shell geometry.
Two devices are electrically connected to electrodes and a laser beam (bright blue) is incident on one of them. The Au electrode contacts the Au core while a Ti electrode contacts the Cu$_2$O shell (red) only at the end (top left) or along most of the length via an additional thin Ti pad (center). The inset shows a cross section of the device geometry. The incident light creates electron-hole pairs (e-, h$^+$), which are extracted via the shell and the core, respectively.

2.1 Introduction

2.1.1 Cu$_2$O as photovoltaic material

Cuprous oxide (Cu$_2$O) is an earth abundant and non-toxic semiconductor that can be grown using many different fabrication methods including evaporation and sputtering. Its direct band gap of $\sim 2.0$ eV provides the potential to reach power conversion efficiencies of up to 20%. This combination of abundance, simple fabrication and efficiency potential has therefore made Cu$_2$O a popular choice for thin-film solar cell research since the early days of photovoltaics.[29][30] Assuming that excellent surface passivation can be achieved, thin-film solar cells can in general even reach higher open-circuit voltage ($V_{oc}$) values than their bulk counter parts due to shorter charge carrier extraction paths and hence reduced bulk recombination.[31] Cu$_2$O has a band gap that is close to the ideal value for a silicon-based tandem solar (1.7-2.0 eV), making it a candidate for high efficiency photovoltaics.[32–34] Recently, several groups have focused on the interface properties of Cu$_2$O and were able to increase the $V_{oc}$ up to 1.2 V by using interfacial layers, such as Ga$_2$O$_3$ and ZnO, combined with transparent conductive oxides (TCOs) as top contacts.[35–43]
2.1.2 Metal-semiconductor core-shell nanowire

Here we utilize a metal-semiconductor core-shell geometry to fabricate a single horizontally aligned Au-Cu$_2$O nanowire photovoltaic cell. Such a structure has several potential advantages. The thin semiconductor shell in direct vicinity of the metal core electrode allows for facile extraction of photogenerated carriers, even in materials with short minority carrier diffusion lengths. The radial core-shell geometry has already proven useful in semiconductor nanowire photovoltaics and we expect even better charge carrier extraction in our geometry where photocarriers are injected into the metal immediately.[44–47] Another previously demonstrated advantage of semiconductor nanowires is their high absorption cross section, which can exceed the geometrical one.[23, 48, 49] The metal-semiconductor core-shell structure can lead to even higher absorption, while further reducing the amount of semiconductor.[50] Several research groups have already utilized metal-semiconductor core-shell nanospheres or rods for plasmon mediated charge carrier dynamics for photovoltaics and photocatalysis. In these examples however, semiconductor materials were not used for the visible light absorption or materials were suspended completely in solution.[51–57] Here we fabricate and test a single metal-semiconductor core-shell nanowire photovoltaic cell, utilizing Au for the core and Cu$_2$O for the shell.

2.2 Results

To fabricate the core-shell nanowires, we followed a procedure developed by Sciaccia et al. for solution-based synthesis of metal (Ag, Au or Cu) core Cu$_2$O shell nanowires.[58] The metal nanowires were synthesized using the polyol process and subsequently coated with a Cu$_2$O shell at room temperature in aqueous solution, adapting a protocol originally developed for core-shell nanoparticles.[59, 60] This specific Cu$_2$O synthesis route was chosen over other methods to produce Cu$_2$O nanowires because it allowed for epitaxial growth on metal nanowires suspended in solution.[61, 62] Photoluminescence (PL) measurements showed a peak near 1.9 eV, similar to what has been observed in pure-phase, bulk Cu$_2$O.[58, 63]

Figure 2.1 shows a schematic of a single nanowire photovoltaic cell illuminated by a laser beam. As can be seen in the drawing, the Cu$_2$O shell has two contacts: one that collects photogenerated holes and one that is selective for photogenerated electrons. One simple and effective method for inducing this carrier selectivity is to use metal contacts with different work functions such that one metal makes an Ohmic contact to the Cu$_2$O and the other a Schottky junction.[19]

Here we have chosen Au as the metal nanowire core because it has a large work function (~ 5.4 eV; similar to that of Cu$_2$O) and makes an Ohmic contact to Cu$_2$O. Furthermore Au has a high chemical stability, low lattice mismatch with Cu$_2$O (~ 4%) and a simple nanowire synthesis route.[58, 64–67] As the Schottky contact we have chosen Ti, which has a low work function (~ 4.3 eV), excellent adhesion to many materials and a stable surface oxide.[68]
2 Au-Cu$_2$O core-shell nanowire photovoltaics

![Figure 2.2: Single nanowire photovoltaic with radial charge carrier collection.](image)

(a) False-colored SEM image of a nanowire (yellow) connected between Ti (blue) and Au (red) contacts. (b) Optical reflection image. (c) Photocurrent map with an incident laser power of 42 $\mu$W, polarization perpendicular to the nanowire axis, a spot size of $\sim 1$ $\mu$m, and illumination wavelength of 405 nm. The local photocurrent collection next to the Ti contact is clearly visible.

To fabricate such samples, we started with Si$_3$N$_4$ covered Si substrates with evaporated Au electrodes. The core-shell nanowires were contacted using electron beam lithography and metal evaporation. The optical characterization was conducted with a tunable laser source in the range of 405 nm - 750 nm. The light was focused through an objective lens to a spot size of $\sim 1$ $\mu$m onto the electrically connected single nanowire photovoltaic cells. The details of the device fabrication and characterization can be found in the supporting information.

Figure 2.2(a) shows a colored scanning electron microscope (SEM) image of a typical single nanowire photovoltaic cell (yellow). The reflection map in Figure 2.2(b) shows the diagonal orientation relative to the parallel contact pads. Figure 2.2(c) shows photocurrent generation of up to 350 pA under 42 $\mu$W laser illumination at $\lambda = 405$ nm. The localized charge carrier collection only occurs near the Ti contact finger, where the Schottky junction induces a built-in electric field, such that the minority charge carriers do not have to travel long distances to get extracted. Due to the optically thick Ti contact we do not expect any substantial contribution to the photocurrent from the Cu$_2$O regions under the contact. This photocurrent collection localized only close to the Ti contact suggests that the minority carrier diffusion length is less than or equal to the beam spot size of $\sim 1$ $\mu$m, consistent with reported values for Cu$_2$O synthesized by different methods.[69, 70]

Despite the excellent crystallinity and epitaxial shell growth in these core-shell nanowires, the high surface and contact areas could lead to even shorter minority carrier diffusion lengths, as these are known to be sources of increased non-radiative recombination in bulk solar cells.[19] Future studies involving thin interfacial spacing layers and surface passivation are needed to quantify the importance...
2.2 Results

![Image](image_url)

Figure 2.3: Extended radial charge carrier collection. (a) Schematic of single nanowire with employed Ti pad. (b) Colored SEM image of a nanowire connected between Ti (blue) and Au (red) contacts and partially covered by a 10 nm thin Ti pad (blue). (b) Reflectance map. (c) Photocurrent map with an incident laser power of 7 µW, polarization perpendicular to the nanowire axis, a spot size of 1 µm, and illumination wavelength of 405 nm. The photocurrent collection is extended by the presence of the Ti pad.

of these effects and our single core-shell nanowire geometry provides a perfect platform for such studies.

To directly probe the importance of the radial built-in field and carrier collection mechanism, we have compared the above results to the case where a 10 nm thin Ti pad covers approximately 2/3 of the nanowire (Figure 2.3(a)). This arrangement is closer to a realistic large-scale device, where the whole nanowire would be covered with an additional contact (either a transparent conductive oxide or a continuous thick metal layer with illumination through a transparent substrate). Figure 2.3(b) shows a false-colored SEM image of the device, with a Ti pad (blue) on top of the nanowire (yellow), which is connected between a Ti (blue) and an Au (red) contact. Figure 2.3(c) shows the reflection image and Figure 2.3(d) the respective photocurrent map under 7 µW laser illumination at λ = 405 nm, which reveals photocurrent collection from an extended elongated area. This photocurrent profile demonstrates charge carrier collection from the nanowire along the entire length covered by the Ti pad. This supports the idea that charge carriers generated by light passing through the 10 nm Ti pad can be separated and collected at the metal core and the Ti top contact. The maximum photocurrent is around 25
Figure 2.4: Spectral response of single nanowire. (a) Reflectance map of the nanowire at 405 nm. (b-e) Responsivity maps at laser wavelengths of (b) 405 nm, (c) 520 nm, (d) 620 nm and (e) 700 nm. The responsivity was obtained by first subtracting the background values and subsequently dividing by the incident laser power, to facilitate comparison. In all cases the laser polarization was perpendicular to the nanowire axis. The spatial shift of the photocurrent with increasing wavelengths is due to chromatic aberration of the objective lens and drift in the mechanical stage.

Times smaller than in the axial collection case shown in Figure 2.2, which can be attributed to the reduction in incident power from 42 to 7 \( \mu \)W and the substantially reduced absorption in the wire due to the Ti pad. The responsivity (photocurrent after background subtraction divided by the incident laser power) is only lowered by a factor of four by the Ti pad. These results prove the utility of this concept: photocurrent collection can take place along the whole length of the nanowire, even with materials that have very short minority carrier diffusion lengths.

To investigate the core-shell nanowire spectral response, we map the responsivity under 405 nm, 520 nm, 620 nm and 700 nm laser illumination (Figure 2.4(b)-2.4(e), respectively). The polarization was perpendicular to the nanowire axis for all
measurements, which is the polarization that supports plasmon resonances. In the other polarization we observed weaker currents. Currently, we can not distinguish between charge carrier generation due to band-to-band absorption in the Cu$_2$O and plasmon-mediated transfer mechanisms, such as resonance energy transfer, direct energy transfer and hot carrier injection.[51, 71–75]

The strong reduction in photocurrent for $\lambda = 700$ nm is consistent with the literature value of the optical band gap (1.95 eV or 635 nm) and our own single nanowire PL measurements.[58, 76] However, absorption in the Ti pad as well as variations in the optical resonances must be taken into account to quantitatively explain the observed results. Finally, we show single nanowire current-voltage (I-V) measurements in the dark and under laser illumination (Figure 2.5). This nanowire device, which did not contain an extended Ti pad showed clear rectification behavior with a turn on voltage of 1 V in the dark. Under laser illumination with 42 $\mu$W power at 405 nm, an $I_{sc}$ of -300 pA and a $V_{oc}$ of 600 mV were observed.

These results clearly demonstrate that single metal-semiconductor core-shell nanowires function as photovoltaic cells. The photocurrent increases at higher reverse voltages and reaches reverse break down before saturating. We attribute this slope to a higher photogenerated carrier collection efficiency at larger reverse bias voltages due to an increased depletion region. Furthermore, we observe a substantial charge carrier extraction barrier and hence s-shaped I-V curve, which is a well-known phenomenon that can be attributed to accumulated space charges at the material interfaces or a non-ideal Ohmic contact.[77–80] This observation

![Figure 2.5: I-V curves of single Au-Cu$_2$O nanowire photovoltaic.](image)
(a) Current-voltage behavior of a single Au-Cu$_2$O core-shell nanowire photovoltaic cell in the dark (red line) and under laser illumination at 405 nm with a power of 42 $\mu$W and polarization perpendicular to the nanowire axis (blue). The inset is a magnified view of the region 0 V - 0.6 V of the I-V curves.
can be explained by the non-optimized metal-semiconductor interfaces, which are likely to induce recombination-active trap states and accumulated space charges. We note that the photocurrent under the AM 1.5G spectrum was below the detection limit (\( \sim 5 \text{ pA} \)) of the source measure unit used and therefore did not allow the measurement of our devices under the full solar spectrum. The low photocurrent can partially be explained by the localized Schottky region close to the optically thick Ti contact which is mostly inaccessible for the incident light. Only a small fraction at the edge of the contact can contribute to the photocurrent.

### 2.3 Conclusions

We have realized for the first time a single metal-semiconductor core-shell nanowire photovoltaic cell. We measured photocurrent maps on individual Au-Cu\(_2\)O core-shell nanowires, showing charge carrier collection via a Schottky Ti contact on the surface, with the Au core being utilized as an Ohmic contact. The spectral response is consistent with a band gap of \( \sim 2 \text{ eV} \). We show that a \( V_{oc} \) of 0.6 V and \( I_{sc} \) of 300 pA can be achieved without any detailed contact optimization, however only at a very high illumination intensity. By depositing a thin (10 nm) Ti layer over the wire, we clearly demonstrate that two conductive radial metal contacts allow for radial photogenerated carrier collection in semiconductors with short minority carrier diffusion lengths \(<1 \mu\text{m}\).

We observe a strongly s-shaped I-V curve, which is indicative of a charge carrier extraction barrier at one of the two metal interfaces. As also reported in previous literature, it is possible that a redox reaction under the Ti contact converts the Cu\(_2\)O to TiO\(_2\) and Cu at the interface.[81] Furthermore, the direct vicinity of a metal and a semiconductor is well known to cause metal-induced band gap states in the semiconductor which can lead to mid-bandgap Fermi level pinning and hence extraction barriers.[19]

Therefore, we would expect better performance if appropriate interfacial passivation layers could be incorporated, as already demonstrated not only with Cu\(_2\)O but also other material systems, such as silicon in Chapter 3 of this thesis.[38, 82, 83] Furthermore, we would expect a further improvement in the device performance for a reversed contact geometry, allowing for a Schottky/metal-insulator-semiconductor junction along the whole length of the metal core. However, the solution growth of a passivating insulator between the metal and the semiconductor and a core-shell structure with a low work function core metal have not been realized so far.[58]

While the limitations discussed above explain the overall low photovoltaic performance of our device, they do not present insurmountable obstacles on the way to high efficiency metal-semiconductor core-shell nanowire solar cells. We note that the metal-semiconductor core-shell nanowire geometry is not limited to the materials used for this proof-of-concept study. An ideal structure would employ low cost metals with appropriate interfacial layers, replacing Au and Ti.
2.4 Supplemental information

2.4.1 Fabrication

Au-Cu$_2$O core-shell nanowires were prepared in solution as described in detail by Sciacca et al.[58] The nanowires had a Au core diameter of ~50 nm and a Cu$_2$O shell thickness of ~30 nm and were then dropcast onto 3 x 3 mm$^2$ low-stress LPCVD-Si$_3$N$_4$ (~300 nm) covered Si chips with evaporated Au electrodes (~150 nm). The core-shell nanowires were contacted using a 2 or 3-step electron beam lithography and metal evaporation scheme. The Cu$_2$O shell was locally etched for 1-2 min with 0.1 mM sulfuric acid prior to Au evaporation (~200 nm) for the core contact, while the Ti contact (~200 nm) was directly evaporated on the Cu$_2$O shell. For the experiments with the 10 nm thin Ti pad, an additional resist exposure and evaporation step was conducted prior to the thick Ti shell contact formation. For the multi-step electron beam lithography process, pre-patterned alignment markers on the substrates were used to align subsequent exposure patterns to the correct nanowire and electrode locations.

2.4.2 Characterization

The optical characterization was conducted with a home-built laser setup. A super-continuum laser (Fianium WL-SC390-3) was sent through an acousto-optic tunable filter (Fianium AOTF-V1-N1) to select wavelengths in the range of 410 nm - 750 nm. The polarization was controlled with a λ/2 plate (Thorlabs) before the light was focused through an objective lens (Mitutoyo M PLAN APO NUV 50X) to a spot with waist $w_0$ ~ 600 nm on the electrically connected single nanowire photo-voltaic cells. The substrate was mounted on and wire bonded to a custom designed printed circuit board to facilitate the electrical connections. Then the substrate was scanned relative to the focused beam position with a 3-axis piezoelectric stage (Piezosystem Jena Tritor 400 CAP). The photocurrent was measured with an Agilent B2902A source-measure unit, while simultaneously recording the reflected and incident beam power (both measured with Thorlabs amplified photodiodes model PDA100A) to correlate the current with the position of the laser spot and to normalize to variations in the laser power during a single measurement. The absolute beam power was measured using a calibrated silicon photodetector (Newport model 818-UV-L). The I-V curves were also measured with the source-measure unit (Agilent B2902A).
Metal-insulator-semiconductor nanowire network solar cells

Metal-insulator-semiconductor (MIS) junctions provide the charge separating properties of Schottky junctions while circumventing the direct and detrimental contact of the metal with the semiconductor. A passivating and tunnel dielectric is used as a separation layer to reduce carrier recombination and remove Fermi level pinning. When applied to solar cells, these junctions result in two main advantages over traditional p-n-junction solar cells: a highly simplified fabrication process and excellent passivation properties and hence high open-circuit voltages. However, one major drawback of MIS solar cells is that a continuous metal layer is needed to form a homogeneous junction at the surface of the silicon, which decreases the optical transmittance and hence short-circuit current density. The decrease of transmittance with increasing metal coverage can, however, be overcome by nanoscale structures. Nanowire networks exhibit precisely the properties that are required for MIS solar cells: closely spaced and conductive metal wires, to induce an inversion layer for homogeneous charge carrier extraction, and simultaneously a high optical transparency. We experimentally demonstrate the nanowire MIS concept by using it to make silicon solar cells with a measured energy conversion efficiency of 7% (~11% after correction). Furthermore, we introduce inverted nanopyramids integrated between the metal nanowire network, decreasing the reflectivity substantially from 36% to ~4%.
3.1 Introduction

When a metal contacts a semiconductor, a carrier selective Schottky junction can be formed. The resulting conduction type inversion in the semiconductor depends on the metal and semiconductor work function difference. For example, when n-type silicon directly contacts a high work function metal (Au), the conductivity for electrons falls below the conductivity for holes close to the surface. This inversion of the majority carrier conduction type causes the carrier selective properties of Schottky junctions. However, as also shown in Chapter 2 the direct contact between metal and semiconductor can increase surface recombination due to metal-induced band gap states and dangling bonds and can even lead to Fermi level pinning at the semiconductor surface.[84] Metal-insulator-semiconductor (MIS) junctions circumvent those problems by separating the metal and semiconductor with a thin tunnel and passivating dielectric.[85] Furthermore, interface charges at the dielectric semiconductor interface can increase the magnitude of the conduction type inversion in the semiconductor.[86]

Because of their charge selective and passivating properties, MIS junctions were successfully used to make silicon solar cells starting in the 1970s.[87, 88] The MIS solar cell device architecture has two main advantages over traditional p-n junction cells: (1) highly simplified fabrication and (2) excellent passivation of the semiconductor even under the contact.[87, 89] For traditional solar cells, highly doped regions are required to induce the charge selectivity, with the disadvantage of increased Auger recombination. The reduced carrier recombination of MIS solar cells led to open-circuit voltage ($V_{oc}$) values of up to 655 mV, surpassing those of traditional p-n junction solar cells in early development stages.[85] More recently, the extraordinary potential of the MIS concept has emerged again, with recent record silicon solar cells employing a carrier selective, tunnel oxide passivated contact at the back side, which is conceptually identical to the MIS structure.[89–91] Furthermore, the MIS junction has emerged as one of the most successful interfaces in photocatalysis in recent years, where the metal induces charge separation, catalyzes the chemical reaction and protects the underlying semiconductor.[92–95]

One major difficulty in applying MIS contacts to the front of a solar cell is the increased reflection due to the required metal coverage for homogenous junction formation. Early generations of MIS solar cells utilized thin metal layers and hence exhibited low short-circuit current densities ($J_{sc}$), while advanced generations introduced widely spaced macroscopic contact fingers which reduced the reflection substantially and led to substantial performance improvements.[96] To form a homogenous junction under the whole surface, additional dielectric layers with a high fixed charge density were employed, which however were insufficient to induce junction properties similar to diffused junctions or continuous metal layers.[96] Therefore, a low reflectivity combined with a high quality homogenous MIS junction over the entire surface, which is especially needed for materials with short carrier diffusion lengths, remains to be a challenge for the MIS device architecture. The decrease of transmittance with increasing metal coverage of homogenous
3.2 Experiment

MIS junctions can be overcome by nanoscale structures. Even though their electrical performance approaches those of continuous thin-films, engineered metal nanowire networks have been demonstrated to exhibit extraordinary transmission, where the transmission is larger than expected from geometric considerations.[97–102] Furthermore, nanowire networks can be fabricated on a large scale with roll-to-roll compatible processes, like nanoimprint lithography, or even using solution-synthesized metal nanowires.[103–106] Therefore, nanowire networks exhibit precisely the properties that are required for MIS solar cells: closely spaced and conductive metal wires, to induce a junction for homogenous carrier extraction, and simultaneously a high optical transparency.

Here, we demonstrate nanowire network based MIS silicon solar cells, by fabricating the nanowire networks on top of passivated silicon half cells using electron beam lithography. By choosing well passivated silicon as a base material, we are able to exclude any effects of short minority carrier diffusion lengths on our results. Our solar cells exhibit a measured conversion efficiency of 7%. After correcting for the influence of the small size of the active area on the $V_{oc}$ and the missing antireflection coating on the $J_{sc}$, we estimate that our MIS solar cells exhibit a corrected power conversion efficiency of $\sim$ 11% with an effective $V_{oc}$ of 560 mV and estimated $J_{sc}$ of 33 mA/cm$^2$. We perform electron beam-induced current (EBIC) measurements to prove that nanowire networks can be used to form an MIS junction, which leads to homogenous charge carrier extraction. Band diagram simulations allow us to investigate the dependence of the conduction type inversion on the work function difference between the metal and the semiconductor and hence to explain the relatively low $V_{oc}$. Reflection measurements show that a high metal coverage of the surface with metal nanowire networks only slightly increases reflection compared to a flat silicon surface. Finally, we demonstrate a first step towards improved device performance by using the metal nanowire network not only as a transparent electrode and for the inversion layer formation, but also as an etch mask for surface texturing. We fabricate inverted nanopyramids integrated into the metal nanowire network. As a result, we are able to decrease the reflectivity substantially from 36% to $\sim$ 4%. We use external quantum efficiency (EQE) measurements to estimate the influence of the reduced reflection on the overall device performance and thereby point out a path towards MIS solar cells that exhibit both high $V_{oc}$ and $J_{sc}$ values.

3.2 Experiment

3.2.1 Fabrication

To isolate the effect of the metal nanowire network on the MIS solar cell performance, we use a state-of-the-art contact scheme for the back of the solar cell, which is employed in industrial silicon heterojunction (SHJ) solar cells (Figure 3.1(a)). It consists of 5 nm of intrinsic a-Si:H followed by 8 nm of n-type a-Si:H, 80 nm ITO and 300 nm Ag. Due to the importance of the tunnel and passivation layer, we rely...
on a high quality double layer for the front surface, consisting of 3 nm intrinsic hydrogenated amorphous silicon (a-Si:H), followed by 1 nm of Al$_2$O$_3$.[107] The intrinsic a-Si:H is grown by inductively coupled plasma chemical vapor deposition (ICP-CVD) and is used due to the excellent chemical passivation properties on the silicon surface. The Al$_2$O$_3$ layer is grown by atomic layer deposition (ALD) and is known for its high stability and insulating properties.[108] When used directly on silicon, ALD Al$_2$O$_3$ has been shown to exhibit a high fixed charge density, which can lead to a field effect passivation of the underlying surface.[109–111] Besides the additional passivation effect, the Al$_2$O$_3$ also serves as a capping layer to prevent the out diffusion of hydrogen from the intrinsic a-Si:H layer. The metal nanowire network is fabricated by electron beam lithography on small areas (2.4 - 4.5 mm$^2$) and subsequent metal evaporation of Pd and Au. Pd was chosen due to the high work function to create a strong inversion layer, while Au was used because of lower optical losses than Pd. The low stability of Ag during subsequent processing precluded a possible usage of that metal. To integrate the inverted nanopyramid texturing in between the metal nanowire networks, the networks are fabricated on a silicon wafer, which is subsequently immersed in a KOH solution (further details in Supplemental Information).

### 3.3 Results

Figure 3.1(b) shows the fabricated Au-Pd nanowire network on top of the passivated substrate. The wires are 100 nm wide, 50 nm high (10 nm Pd/ 40 nm Au) and the pitch is 1 µm. The network is highly uniform and spans an area of 2.4 mm$^2$. Figure 3.2(a) shows the current density-voltage (J-V) traces of a masked nanowire network MIS solar cell under 1 sun illumination (green) and in the dark (red). The inset shows a schematic of the 2.4 mm$^2$ solar cell, which is created by fabricating a nanowire network (red) on top of a 2 cm$^2$ large substrate (blue). The silver back con-
3.3 Results

tact (grey), the contact probes (black) and the shadow mask (green) are indicated. The J-V curve in the dark shows a clear rectification. Under 1 sun illumination intensity, an open-circuit voltage ($V_{oc}$) of 423 mV, a short-circuit current density ($J_{sc}$) of 23 mA/cm$^2$ and a fill factor ($FF$) of 58% are obtained.

To account for the smaller size of the masked collection area (2.4 mm$^2$) compared to the substrate area (2 cm$^2$) we calculate the impact on the $V_{oc}$, with the main effect being the high contribution of the recombination current ($I_0$) originating from a larger area than the $J_{sc}$. As explained in detail in the SI, we use two different approaches to estimate the effective $V_{oc}$, both resulting in the same value of about 560 mV (see Figure 3.5-3.8). Finally, we estimate the current density with an antireflection (AR) ($n = 2$) coating with 10% residual reflectivity (simulated value), compared to the uncoated solar cell (36% measured reflectivity). Figure 3.2(b) shows a table with the measured and rescaled/estimated solar cell parameters, taking into account the aforementioned effects. As a result, the nanowire network MIS solar cell has an effective $V_{oc}$ of 560 mV, an estimated $J_{sc}$ of 33 mA/cm$^2$ and a $FF$ of 58%, resulting in an 11% energy conversion efficiency (after correction).

The results show that the metal nanowire network not only gives rise to charge carrier extraction, but also charge carrier separation inside the semiconductor, i.e. the metal nanowire network can potentially be used to replace the traditional contacts of an MIS solar cell. The small spacing of the metal networks makes our MIS concept applicable to materials with minority carrier diffusion lengths $\sim$1 $\mu$m, as is the case for many thin-film materials such as CIGS, CdTe, halide perovskites and GaAs (see also Figure 3.3).[112] However, our results also show that our obtained solar cell parameters, i.e. the $V_{oc}$, $J_{sc}$ and $FF$, are well below those of state of the

![Figure 3.2: Device performance.](image)

(a) J-V trace of nanowire network MIS solar cells in the dark (red) and under 1 sun (AM1.5G) illumination intensity (green). The active area shown here has a size of 2.4 mm$^2$ on a 2 cm$^2$ substrate. The measurements are performed under masked conditions. The inset shows the experimental geometry, where the nanowire network (red) and the shadow mask (green) are used to define the cell area. (b) Table with the measured and rescaled/estimated solar cell parameters.
art silicon solar cells. Therefore, we conduct the following electrical and optical analyses to get insight into the device performance and to point out crucial steps towards improvements.

Figure 3.9 and 3.10 show band diagram simulations which have been performed to study the dependence of the conduction type inversion, and hence selectivity of the MIS contact, on the work function (WF) difference between the n-type silicon and the adjacent metal. The simulations show that high metal work functions (>5 eV) can lead to strong conduction type inversion in the underlying silicon, the prerequisite for a high $V_{oc}$. Conversely, any decrease of the effective metal WF will lead to a decrease in the $V_{oc}$. After considering other possibilities, we conclude that the cause for the relatively low $V_{oc}$, when compared to state-of-the-art silicon solar cells (>700 mV), can be the lowering of the Pd vacuum work function due to the presence of the dielectric Al$_2$O$_3$. From developments in the field of complementary-metal-oxide-semiconductor (CMOS) transistors, it is known that Fermi level pinning to a charge neutrality level (CNL) in the dielectric can lower the effective work function of the metal.[113–115] Therefore, other dielectrics, e.g. SiO$_2$, that cause much weaker Fermi level pinning to the CNL should be employed in future devices. However, when searching for alternatives the stability and passivation properties for ultrathin layers have to be kept in mind. For a detailed discussion see SI.

Besides the aforementioned reasons, the typically high costs associated with high WF metals (Ag, Au, Pd, Pt) and their potentially detrimental influence on the material quality (e.g. lifetime) have to be considered. Therefore, high WF oxides (e.g. MoO$_3$) are a promising alternative as an interfacial layer.[28, 116, 117] The same holds for layers of doped semiconductors, like n-type (and p-type) a-Si:H in high-efficiency silicon heterojunction (SHJ) solar cells.[10, 89, 118] However, as also

![Figure 3.3: Electron-beam-induced-current (EBIC) measurement.](image)

(a) SEM image of a region of interest (ROI) of a similar sample to the one shown in Figure 3.2. Two residual metal flakes from the fabrication can be seen. (b) EBIC measurements, showing a uniform charge carrier separation and collection in the ROI due to the closely spaced metal nanowire network and the large carrier diffusion lengths in silicon. We note that the shadowed regions due to the metal nanowires are smaller for a sample under light illumination, because of efficient directional scattering by optical (plasmon) resonances.
3.3 Results

our results show (see Figure 3.13) the stability and process compatibility, especially with nanostructuring have to be considered when employing such layers.[119]

Besides the degree of conduction type inversion, the simulations also show that the depth of the inversion layer extends to about 200 nm into the silicon, depending on the metal work function. Given the nanowire network pitch of 1 μm and assuming a constant radial extent of the inversion around the metal as an upper bound, a large fraction of the silicon square between the metal wires is inverted close to the surface. Electron-beam-induced-current (EBIC) measurements (Figure 3.3) show that this conduction type inversion, together with the large diffusion lengths in silicon lead to homogenous carrier collection.

As can be seen in Figure 3.2, the $J_{sc}$ of our solar cell reaches a value of 23 mA/cm$^2$. We ascribe the primary deviation from state-of-the-art silicon solar cells ($\sim 42$ mA/cm$^2$) to the high reflectivity of the uncoated and flat silicon substrate. Therefore, we measure the total reflectance of the completed devices using an integrating sphere setup. Then, we introduce a low reflectivity structure, consisting of nanopyramids integrated in between the nanowire network. We use EQE measurements to estimate the effect on the final device performance, as a first step towards improved $J_{sc}$ values for nanostructured MIS solar cells.

Figure 3.4(a) shows the measured reflection values of the nanowire network solar cell (blue), the network with integrated inverted nanopyramids (orange) and a bare polished silicon surface as reference (green). FDTD Simulations were used to obtain an estimate of the residual reflection when a standard anti-reflection coating (n=2) of 80 nm would be included on top of the flat nanowire network solar cell (violet). The average reflectivity ($\bar{R}$) in the wavelength range from 420 - 900 nm is also shown for the different structures. Figure 3.4(c) shows the measured external quantum efficiency (EQE, extracted charge carriers per incident photon) of the flat nanowire network solar cell (blue line). The curve shows relatively uniform quantum efficiency over the visible range. Taking into account the measured reflection and the simulated absorption in the metal, the internal quantum efficiency (IQE, extracted charge carriers per absorbed photon in the semiconductor) was determined (black line). For wavelengths below the band gap of silicon (1.1 eV) the IQE increases until it reaches unity in the range between 600 - 800 nm. For short wavelengths, the IQE drops to a value of $\sim 0.8$, indicating charge carrier recombination near the front surface. The effect of detrimental absorption in the metal can be seen for the IQE with the metal absorption (grey line). To estimate the effect of a standard SiN AR coating on the optical response of the solar cell, the EQE was calculated taking into account the simulated reflection of Figure 3.4(a) (violet dashed line).

The measurements and simulations in Figure 3.4(a) show that the nanowire network only adds a small amount of additional reflection, the value increases from 33% for a bare silicon surface to 36%. For this sample we measured a $J_{sc}$ of 23 mA/cm$^2$ (see Figure 3.4(a) and 3.4(c)). A standard 80 nm AR coating (n = 2) can reduce the reflection of the flat nanowire network silicon surface to $\sim 9\%$, which would result in a short-circuit current density of $\sim 33$ mA/cm$^2$ (see Figure 3.4(c)).
Figure 3.4: Reflection, EQE, IQE and inverted nanopyramids. (a) Reflection measurements (solid lines) of silicon reference wafer (green), a solar cell with a metal nanowire network (NWN) with a pitch of 1 µm and a nanowire width of 100 nm (blue) and a sample with integrated inverted nanopyramids between the metal nanowires (orange). Also shown are the simulated reflection values (dashed lines) of the flat metal network with 80 nm SiN coating for a wire width of 100 nm (violet) and the integrated inverted nanopyramid metal nanowire structure with 100 nm SiN coating on top of 50 nm wide wires (red). The average reflection values between 420 - 900 nm are listed next to the legend. (b) Scanning electron microscopy image of a metal nanowire network with integrated inverted nanopyramids. A high-resolution SEM is shown as an inset. (c) External quantum efficiency (EQE) of solar cell with metal nanowire network (blue). The IQE was determined by accounting for the reflection (blue line in (a)) and the simulated absorption of the metal network. The simulated reflection curves in (a) for the SiN coating (violet) and the integrated nanopyramid nanowire structure (red) were used to estimate the effect on the EQE of the final device. The respective short-circuit current densities are depicted next to the legend.

The measured $J_{sc}$ of 23 mA/cm$^2$ (see Figure 3.2(a) was obtained for a MIS solar cell with a bare nanowire network silicon surface with an average reflection of 36%. Therefore, the photocurrent density after subtracting the reflection losses amounts to 36 mA/cm$^2$ (grey curve in Figure 3.4(c), which shows that a large fraction of the photogenerated charges is collected. However, since it does not reach the maximum photocurrent density under 1 sun illumination for silicon ($\sim$ 44 mA/cm$^2$), we conclude that other loss mechanisms must be present, which are discussed below.
Figure 3.11 shows the simulated reflection, transmission and absorption values for a metal nanowire network with the dimensions mentioned above on a flat silicon wafer. As can be seen, the averaged absorption amounts to \( \sim 10\% \) in the 420 - 900 nm spectral range. Therefore, we conclude, that the short-circuit current density is partly lowered due to absorption in the metal by approximately 4 mA/cm\(^2\) to the value of 36 mA/cm\(^2\) (black curve in Figure 3.4(c)). A potentially detrimental influence of the tunnel junction, which could result in nonlinear current-voltage behavior, was ruled out by measurements of the \( J_{sc} \) under different illumination intensities, which prove that the 1 nm Al\(_2\)O\(_3\) has a negligible tunnel resistance under normal operation conditions (see Figure 3.12).[120] Previous research has shown that the insulator thickness for MIS type solar cells should not exceed 2 nm to limit the tunnel resistance.[87, 88] Another origin of the photocurrent loss can be attributed to fabrication-induced defect formation. After the fabrication of the metal nanowire networks we encounter strongly s-shaped I-V curves, which can be attributed to charge carrier extraction barriers at the contact-silicon interfaces.[77] We anneal our samples until the s-shape is completely removed. We ascribe the damage mostly to the electron beam exposure of the a-Si:H.[119] With increasing annealing temperatures, the \( I_{sc} \) (and \( FF \)) of the solar cells is monotonically increasing. However, the \( V_{oc} \) reaches its maximum at around 220 - 230 °C, after which it starts to decrease. Therefore, we chose the annealing temperature not to exceed 220 °C, recovering the maximum \( V_{oc} \), while being aware of the non-optimized \( I_{sc} \) (and \( FF \)) values, due to residual fabrication induced defects. For further explanation, see the Figure 3.13. The IQE (black curve) in Figure 3.4(c) shows a decrease in IQE for short wavelength until it reaches \( \sim 0.8 \). This supports our assumption as light in the short wavelengths range is absorbed close to the surface, where the fabrication induced defects must be located. Therefore, the annealing behavior and the absorption in the metal nanowire network discussed above can explain the main difference between the \( J_{sc} \) of our solar cells (36 mA/cm\(^2\), after reflection) and a \( J_{sc} \) of 42 mA/cm\(^2\), which is reached by highly efficient silicon solar cells. We note that other losses, such as parasitic absorption in the thin a-Si:H layer, are likely to be present.[121]

As a first step towards improved \( J_{sc} \) values for nanostructured MIS solar cells, we fabricate inverted nanopyramids integrated in between the metal nanowire network. Bare inverted nanopyramids with optimized pitch and additional AR coating have shown outstanding optical performance.[122, 123] Furthermore, etch resistant metals, such as the ones employed for our metal nanowire network, are frequently used as masking layers in micro-and nanofabrication.[124, 125] Figure 3.4(b) shows a scanning electron microscopy (SEM) image (magnified in the inset) of the fabricated inverted nanopyramid nanowire network structure. The measured reflection of the network with inverted pyramids (Figure 3.4(a), solid yellow line) shows clear resonant features due to the diffraction modes created by the effective grating. The average reflectivity of 19% proves the strong decrease in reflection compared to the flat nanowire network surface. By simulating an additional AR coating of 100 nm on top of the nanopyramid structure and a nanowire width of
50 nm instead of 100 nm (Figure 3.4(a), dashed red line) we show that the residual reflection can be even further reduced to 4%, which is well below the optimized AR coating for a flat silicon nanowire network surface (9%) (solid violet line). Figure 3.4(c) shows the effect of the integrated nanopyramid texturing on the EQE (red dashed curve), which results in a $J_{sc}$ of $\sim 35$ mA/cm$^2$. We stress that a further decrease in reflection with optimized dimensions, e.g. AR coating thickness and wire thickness, can be expected. However, the optimization of the non-trivial optical response, as well as the integration into the solar cell fabrication process of the metal nanowire network with integrated nanopyramids is beyond the scope of this report and focus of ongoing research.

3.4 Conclusions

We successfully apply metal nanowire networks to the MIS solar cell scheme. After correcting for the influence of the small size of the active area on the $V_{oc}$ and the missing anti-reflection coating, our MIS solar cells exhibit a corrected power conversion efficiency of $\sim 11\%$ with an effective $V_{oc}$ of 560 mV and estimated $J_{sc}$ of 33 mA/cm$^2$. We use EBIC measurements to show that the metal nanowire network homogenously extracts charge carriers via an inversion layer in the underlying silicon. Band diagram simulations allow us to investigate the dependence of the conduction type inversion on the work function difference between the metal and the semiconductor and indicate the occurrence of Fermi level pinning at a charge neutrality level at the metal dielectric interface. Reflection measurements show that a high metal coverage of the surface with metal nanowire networks only adds 3% of additional reflection compared to a flat silicon surface.

Finally, we demonstrate a first step towards improved device performance by using the metal nanowire network not only as a transparent electrode and for the inversion layer formation, but also as an etch mask for surface texturing. We fabricate inverted nanopyramids integrated into the metal nanowire network. This way we are able to decrease the reflectivity substantially from 36% to $\sim 4\%$. We use external quantum efficiency (EQE) measurements to estimate the influence of the reduced reflection on the overall device performance and thereby point out a path towards MIS solar cells that exhibit both high $V_{oc}$ and $J_{sc}$ values. Furthermore, our work shows potential for the MIS concept to be used to directly contact well passivated, intrinsic semiconducting layers, which naturally show higher carrier lifetimes and mobilities and are therefore preferable for high efficiency solar cells. Finally, our results are not limited to silicon, but can be applied to many thin-film materials with small charge carrier diffusion lengths where the difficulty of doping makes carrier selective contact formation more challenging.
3.5 Supplemental information

3.5.1 Fabrication details

To isolate the effect of the metal nanowire network on the MIS solar cell performance, we are using a state-of-the-art contact scheme for the back of the solar cell, which is employed in industrial solar cells (see Figure 3.1). This half cell consists of a double side polished float zone silicon base wafer with low n-type doping (3 Ohmcm), followed by different layers which create the back contact; a thin-film of intrinsic hydrogenated amorphous silicon (a-Si:H) (5 nm) followed by a layer of highly doped n-type a-Si:H (8 nm) are grown on the silicon wafer by plasma enhanced chemical vapor deposition (PECVD, Roth & Rau). The n-type a-Si:H is contacted via a sputtered indium tin oxide (ITO) layer (80 nm), followed by a sputtered silver layer (300 nm) as metal contact (Roth & Rau AK tool system).

The passivating and insulating layer, which is grown on the front surface after a short HF treatment (45 s in 1%), consists of 3 nm intrinsic a-Si:H followed by 1 nm of Al₂O₃.[107] The a-Si:H is grown by inductively coupled plasma chemical vapor deposition (ICP-CVD, PlasmaLab System 100, Oxford Instruments) and is used due to the excellent chemical passivation properties on the silicon surface. An argon and silane flow of 20 sccm, a temperature of 50 °C and a power of 400 W at a pressure of 10 mTorr were used for 24 s (~ 3 nm thickness). The Al₂O₃ layer (9 cycles with a total nominal thickness of ~ 1 nm) is grown by atomic layer deposition (ALD) (OpAL, Oxford Instruments) at 190 °C with trimethylaluminum (TMA) and O₂ plasma. Al₂O₃ is known for its high stability and insulating properties. When used directly on silicon, ALD Al₂O₃ has been shown to exhibit a high fixed charge density, which can lead to a field effect passivation of the underlying surface.[108–111] Subsequently, the samples were exposed to N₂ atmosphere in a rapid thermal annealing oven at 190°C for 30 min.

The passivated and back contacted half cells were fabricated on 4 inch wafers, which were subsequently cut into about 2-3 cm² small pieces to allow the optimization of the following fabrication steps.

The square metal network (nanowire width ~ 100 nm, network pitch ~ 1-2 μm) is fabricated by electron beam lithography (EBL) on small areas (2.4 - 4.5 mm²) on ~ 2 cm² substrates. EBL resist ZEP 520 A (Zeonrex Electronic Chemicals) is used in a 2:1 mixture with anisole and spun (1000 rpm for 40 s) to achieve a resist thickness of ~ 200 nm. Afterwards, the substrates are baked at 180 °C for 5 min. The resist is exposed with 30 kV beam acceleration at a dose of 400 μC/cm² (10 μm aperture) in a fixed beam-moving stage modus (FBMS), with a predefined square nanowire network structure with pitches of 1 μm and 2 μm. After developing in pentyacetate for 1 min the samples are rinsed for 15 s in a 9:1 mixture of methyl isobutyl ketone (MIBK) and isopropanol (IPA) and additionally for 15 s in pure IPA.

The samples are blow-dried with nitrogen and transferred to the vacuum chamber of an electron beam evaporator. At a pressure of ~ 5×10⁻⁷ mbar, first a 10 nm thin layer of palladium, followed by a 40 nm thin layer of gold are evaporated at a
rate of 0.2 - 0.5 Å/s from water-cooled copper and tungsten crucibles, respectively. The Pd and the Au pellets are of at least 99.95% purity. This double structure is used because of the higher work function (WF) of Pd (5.2 - 5.6 eV) than Au (5.1 - 5.5 eV), which allows a stronger inversion in the underlying silicon, and the lower optical losses of Au compared to Pd.

After the evaporation, the samples are immersed in warm acetone (50 °C) to dissolve the EBL resist and this way lift-off the redundant metal film, leaving behind the desired square metal nanowire network structure. Metal pads for later contacting purposes are placed on two sides of the square network with conventional UV lithography and subsequent metal evaporation, using a 100 nm, opaque Au layer.

Electron beam (e-beam) and intense UV light exposure is known to cause damage in a-Si:H. Therefore, the samples are subsequently transferred into a vacuum oven and annealed for 60 min at a pressure of 5x10^{-5} mbar and a temperature of 220 °C to reverse the majority of the damage (see Figure 3.13).

The integrated inverted nanopyramids in between the metal nanowire network were fabricated by first fabricating the metal nanowire network on a simple silicon wafer and subsequently immersing the sample into KOH etching solution (30%) for 2 min. at a temperature of 20 °C. The metal (Pd/Au) nanowire network acts as an etching mask for the KOH solution and allows therefore the crystal plane selective dissolution of silicon, with the (111) crystal plane having the slowest etch rate.

### 3.5.2 Electrical and optical characterization

The J-V traces of the fabricated solar cells are measured under a solar simulator (Oriel SOL2 94062A (6X6) Class ABA, Newport) with the AM1.5G spectrum at 1 sun (100 mW/cm^2) illumination intensity, under masked conditions and at a temperature of 50 °C. The lamp intensity of the solar simulator is adjusted with a silicon reference cell. The right masking conditions are a crucial step for our solar cells, as the network only covers a small part (2 - 4.5 mm^2) of the passivated silicon half cells (2-3 cm^2 small substrates) (see Figure 3.5). Electrical probes are used to contact the front pad of the nanowire network and the back contact of the whole substrate with a source measure unit (Agilent B2910). The voltage is scanned with a positive and negative scan rate between -1V and 1V in 2001 steps while the current is being measured. No pronounced hysteresis or instability could be detected during the course of the measurements.

A lifetime of 1 ms was measured on the back contacted (w/o ITO) and front passivated silicon wafers before the nanowire network fabrication with a Sinton WCT-120TS lifetime tester.

The reflection measurements are performed using an integrating sphere setup. A supercontinuum white light source (Fianium) is used to illuminate the solar cells. The unpolarized light is weakly focused on the back plane of the sphere (4 inch Labsphere) to ensure near to normal incidence. A 105 μm core fiber is used to collect the reflected light and send it to a spectrometer, consisting of a spectrograph (Spectrapro 2300i) and a Si CCD array (PIXIS 400 CCD, cooled to -70 °C). The
measurements cover the 420 - 970 nm spectral range, and a 400 ms integration time with 50 accumulations were used.

### 3.5.3 Simulations

The band diagram simulations are performed with the software package AFORS-HET.[126] The simulated structure consists of an n-type Si wafer with a base doping of $1.6 \times 10^{15} \text{ cm}^{-3}$, a 3 nm intrinsic a-Si:H layer, a 1 nm $\text{Al}_2\text{O}_3$ layer and a metal contact which is simulated by having a fixed work function as boundary condition. Fixed charge is placed at the a-Si:H/$\text{Al}_2\text{O}_3$ interface. For the material properties, the default simulation values provided by AFORS-HET are used. Simulations are performed in the dark.

The finite difference time domain (FDTD) simulations are performed with the software package Lumerical to obtain the reflection values for the 80 nm silicon nitride coated ($n = 2$) network with and without integrated inverted nanopyramids. The network has a pitch of 1 $\mu$m, a nanowire width of 100 nm (50 nm for red data in Fig. 3.4) and a thickness of 50 nm, with 40 nm of Au (top) and 10 nm Pd (bottom). A plane wave ($\lambda = 400 - 1100$ nm) under normal incidence and a power monitor, positioned above the nanowire network, are used to determine the reflectance. A perfectly matched layer as boundary condition in vertical direction is used to prevent scattering artifacts from the edges of the simulation box, while periodic boundary conditions are used for the in-plane dimensions to simulate an infinite network. The mesh size was 2 nm and the optical constants for Au, Pd and Si are taken from Palik.

### 3.5.4 Influence of active area size

In the following, we investigate the effect of the small size (2.4 - 4.5 mm$^2$) of the illuminated area on the open-circuit voltage. The illuminated area equals the area

![Figure 3.5: Influence of masking condition.](image)

(a), (b) The measurements under illumination are done with a mask (green), which covers the areas of the passivated and back contacted silicon substrate (blue). The mask has an opening in the middle, which allows illumination of the area with the fabricated metal nanowire network (red). (c) The measured $V_{oc}$ is strongly affected by the relatively larger contribution of $J_0$ compared to $J_L$. Therefore, the effect is investigated and an effective $V_{oc}$ derived, which allows the estimation of the solar cell performance, for which the substrate has the same size as the active area, as depicted here.
of the nanowire network, which has been limited in size due to the use of e-beam lithography. Taking into account that $J_0$ stems from a much larger region than the photocurrent, we are able to estimate the open-circuit voltage for a 1 cm$^2$ sample. This way we are able to evaluate and compare our results with regard to other solar cell device architectures.

We use two approaches, based on two separate sets of measurements, that both yield the same result for the estimated $V_{oc}$. The first approach investigates the scaling behavior of the recombination parameter $J_0$ with different sample sizes.

The second approach studies the variation of the $V_{oc}$ for two different measurements; under masked and under unmasked conditions. This second approach makes use of the fact that the $V_{oc}$ can be related to the carrier concentration inside the solar cell (implied $V_{oc}$).[19]

Because we employ high-purity monocrystalline FZ-silicon wafers we attribute the main contribution to $J_0$ to stem from recombination active surface sites. This surface recombination originates mostly from a larger area than the illuminated one. It is facilitated via diffusion of carriers to unilluminated regions and further to respective recombination sites. The diffusion is therefore taking place because of the difference in the carrier concentrations between the illuminated and the dark regions and between the recombination inactive bulk and recombination active surface.

**Scaling behavior of $J_0$ with active area size**

We compare three samples (S1-S3) that are fabricated in the exact same way but with different sizes of the metal nanowire network (2.4 - 4.5 mm$^2$). The short-circuit current density for 1 sun illumination is approximately the same for all the fabricated samples which strongly supports the reproducibility of our fabrication scheme.

$J_0$ mainly originates from surface recombination. However, the exact size of the surface area which causes $J_0$ is unknown. Under illumination, the diffusion

---

**Figure 3.6: Origin of large recombination current.** (a) The main contribution to $J_0$ is originating from surface recombination, as derived and described in the text. (b) The illuminated area $A_L$ is much smaller than the area $A_S$, which significantly contributes to the recombination current density $J_0$. 

---
of photo-generated charge carriers to recombination active surface sites has to be taken into account and hence forbids any simple estimation of the contribution of any single dimension or region (e.g. the whole substrate area). Nonetheless, by using three samples, that have been fabricated under the exact same conditions, but are of different size, and investigating the scaling behavior of the recombination current density $J_0$, we are able to estimate the value of $J_0$ for a standardized sample size of 1 cm$^2$.

The ideal diode equation results in the well-known $V_{oc}$ equation:

$$V_{oc} = \frac{n \times k_T}{q} \times \ln \left( \frac{J_L}{J_0} + 1 \right) \sim \frac{n \times k_T}{q} \times \ln \left( \frac{J_L}{J_0} \right)$$

(3.1)

with the ideality factor $n$, the Boltzmann constant $K$, temperature $T$, the elementary charge $q$, the photocurrent density $J_L$ and the recombination current density $J_0$.

In the following, we assume an ideality factor of $n = 1$, but this assumption has no influence of the scaling of $J_0$. Using the above equation, we calculate the recombination parameter $J_0$ for the three samples under illumination. The temperature during the measurements was $\sim 50 ^\circ C$ (323 K) and the respective measured $V_{oc}$ and $J_{sc}$ values are listed in Table 3.1:

$$J_0 = \exp \left( - \frac{V_{oc}}{27.8 \, mV} \times J_L \right)$$

(3.2)

$J_0^{S_1} = 6.60 \times 10^{-9} A/cm^2$, $J_0^{S_2} = 2.90 \times 10^{-9} A/cm^2$, $J_0^{S_3} = 1.68 \times 10^{-9} A/cm^2$.

In general, $J_0^{tot}$ can be expressed as the sum of the different recombination processes:[127]

$$J_0^{tot} = J_0^{Surf} + J_0^{SRH} + J_0^{Aug} + J_0^{Rad}.$$  (3.3)

$J_0^{Surf}$ stems from surface recombination, $J_0^{SRH}$ from Shockley-Read-Hall (SRH) recombination, $J_0^{Aug}$ from Auger recombination and $J_0^{Rad}$ from radiative/ band-to-band recombination. Often, $J_0^{tot}$ is also separated according to the different regions in the solar cell from which the respective $J_0$ originates (e.g. for a n$^-$-emitter). As

<table>
<thead>
<tr>
<th>Sample</th>
<th>Area [mm$^2$]</th>
<th>$V_{oc}$ [mV]</th>
<th>$J_{sc}$ [mA/cm$^2$]</th>
<th>$J_0$ [A/cm$^2$]</th>
</tr>
</thead>
<tbody>
<tr>
<td>S1</td>
<td>2.4</td>
<td>419 (M)</td>
<td>23.2 (M)</td>
<td>660x10$^{-11}$ (C)</td>
</tr>
<tr>
<td>S2</td>
<td>3</td>
<td>439 (M)</td>
<td>21.0 (M)</td>
<td>290x10$^{-11}$ (C)</td>
</tr>
<tr>
<td>S3</td>
<td>4.5</td>
<td>457 (M)</td>
<td>23.3 (M)</td>
<td>168x10$^{-11}$ (C)</td>
</tr>
<tr>
<td>$S_{a-1}$</td>
<td>100</td>
<td>562 (C)</td>
<td>23.2 (E)</td>
<td>3.97x10$^{-11}$ (F)</td>
</tr>
</tbody>
</table>

Table 3.1: Solar cell parameters for differently sized samples. Measured (M), calculated (C), estimated (E) and fitted (F) solar cell parameters of the small area samples S1-S3 and the estimated 1 cm$^2$ sample $S_{a-1}$.
mentioned above, we expect the main contributor to be $J_0^{surf}$ due to the absence of highly doped regions and the high crystal quality of the FZ-silicon base wafer.

For our small samples we expect approximately a $1/A_i$ dependence for the $J_0$, especially with increasing area size up to $1 \text{ cm}^2$. The total recombination current can be approximated as a constant that originates from a much larger area (for surface recombination) or volume (for SRH and Auger):

$$J_0^{Si}(A_i) = I_0^{Tot}.$$  \(3.4\)

For increasing area size, but with $A_i < 1 \text{ cm}^2$, $J_0$ approaches more accurately a value that represents the recombination originating from a $1 \text{ cm}^2$ sample. However, for the measured samples we expect a deviation from the $1/A$ dependency, due to the nature of our samples. As we show in Figure 3.13, we observe electron beam-induced damage in the top 3 nm a-Si:H layer which can mostly be removed with a post fabrication anneal. However, as we discuss below, we are not able to remove all the induced damage. We choose an annealing temperature that is optimized with regard to the $V_{oc}$, but we cannot prove that this maximum $V_{oc}$ is completely unaffected by the damage. As a result, we expect a slightly higher $J_0$ for the fabricated samples, than a simple $1/A$ dependency would suggest. However, even for those samples the major $J_0$ contribution will stem from a much larger area than the illuminated one, unrelated to the electron beam-induced degradation.

Because of those reasons, we use a least squares fit method, to fit an equation of the following form to our calculated $J_0$ values:

$$f(x) = \frac{p}{x^q}.$$  \(3.5\)
As shown in Fig. 3.7, we obtain good agreement with $p = 3.90 \times 10^{-9}$ and $q = -1.85$:

$$j_0^{S_a} \approx \frac{3.90 \times 10^{-9}}{A_x - 1.85} \text{A/cm}^2$$

Therefore, we can estimate the recombination parameter $j_0^{S_a}$ for a 1 cm$^2$ large sample:

$$j_0^{S_a} = 3.97 \times 10^{-11} \text{A/cm}^2$$

Finally, we can calculate the $V_{oc}$ of the 1 cm$^2$ sample $S_a$, assuming a short-circuit current density as observed for samples S1 and S3, i.e. $\approx 23.2 \text{mA/cm}^2$. As discussed above, setting the ideality factor to $n = 1$ does not influence our result, as the estimated $j_0^{S_a}$ would have been higher for $2 > n > 1$.

$$V_{oc}^{S_a} \approx n \times 27.8 \text{mV} \times \ln \left( \frac{j_L^{S_a}}{j_0^{S_a}} \right)$$

$$V_{oc}^{S_a} \approx 562 \text{mV} (n = 1, j_L^{S_a} = j_L^{S_i})$$

**Influence of masking conditions on carrier concentrations**

The second approach makes use of the fact, that the $V_{oc}$ is related to the carrier concentrations:[19]

$$V_{oc}^{imp} = k_B T \times \ln \left( \frac{(N_A + \Delta n)\Delta n}{n_i^2} \right)$$

$N_A$ is the doping concentration, $\Delta n$ is the excess and $n_i$ the intrinsic carrier concentration. $V_{oc}^{imp}$ is the implied open-circuit voltage, because it can be seen as the $V_{oc}$ that is implied by the carrier concentrations inside the semiconductor. For the actual $V_{oc}$ the energy levels of the contacts for the charge carrier extraction have to be considered, as well. By comparing measurements under illumination of a masked and an unmasked sample we can show that the carrier concentration for the masked sample is the limiting case. The energy levels of the contacts, determined by the metal WF for the (MIS) hole contact and the a-Si:H n-type doping for the electron contact, allow for a substantially higher $V_{oc}$.

As shown in Figure 3.8, the lateral diffusive currents lead to a decrease in the carrier concentrations in the small illuminated region. This decrease directly results in a decrease in the quasi-Fermi level splitting, i.e. the $V_{oc}^{imp}$. In other words, the carrier concentration is reduced compared to a case of complete substrate illumination. For the latter, only gradients in the carrier concentrations due to the surface recombination exist. However, the interpretation of an unmasked measurement for which the complete substrate is illuminated has to be done with caution.

First of all, only a small part of the area that is illuminated is also patterned with the nanowire network. The optical properties of the flat metal nanowire network on top of silicon are very similar to a flat bare silicon substrate, i.e. 36 vs. 33 %
Figure 3.8: Schematic band diagram with lateral diffusion. Differences in carrier concentrations between the illuminated and the dark regions inside the bulk n-type wafer lead to gradients in the quasi-Fermi levels. Those in turn result in diffusive transport (red arrows) away from the illuminated region. The result is a lower implied $V_{oc}$.

Reflection, and 10% additional absorption, as shown in Figure 3.4. However, because of the logarithmic dependence of the $V_{oc}$ on the $I_{sc}$, the overestimation can be neglected. Therefore, the $V_{oc}$-loss due to lateral diffusion, $\Delta V_{oc}^{diff}$, is given by:

$$\Delta V_{oc}^{diff} = V_{oc}^{S1\_nomask} - V_{oc}^{S1\_mask} - V_{oc}^{S1\_optical} \approx 100\, mV$$  \hspace{1cm} (3.11)$$

$\Delta V_{oc}^{optical}$ is the $V_{oc}$-overestimation due to the lower reflection of the bare silicon surface and the absence of metal absorption. However, as we argued above, $V_{oc}^{S1\_optical} \sim 0\, mV$. $V_{oc}^{\_nomask}$ and $V_{oc}^{\_mask}$ are the open-circuit voltages of the unmasked and masked samples, respectively.

Furthermore, the $I_{sc}$ of the unmasked sample is substantially higher than for the masked sample, especially for high purity silicon with its large minority carrier diffusion lengths. However, it does not reach the $I_{sc}$ values predicted for a 1 cm$^2$ sample, i.e. 23 mA. For our measurement the unmasked $I_{sc}$ is about 10 times higher than the masked one, i.e. 5.58 mA vs. 0.557 mA, as shown in Table 3.2. Therefore, we can estimate the area to be roughly 10 times larger than the 2.4 mm$^2$ small sample (neglecting the slightly different optical properties). Furthermore, the recombination current $I_0$ for a 24 mm$^2$ area is close to the value for a 100 mm$^2$ area (see also the extensive discussion above). Hence, we can estimate the additional gain in $V_{oc}$
### 3.5 Supplemental information

#### Table 3.2: Measured solar cell parameters with and without mask.

<table>
<thead>
<tr>
<th>Sample</th>
<th>Area [mm²]</th>
<th>$V_{oc}$ [mV]</th>
<th>$I_{sc}$ [mA]</th>
<th>$I_0$</th>
</tr>
</thead>
<tbody>
<tr>
<td>$S_1^m$ (masked)</td>
<td>2.4</td>
<td>419</td>
<td>0.557</td>
<td>$I_0^{S_1^m}$</td>
</tr>
<tr>
<td>$S_{unm}^1$ (unmasked) (unknown)</td>
<td>~24</td>
<td>519</td>
<td>5.580</td>
<td>1</td>
</tr>
<tr>
<td>$S_{a-2}$</td>
<td>100</td>
<td>559 (C)</td>
<td>23.3 (E)</td>
<td>4.17</td>
</tr>
</tbody>
</table>

Measured solar cell parameters of the small area sample S1 with and without a shadow mask. Calculated (C) and estimated (E) parameters for the 1 cm² sample $S_{a-2}$.

For a 100 mm² sample due to an increase of $I_{sc}$ to 23 mA, with the term $\Delta V_{oc}^{light}$.

$$\Delta V_{oc}^{light} = 27.8 mV \times ln(4.17) \approx 40 mV \quad (3.12)$$

We note, that this approximation leads to a conservative estimate of the additional $V_{oc}$-gain because we use an $I_0$ that stems from a 100 mm² sized sample. Another deviation is expected due to the less efficient carrier extraction in the case of the unmasked sample which heavily impacts the resistance and hence fill factor of the unmasked solar cells. The current of 5.58 mA of the unmasked sample is separated and collected with the same inversion layer and metal nanowire network than the 0.557 mA of the masked sample. Nonetheless, we can estimate the $V_{oc}$ for a 1 cm² sample:

$$\Delta V_{S_{x2}}^{S_{a-2}} = V_{oc}^{S_{x2}} + \Delta V_{oc}^{light} \left( I_0^{S_{x2}} \sim I_0^{S_{unm}} \right) + \Delta V_{oc}^{diff} \approx 559 mV \quad (3.13)$$

Comparing the scaling behavior of the $J_0$ and the variation of the $V_{oc}$ for different masking conditions shows close agreement for the $V_{oc}$ of a 1 cm² sample:

$$V_{oc}^{S_{x2}} \sim 559 mV \sim V_{oc}^{S_{a-2}} = 562 mV \quad (3.14)$$

### 3.5.5 Band diagram simulations

#### Influence of work function

Figure 3.9 shows the results of band diagram simulations, which are performed to investigate the influence of different metal work functions (WF) on the inversion of the n-type silicon. For the chosen WFs between 4.6 - 5.6 eV the conduction bands ($E_C$) and the valence bands ($E_V$) are plotted. All the Fermi levels ($E_F$) are set to 0 eV for clarity. The metal next to the adjacent $Al_2O_3$ is not shown. As can be seen, the WF of the metal determines the extent of the conduction type inversion in the semiconductor. N-type silicon has a WF of around 4.2 eV, hence employing metals with higher WFs reduces the free electron concentration in the n-type silicon, even leading to strong conduction type inversion in the extreme case. For comparison,
3 Metal-Insulator-Semiconductor Nanowire Network Solar Cells

Figure 3.9: Band diagram simulations for the metal work function influence.

Band diagram simulations showing the influence of the metal work function for the conduction type inversion in silicon. The conduction bands ($E_C$) are plotted in the upper half ($E>0$ eV) and the valence bands ($E_V$) in the lower half of the figure ($E<0$ eV). For a better overview all the Fermi levels ($E_F$) are set to 0 eV.

silicon that is strongly p-type doped ($p^+$) has a WF of around 5.3 eV. The simulations show that for WFs between 4.6 - 5.2 eV, an increase in the WF leads to increased inversion. Above ~ 5.2 eV on the other hand, the additional inversion with increasing metal WF becomes less pronounced. Besides the logarithmic dependence of the Fermi level position, part of this decreasing sensitivity of the inversion with increasing WF can be ascribed to the intrinsic (low conductivity) a-Si:H. Between 5.2 - 5.6 eV the initial energy difference of the conduction bands (red, violet and blue lines) at the metal - a-Si:H interface falls off over the intrinsic a-Si:H.

In the simulations shown here, no additional fixed charge density ($Q_f$) of the $\text{Al}_2\text{O}_3$ at the metal - a-Si:H interface is assumed. As shown in Figure 3.10, and discussed in detail below, only an additional fixed charge density with very high (negative) $Q_f$ values of around $10^{13}$ cm$^{-2}$ has a substantial effect for high WF metals. For low WF metals (<5 eV) $Q_f$ values above $10^{12}$ cm$^{-2}$ can already substantially improve the inversion.

Influence of fixed charged density

$\text{Al}_2\text{O}_3$ is known to exhibit a fixed charge density at a $\text{Al}_2\text{O}_3$-silicon interface, which can lead to electrical passivation of the interface, by repelling minority carriers with the same polarity of the surface charge. This so called field-effect passivation is being used in solar cells to increase the lifetime of the minority carriers by preventing their diffusion towards recombination active surface/interface sides. For the tunnel and passivation layer employed in this work, consisting of a 1 nm $\text{Al}_2\text{O}_3$
and a 3 nm a-Si:H layer, the occurrence of a fixed charge density is being debated at the moment. Therefore, we performed band diagram simulations to investigate the effect of a potential fixed charge density on the magnitude of the inversion layer. In principle, a fixed charge density could lead to a stronger inversion in MIS type solar cells than given by the difference in work function between the metal and the adjacent semiconductor. Figure 3.10 shows the magnitude of the conduction type inversion for a metal work function of 4.6 eV (3.10(a)) and 5 eV (3.10(b)) in dependence of a fixed charge density at the Al$_2$O$_3$/a-$\text{Si}$:H interface. The interface charge density $Q_f$ changes between 0 cm$^{-2}$ and 10$^{13}$ cm$^{-2}$. As can be seen in Figure 3.10(a), for a metal work function of 4.6 eV the additional fixed charge density can have a very strong effect on the magnitude of the inversion layer. However, as can be seen in Figure 3.10(b) for a higher metal work function of 5 eV, even without a fixed charge density the inversion already reaches the same magnitude than for a work function of 4.6 and a very high fixed charge density of 10$^{13}$ cm$^{-2}$. Furthermore, any additional fixed charge density only has a relatively smaller effect on the conduction type inversion for a metal work function of 5 eV. This can be understood by the logarithmic dependence of the Fermi level position in the band gap with carrier concentration.

We conclude, that additional (negative) fixed charge density can lead to a stronger conduction type inversion (and hence higher $V_{oc}$), however the difference between the metal and the semiconductor work function has a more pronounced effect.
Explanation of the low open-circuit voltage

The simulations show that high metal work functions (> 5 eV) can lead to strong conduction type inversion in the underlying silicon, the prerequisite for a high $V_{oc}$. Conversely, any decrease of the effective metal WF will lead to a decrease in the $V_{oc}$. When corrected for the small illuminated area of our cells compared to the large substrate, the calculated effective $V_{oc}$ is 560 mV. The WF of high purity Pd is reported to be in the range of 5.2 - 5.6 eV, with the exact value being crystal facet dependent.[128] Given our surface passivation scheme and the high purity of the FZ-silicon wafer, even a slightly lower work function of Pd due to trace amounts of impurities seems insufficient to explain our results (see Figure 3.9).

A cause for the relatively low $V_{oc}$, when compared to state-of-the-art silicon solar cells (>700 mV), can be the lowering of the Pd vacuum work function due to the presence of the dielectric Al$_2$O$_3$.[113] From developments in the field of complementary-metal-oxide-semiconductor (CMOS) transistors, it is known that Fermi level pinning to a charge neutrality level (CNL) in the dielectric can lower the effective work function of the metal.[113–115] As a result, the effective WF of Pd is lowered to the range of 4.6 - 4.9 eV by the dielectric Al$_2$O$_3$, which is well below the reference WF of highly doped p-type silicon (~ 5.2 eV). Therefore, other dielectrics, e.g. SiO$_2$, that cause much weaker Fermi level pinning to the CNL should be employed in future devices. However, when searching for alternatives the stability and passivation properties for ultrathin layers of 1-2 nm have to be kept in mind.

We note that a strong inversion in the underlying silicon is not the only factor to consider for high open-circuit voltages in MIS silicon solar cells. To exclude fabrication induced material degradation as a major cause for the low $V_{oc}$, lifetime measurements after each fabrication step would be highly desirable. Unfortunately, the specific process sequence (e.g. the initial fabrication of the metalized backside) does not allow to track the lifetime with the Sinton lifetime tester. Besides the observed electron beam-induced damage of the a-Si:H (Figure 3.13), other steps known to negatively impact the passivation were avoided.

Furthermore, the selectivity of the contacts will fundamentally determine the degree to which the implied open-circuit voltage ($V_{oc}^{imp}$) can be translated to the measured $V_{oc}$.[19, 90, 129, 130] While it is true that a stronger inversion leads to a higher selectivity, the latter might be limited for conduction type inversion in silicon compared to state-of-the-art diffused junction or SHJ solar cells. However, in the light of the open-circuit voltages obtained in the past for MIS silicon solar cells, which reached values of 655 mV with inferior passivation layers, we expect the main limiting factor for our solar cells to be the ones discussed above.[85, 129]

3.5.6 Optical FDTD simulations

Figure 3.11 show the simulated (FDTD) reflection, transmission and absorption values for a metal nanowire network. The network absorbs on average about 10% of the incident light across the visible wavelength range.
3.5 Supplemental information

Figure 3.11: Simulated reflection, transmission and absorption. Simulated (FDTD) reflection, transmission and absorption values for metal nanowire network with a thickness of 50 nm (10 nm Pd, 40 nm Au), width of 100 nm, pitch of 1 µm.

3.5.7 Tunnel resistance

The resistance of the interfacial layer is non-linear in nature. For low intensities and insulator thicknesses below 1.5 - 2 nm, the $I_{sc}$ is limited by the semiconductor; all charge carriers are extracted and only an increase in intensity can increase the current further. Tunneling resistance is insignificant in that region, as the rate of tunneling is relatively low. For larger insulator thicknesses or higher intensities, the device characteristics shift from a semiconductor-limited to a tunnel-limited regime. [120] Because we observe a linear increase of the $I_{sc}$ and the efficiency throughout the investigated regime the contact resistance is not tunnel-limited.

Figure 3.12: Efficiency and short-circuit current vs incident light intensity. The measurements show that the contact is not tunnel-limited under 1 sun illumination conditions.
3.5.8 Annealing behavior

After the fabrication of our samples we encounter s-shaped I-V curves (Fig. 3.13(b)), which indicate charge carrier extraction barriers at the interface. Electron beam exposure of a-Si:H is known to cause the defects in the material.[119] As shown by others, and confirmed with our performed annealing experiments, those defects can mostly be removed by annealing the a-Si:H at around 220 °C for 30 min. In that temperature range the s-shaped I-V curves disappear and the measured $I_{SC}$ and $V_{OC}$ values after each subsequent annealing step (see Figure 3.13(a) and (d)) improve substantially. We reach a maximum for the $V_{OC}$ in the temperature range between 180 - 230 °C and an annealing time of around 30 min. However, the $I_{SC}$ and with it the $FF$ (not shown) do not reach a maximum but are monotonically increasing for the temperature and time range investigated. We choose to optimize the annealing conditions with respect to the $V_{OC}$ to be able to make conclusions with respect to the extent of the inversion layer. We note that, while the $I_{SC}$ and $FF$ of our solar cells could be better, based on the annealing experiments, we cannot exclude the possibility that the $V_{OC}$-value of our cells is reaching a value that is affected by the electron beam-induced damage in the a-Si:H.

Figure 3.13: Annealing behavior. Influence of post-fabrication annealing steps on the $I_{SC}$, $V_{OC}$ and charge carrier extraction barrier at the interface. The subsequent annealing steps are listed in (c). (a) The measured $I_{SC}$ (blue) and $V_{OC}$ (green) values as a function of the annealing step. As can be seen, the $V_{OC}$ increases before reaching its maximum for an annealing temperature between 180 - 230 °C, and an annealing time of around 30 min. (b) With increasing annealing temperature and time the s-shaped IV curve disappears. (d) The $I_{SC}$ increases monotonically without reaching a maximum in the range investigated.
Quantifying losses and thermodynamic limits in single InP nanowire photovoltaics

Nanowire array solar cells promise record performance by taking advantage of nanophotonic effects. Single nanowire devices facilitate studying these effects, but also render standard definitions of power conversion efficiency and external quantum efficiency meaningless, limiting characterization and understanding. Here we analyze a record InP single nanowire solar cell using intrinsic metrics to place its performance on an absolute thermodynamic scale. Determining these metrics requires novel integrating sphere microscopy, which combines spatially-resolved quantitative absorption, photocurrent, and photoluminescence measurements. We measure a photocurrent collection efficiency of >90% and a record open-circuit voltage (850 mV) that is 73% of the thermodynamic limit (1.16 V). Improving contact selectivity can increase the voltage to 85% of this limit, comparable to record Si and Cu(In,Ga)Se₂ planar solar cells.
Figure 4.1: Characterization of a record single nanowire solar cell. (a) False-color SEM image of the InP nanowire device (yellow) with hole contact (red) and electron contact (blue). (b) The nanowire I-V curve in the dark (blue) and under the solar simulator at 1 sun intensity (red). The solid line is a smoothed fit to the data points (shown as small crosses). (c) A schematic depicting the integrating sphere microscopy setup. A microscope objective focuses light from a monochromated supercontinuum laser source on the nanowire solar cell inside the integrating sphere. The sphere collects transmitted as well as scattered light via a photodetector behind a baffle, while the objective directs the reflected light to another photodetector (not shown). Subtracting these calibrated signals from the input gives the local absorbance (fraction of incident light that is absorbed) with diffraction limited resolution. Photocurrent is measured simultaneously to determine the internal quantum efficiency (IQE). With a long-pass filter in front of the detector, photoluminescence can be collected quantitatively to give the photoluminescence quantum yield (PLQY). The sample is mounted on a piezoelectric stage, enabling spatial mapping of all these output parameters.

4.1 Introduction

Nanophotonic engineering holds great promise for photovoltaics: the record conversion efficiencies of nanowire solar cells are increasing rapidly, and the record open-circuit voltage has already surpassed the record planar equivalent.[14, 23] Furthermore, several authors have suggested that nanophotonic effects could help photovoltaics surpass the fundamental efficiency limits of planar solar cells.[131, 132] These effects are particularly pronounced in single nanowire devices, where two out of the three dimensions are subwavelength. They therefore provide an ideal platform to study how nanophotonics affects photovoltaics.[46, 49, 132–137]
However, in isolated nanophotonic systems the standard definition of power conversion efficiency no longer applies, because the device can absorb light from an area much larger than its own size. Additionally, while a thermodynamic bound on the photovoltage still exists, it is \textit{a priori} unknown and may be very different from that of a planar solar cell. This complicates characterization of such nanoscale devices: it is unclear how well they perform with respect to fundamental limits and to other devices, how much can be gained through optimization, and whether the efficiency limits of planar devices can be surpassed by understanding and applying nanophotonics to photovoltaics.

Here, we analyze a record InP single nanowire solar cell using intrinsic metrics to place its performance on an absolute thermodynamic scale. Determining these metrics requires novel integrating sphere microscopy, which combines spatially resolved quantitative absorption, photocurrent, and photoluminescence measurements. We measure a photocurrent collection efficiency of >90% and a record open-circuit voltage (850 mV) that is 73% of the thermodynamic limit (1.16 V).

\section*{4.2 Results and discussion}

In order to understand the fundamental limits and losses in nanophotonic solar cells and place their performance on an absolute thermodynamic scale, we study a record single nanowire solar cell. The device consists of a 310 nm diameter wurtzite InP nanowire with a 50 nm SiO$_2$ coating (Fig. 4.1(a)). It has a short-circuit current of $I_{sc} = 450$ pA, an open-circuit voltage of $V_{oc} = 850$ mV, and a fill factor of $FF = 0.76$ under AM1.5 solar spectrum illumination (Fig. 4.1(b)), all of which are excellent compared to previous nanowire devices. Using a novel characterization method, integrating sphere microscopy, we determine the spatially resolved absorptance (fraction of incident light absorbed), internal quantum efficiency (IQE, fraction of absorptance converted to current), and photoluminescence quantum yield (PLQY, fraction of absorptance converted to external photoluminescence) for the first time. Absorptance, IQE and PLQY directly quantify the three fundamental processes in solar energy conversion - charge carrier generation, collection and recombination, respectively - and therefore provide intrinsic performance metrics. We use these quantities to determine the fundamental thermodynamic limits, benchmark the performance against state-of-the-art technology, and pinpoint the remaining loss mechanisms. Although we focus on nanowire photovoltaics, these intrinsic metrics contain valuable information for any other nanophotonic optoelectronic device, and in particular nanoscale light-emitting diodes.

We begin our analysis of the nanowire solar cell by determining the absorptance and IQE. To date the primary experimental challenge in determining intrinsic performance metrics for single nanowire devices has been measuring quantitative absorption during solar cell operation, which is not possible with existing techniques. These methods assume that absorbed power is converted into heat (photothermal
4 Quantifying losses and thermodynamic limits in single InP nanowire photovoltaics

Figure 4.2: Internal quantum efficiency of a single nanowire photovoltaic. (a) False color scanning electron microscopy (SEM) image of the single nanowire device (InP nanowire diameter = 310 nm, length = 12.1 μm, SiO₂ shell thickness = 50 nm). The p-i-n doped InP nanowire device is visible in the center with an electron contact (blue) and hole contact (red). (b) and (c) Absorptance and internal quantum efficiency (IQE) as a function of position for the nanowire device. (d) The IQE as a function of position along the nanowire length, convoluted with the focused spot size (beam radius 730 nm). The color shading shows the nanowire doping profile as intended during nanowire growth. The SEM image on top has an electron beam-induced current (EBIC) measurement (blue shade) in good agreement with the IQE profile. (e) The peak IQE as a function of wavelength, which lies between 90% and 100% up to wavelengths close to the band gap, where the anisotropic nature of wurtzite InP becomes apparent. The shading displays the measurement uncertainty, which arises largely due to noise in the photodetectors.
4.2 Results and discussion

Figure 4.3: Photoluminescence quantum yield, power dependence, and recombination mechanism. (a) The photoluminescence quantum yield (PLQY) as a function of position, indicating that it peaks where IQE is highest (measured at 1400 suns to increase the signal to noise ratio). (b) To determine the PLQY at 1 sun intensity we measured it for a range of intensities lower than in panel (a). The PLQY clearly shows linear behavior with intensity, which indicates that Shockley-Read-Hall recombination dominates. The inset shows the nanowire photoluminescence (PL) spectrum at the brightest position in panel (a), also at 1400 suns. All PLQY measurements were performed with 600 nm excitation light parallel to the nanowire axis.

With integrating sphere microscopy we can probe not only the IQE to understand the current collection efficiency, but also directly measure the PLQY. In absence of non-radiative recombination, PLQY=1 and the open-circuit voltage reaches the thermodynamic limit $V_{oc}^{rad}$. For a PLQY below 1, the $V_{oc}$ is reduced from the radiative limit to the implied $V_{oc}^{imp} = V_{oc}^{rad} - V_T \ln(PLQY)$, where $V_T$ is the thermal voltage (25.9 mV). [150–152] Hence, the PLQY plays a crucial role in

an excitation wavelength of 600 nm. The IQE reaches a peak value of 100% and is strongly localized to the upper half of the wire, as is more clearly visible in the line profile of the IQE along the nanowire in Fig. 4.2(d). The color shading in Fig. 4.2(d) shows the intended doping profile during growth. It should be noted that the p-type dopant zinc might have diffused further into the nanowire during growth as it is very mobile in InP at high concentrations.[148] Carrier collection is most efficient near the n-type/intrinsic interface, and collection occurs over a length of 3.4 microns. In the p-type region the IQE is essentially zero, indicating short electron diffusion lengths. This is confirmed by an electron beam-induced current (EBIC) measurement shown above the IQE line profile, from which we determine the electron diffusion length in the intrinsic/p-type segment to be 285 nm (see Section 4.3.5). The IQE is nearly independent of polarization and wavelength, with values >90% over the whole wavelength range up to the band gap (Fig. 4.2(e)). The small difference in band gap depending on excitation polarization is caused by the anisotropic nature of wurtzite InP and has previously been observed with photoluminescence excitation spectroscopy.[149]
understanding the photovoltage. To measure the PLQY, we place a filter in front of the integrating sphere photodetector, such that only photoluminescence is detected (see Section 4.3.7). Our spatially-resolved measurements show that the nanowire PLQY peaks in the same region where the IQE is highest (Fig. 4.3(a)), with an average PLQY over the active area of 0.9% at an excitation intensity of 1 \( \mu \text{W} \) 600 nm light (\( \sim 10^3 \) suns). To determine the average PLQY at 1 sun intensity, we measure at a range of lower excitation powers (Fig. 4.3(b)). The PLQY decreases linearly with excitation intensity, indicating that in this regime Shockley-Read-Hall recombination dominates (see Section 4.3.7). Assuming linearity down to 1 sun intensity, the average PLQY is \( 4 \times 10^{-4} \) (0.040%). This value corresponds to a \( V_{oc} \)-loss of 210 mV from the thermodynamic limit, and is comparable to what is observed in world record planar crystalline Si, Cu(In,Ga)Se\(_2\), and InP solar cells.[151]

The PLQY can provide the \( V_{oc} \)-loss from the thermodynamic bound \( V_{oc}^{rad} \), but in order to calculate the latter value for our device we must know the recombination current corresponding to radiative thermal emission, \( I_{0}^{rad} \). This emission current together with the \( I_{sc} \) determines \( V_{oc}^{rad} = V_T \ln(I_{sc}/I_{0}^{rad}) \).[150] In a macroscopic solar cell, the \( I_{sc} \) and \( I_{0}^{rad} \) can be calculated by integrating the external quantum efficiency (EQE, fraction of incident photons converted to current) over the solar and blackbody spectra, respectively.[151] However, for single nanowire solar cells the standard definition of EQE is not valid, because the absorption cross section \( (\sigma_{abs}) \) can be much larger than the device area. To solve this important issue, we define a new quantity called the collection cross section that takes on the same role:

\[
\sigma_{EQE}(\lambda, \Omega) = \int IQE(\lambda, z) \sigma_{abs}^{1D}(\lambda, \Omega) dz
\]

(4.1)

where \( IQE(\lambda, z) \) is the spatially resolved internal quantum efficiency (shown in Fig. 4.2(e)) and \( \sigma_{abs}^{1D}(\lambda, \Omega) \) is the effective absorption width of the nanowire (determined from the absorptance, see Section 4.3.10). Fig. 4.4(a) shows \( \sigma_{EQE} \) for the nanowire device studied here, in both polarizations. Note that \( \sigma_{EQE} \) requires units of area, while the conventional EQE is a unitless quantum efficiency. This is a crucial difference, because for macroscopic solar cells the area collecting photons is independent of the incident wavelength and simply equal to the geometric area. In contrast, for nanostructures the interaction area with the incident light can be strongly wavelength dependent, e.g. due to resonances.[153] Additionally, in contrast to the IQE and PLQY, \( \sigma_{EQE} \) can be determined directly from the photocurrent measurement, incident flux, and laser spot size (Section 4.3.10).

Integrating \( \sigma_{EQE} \) over the black body spectrum and all angles we find, which leads to a maximum open-circuit voltage for our nanowire device (see Section 4.3.11). The difference between the ideal voltage (\( V_{oc}^{rad} \)) and the measured \( V_{oc} \) (850 mV) is 310 mV: the \( V_{oc} \) is 73% of the thermodynamic limit. The measured \( V_{oc} \) is 100 mV smaller than the implied open-circuit voltage \( V_{oc}^{imp} \) in the semiconductor nanowire, suggesting that the contact selectivity plays a significant role in the \( V_{oc} \)-loss. The \( V_{oc}^{rad} \) for this device is significantly higher than the Shockley-Queisser \( V_{oc} \) for a planar cell with an absorption onset at 890 nm (like our nanowire device,
4.2 Results and discussion

Figure 4.4: Measuring thermodynamic limits and quantifying loss mechanisms in single nanowire solar cells. (a) The collection cross section $\sigma_{\text{EQE}}$ is the nanophotonic equivalent to the standard external quantum efficiency (EQE) for a macroscopic solar cell, but takes into account the effective area over which photons are absorbed. This area is determined by multiplying the absorption width $\sigma_{\text{abs}}^\text{LD}$ (see Section 4.3.10) by the internal quantum efficiency (IQE) integrated over the nanowire length (see Fig. 4.2(d)). The shading displays the uncertainty, which is largely due to determination of the focused beam waist. (b) Based on $\sigma_{\text{EQE}}$ we estimate the different contributions to the open-circuit voltage. The thermodynamic limit is $V_{\text{oc}}^{\text{rad}} = 1.16 \text{ V}$, which is reduced by 210 mV due to the PLQY (non-radiative recombination in the semiconductor) to $V_{\text{oc}}^{\text{imp}} = 950 \text{ mV}$, and further reduced by 100 mV due to losses at the contacts, to a final $V_{\text{oc}} = 850 \text{ mV}$.

see Fig. 4.4(a)), which is 1.13 V.[154] The difference arises due to suppressed absorption near the band gap, which thus leads to reduced emission and a lower radiative recombination current.[155] It is important to note that such a voltage enhancement due to suppressed absorption necessarily comes at a cost in current, and can therefore not lead to efficiencies above the Shockley-Queisser limit in macroscopic devices.

Integrating the EQE over the AM1.5 solar spectrum is a common procedure used in macroscopic solar cells to verify the $I_{\text{sc}}$ from solar simulator measurements. Here we find that an analogous procedure using $\sigma_{\text{EQE}}$ instead of EQE gives a calculated short-circuit current of 320 pA, which is 29% lower than the value measured under the solar simulator (450 pA). We attribute the difference to light trapping in the glass substrate, which leads to an overestimation of the actual photocurrent of nanowire photovoltaic devices when measured on glass substrates with a solar simulator. This is supported by the fact that covering almost the entire sample, including the nanowire, with opaque foil still results in a short-circuit current of $\approx$100 pA (22% of total, see Section 4.3.3). This suggests that just as with macroscopic solar cells, $I_{\text{sc}}$ measurements under the solar simulator require proper masking to avoid artifacts. We therefore used the $I_{\text{sc}}$ value based on $\sigma_{\text{EQE}}$ for the calculation of $V_{\text{oc}}^{\text{rad}}$ (see Section 4.3.11).

In conclusion, the detailed integrating sphere microscopy measurements and analysis allow us to place single nanowire solar cell performance on an absolute
thermodynamic scale, pinpoint loss mechanisms, and direct our efforts to make future nanowire solar cells that can beat record planar cell efficiencies. In terms of photocarrier collection, these nanowires are already close to the limit, reaching IQE values >90% in both polarizations for a 3.4 micron segment of the nanowire. In a vertical nanowire geometry, with the n-type segment facing the sun, this is enough to absorb all incident light and collect the generated carriers. Regarding the photovoltage, we determined three different values for the $V_{oc}$ that can help us pinpoint remaining loss mechanisms (Fig. 4.4(b)): (1) the thermodynamic limit calculated from wavelength-dependent $\sigma_{EQE}$ measurements (1.16 V), which only includes radiative recombination; (2) the material limit extracted from local PLQY measurements (950 mV), that includes non-radiative recombination in the nanowire; and (3) the device limit extracted from solar cell operation (850 mV), that also includes losses at the contacts. The 210 mV (18%) loss related to non-radiative recombination in the nanowire could be reduced by lowering the surface recombination velocity (surface passivation) or material defect density (purification).

Improvements in contact selectivity alone could lead to a 100 mV (12%) increase in the $V_{oc}$ compared to our record single nanowire results. Combining both makes $>1V$ for InP nanowire solar cells far above world record planar InP solar cell performance certainly within reach.
4.3 Supplemental information

4.3.1 Sample fabrication

Nanowires are grown in a low-pressure Aixtron 200/4 Metal-Organic Vapor Phase Epitaxy (MOVPE) reactor, with the Selective Area MOVPE growth method. A 50 nm thick silicon nitride layer is used as Selective Area growth mask, patterned by the Soft Contact Nanoimprint Lithography technique on a (111)A oriented p-doped InP substrate (Zn doping carrier concentration $2 \times 10^{18}$ cm$^{-3}$ from AXT, USA). Hydrogen ($H_2$) is used as a carrier gas for precursors, with a total flow of 15 L/min. Growth is performed at 730 °C with a pressure of 100 mbar, using trimethylindium (TMI) and phosphine (PH$_3$) as precursors with molar fractions $x_i (\text{TMI}) = 4.7 \times 10^{-5}$ and $x_i (\text{PH}_3) = 3.9 \times 10^{-3}$, resulting in a V/III ratio of 83. The total growth time is 11 minutes with a doping profile $p^{++} / p / i / n / n^{--}$, with respective segment growth times of 0.5 min / 3 min / 4 min / 3 min / 0.5 min (1 µm / 3 µm / 4 µm / 3 µm / 1 µm). We use diethylzinc (DEZn) as p-dopant, with molar fractions $1.3 \times 10^{-5}$ in the $p^{++}$ region and $6.4 \times 10^{-6}$ in the $p$ region. Ditertbutylsilane (DTBSi) is used as n-dopant, with molar fractions $9.5 \times 10^{-6}$ for n$^{--}$ and n regions, respectively. After the growth, the wires were coated with a conformal 50 nm thick SiO$_2$ shell by plasma enhanced chemical vapor deposition, performed with silane and nitrous oxide as precursors at 300 °C. The nanowire measured in this Chapter had a total diameter of 410 nm (310 nm diameter InP), a length of 12 µm (9.8 µm between the contacts) and SiO$_2$ shell thickness of 50 nm.

4.3.2 Macroscopic electrode pads and contacting

Au electrodes with alignment markers were fabricated on plasma cleaned glass substrates by UV lithography and metal evaporation (see Fig. 4.5). The nanowires are transferred from the arrays (~200x200 µm$^2$) via a pipette in ethanol and are randomly dropcast on the substrates. Electron beam lithography and metal evaporation are used to contact the single nanowires to the Au electrodes. It was found that the exact placement of the contact position on the highly doped end-segments of the nanowires is a crucial step to allow good Ohmic contact and prevent extraction barriers. Then, the glass substrates are wire-bonded to glass holders, which have prefabricated metal contact lines (also by UV lithography and metal evaporation). The bottom of the glass holder is connected to a printed-circuit-board socket which also connects to a flat electrical cable extending outside of the integrating sphere (see Fig. 4.1(c)). The metals used to contact the single nanowires were Ti (200 nm) and Au (30 nm) for the electron contact (on the n$^{--}$ doped part) and Cr (~3 nm), Zn (15 nm), Au (215 nm) for the hole contact (on the p$^{++}$-doped part). Before the metal was evaporated, the exposed and developed substrates were etched in buffered HF (1:7, HF (49%): NH$_4$F (40%)) for 10 s to remove the protective SiO$_2$ shell (~50 nm) and the native oxide of the InP under the contact. The latter is known to cause Fermi level pinning under the conduction band, which easily creates ex-
traction barriers for the hole-contact.[158] The etched samples were transferred right away into the evaporation chamber to minimize the regrowth of the native oxide as much as possible. It is common to use an additional annealing step at high temperatures to diffuse Zn into the p-type InP nanowire and create a highly p-doped layer.[137] We found this treatment to be damaging to our nanowires (strong decrease in photoluminescence efficiency) and therefore omitted this step, as the in situ doping of our nanowires allowed the formation of Ohmic contacts even without annealing. Nevertheless, we chose to evaporate Zn for the hole contact to prevent diffusion of Zn from the nanowire into the contact metal at elevated temperatures during the evaporation and lift-off steps. For the electron contact, Ti and Au were evaporated with an electron beam evaporator at a pressure of \((5 - 10) \times 10^{-7}\) mbar at an evaporation rate of 0.3-2 Å/s and acceleration voltage of 10 keV. For the hole contact Cr, Zn and Au were evaporated with a thermal evaporator at \(\sim 2 \times 10^{-6}\) mbar at a rate of 0.2-1.5 Å/s.

4.3.3 Solar simulator measurements and influence of masking

The I-V trace of the nanowire device is measured with a solar simulator (Oriel SOL2 94062A (6X6) Class ABA, Newport) with the AM1.5G spectrum at 1 sun (100 mW/cm²) illumination intensity at a temperature of ~50 °C. The lamp intensity of the solar simulator is adjusted with a silicon reference cell. Electrical probes are used to contact the contact pads on the glass substrate with a source-measure unit (Agilent B2910). The voltage is scanned with a positive and negative scan rate between -1V and 1V in 2001 steps while the current is being measured.
Masking of glass substrates

Fig. 4.6(a) shows a top-down view on the electrode glass substrate under the solar simulator. The connected nanowire (red, not to scale) is placed in the center and black, fully opaque foil covers a large part of the substrate. Even though the nanowire is fully covered the solar simulator measurement results in a short-circuit current of $I_{sc} \sim 100 \text{ pA}$ ($\pm 5 \text{ pA}$). We note, that this amounts approximately to the difference between the short-circuit current determined with the solar simulator (450 pA) and the one determined with the integrating sphere setup (320 pA).

Fig. 4.6(b) shows as a schematic the side view on the setup configuration. The light is scattered into the glass substrate at the glass and Au electrode edges and trapped inside the thin glass slab. As a result the nanowire is not only illuminated from the top, but also partly from the bottom, and hence results in an inaccurate measurement. Given the common usage of glass substrates for single optoelectronic nanoscale device measurements, we stress the importance of using appropriate setups or masking conditions to avoid measurement errors. The 28% higher intensity in the solar simulator measurement may lead to an overestimation of the $V_{oc}$ under 1 sun of up to 8 mV. However, given that the $V_{oc}$ seems limited by contact selectivity, it is not clear by how much exactly it would decrease.

Figure 4.6: Schematic of masking conditions under solar simulator. (a) Schematic of top-down view on electrode glass substrate under solar simulator. The connected nanowire (red, not to scale) is placed in the center and black opaque foil covers a large part of the substrate. Even though the nanowire is fully covered the solar simulator measurement results in a short-circuit current of $I_{sc} = 100 \text{ pA}$. (b) Schematic of side view, showing the solar simulator and the glass substrate with the single nanowire device. The light is scattered into the glass substrate at the glass and Au electrode edges and trapped inside the thin glass slab. As a result the nanowire is not only illuminated from the top, but also partly from the bottom, which results in inaccurate measurements.
4.3.4 Nanowire device statistics

Table 4.1 shows the statistics of four different nanowire batches, that were grown with a different pitch \( (p) \) and doping profile \( (d) \). Due to the small number of measured devices the statistical interpretation becomes limited for batch \( p2 - d1 \). However, it can clearly be seen that not only the maximum \( V_{oc} = 850 \text{ mV} \) and \( I_{sc} = 609 \text{ pA} \), but also the highest means can be found in that batch. The second and third highest \( V_{oc} \)'s in that batch were 820 mV and 800 mV, respectively. Even though the doping profile of batch \( p2 - d1 \) (described above) was the same as for batch \( p1 - d1 \) the results show a clear difference in performance. To understand the influence of a different nanowire pitch (density) on the growth conditions, more studies are needed. The low yield of batch \( p2 - d1 \) can be mainly ascribed to the lower density of nanowires. However, during the contacting process several additional steps are potentially lowering the yield of the devices. Transferring the wires from the array can lead to cleavage of the wires from the substrate in a detrimental way. If the wire breaks not at the bottom, directly above the substrate, the broken end-facet does not correspond to the highly p-type doped part of the wire, that easily facilitates Ohmic contacts. Furthermore, prior to the contacting the orientation of the nanowire doping profile is not known. And finally, even a slight misalignment during the electron beam lithography will lead to metal contacts that are placed onto the lower doped regions of the wire (or are missing the nanowire altogether). In all those cases, the placement of the contacts on a region with a wrong doping type and density will lead to a strong extraction barrier in the final devices. In summary, great care has to be taken to yield any meaningful number of single nanowire devices, even for arrays with a large density of wires, while low densities almost certainly translate into low numbers of single nanowire devices.

<table>
<thead>
<tr>
<th>Batch</th>
<th>( I_{sc} )</th>
<th>( \sigma_{I_{sc}} )</th>
<th>( I_{sc}^{\max} )</th>
<th>( V_{oc} )</th>
<th>( \sigma_{V_{oc}} )</th>
<th>( V_{oc}^{\max} )</th>
<th>( # )</th>
</tr>
</thead>
<tbody>
<tr>
<td>( p1 - d1 )</td>
<td>54</td>
<td>22</td>
<td>90</td>
<td>228</td>
<td>117</td>
<td>512</td>
<td>18</td>
</tr>
<tr>
<td>( p1 - d2 )</td>
<td>61</td>
<td>20</td>
<td>93</td>
<td>285</td>
<td>49</td>
<td>350</td>
<td>8</td>
</tr>
<tr>
<td>( p1 - d3 )</td>
<td>210</td>
<td>83</td>
<td>398</td>
<td>329</td>
<td>146</td>
<td>640</td>
<td>22</td>
</tr>
<tr>
<td>( p2 - d1 )</td>
<td>321</td>
<td>175</td>
<td>609</td>
<td>696</td>
<td>105</td>
<td>850</td>
<td>12</td>
</tr>
</tbody>
</table>

**Table 4.1: Nanowire device statistics.** Statistics of single nanowire devices from different growth batches \( (I_{sc} \text{ in pA and } V_{oc} \text{ in mV}) \). The nanowires were grown under different growth conditions \( (\text{array pitch } (p) \text{ and doping profile } (d)) \). The device shown in this chapter comes from batch \( p2 - d1 \). While the statistical interpretation of the results is limited due to the small number of total devices for that batch (low density of nanowires), not only the maximum open-circuit voltages and short-circuit currents but also the highest means can be found in that batch. The second and third highest open-circuit voltages from that batch were 800 mV and 760 mV, respectively.
4.3 Supplemental information

4.3.5 Electron beam-induced current

The electron beam-induced current (EBIC) measurements are conducted with a beam current of 100 pA and 5 kV acceleration voltage. The integration time per pixel is 10 μs. The position of the electron beam is synchronized with the read-out of the current signal which allows the superposition of the extracted current signal with the SEM image. From the profile of the EBIC intensity along the length of the nanowire we extract an electron diffusion length of in the p-doped part of the wire (Fig. 4.7). As can be clearly seen, only the part next to the electron contact (at 0.5 - 4 μm) is active. By fitting an exponential decay curve to the tail between 4 - 6 μm, a diffusion length of the p-doped part of the wire can be extracted.

![Figure 4.7: EBIC profile. Electron beam-induced current (EBIC) profile along the length of the wire, oriented as shown in Fig. 4.2(d).](image)

4.3.6 Integrating sphere microscopy

We use a supercontinuum laser (Fianium WL-SC-400-4), sent through an acousto-optical tunable filter (AOTF; Crystal Technologies, ~5 nm bandwidth). The long working distance objective required for illuminating the nanowires is a Mitutoyo M Apo Plan NIR 50x NA 0.42 objective with a 17 mm working distance. The integrating sphere is a custom modification to a GPS-020-SL integrating sphere built by LabSphere, modified to accommodate the objective lens. We use low-noise Newport 818-UV calibrated photodiodes, each connected to Stanford Research Systems SR830 lock-in amplifiers. The transmission of the acousto-optic tunable filter was digitally modulated with a 50 percent duty cycle as a source for the lock-in amplifiers. The sample was mounted on a 3D piezoelectric stage (Piezojena Tritor400), which itself was mounted on a Newport mechanical stage for rough alignment. The incident intensity was controlled with ND filters (Thorlabs) and the AOTF RF power. The integrating sphere microscopy setup is shown schematically in Fig. 4.8.
4 Quantifying losses and thermodynamic limits in single InP nanowire photovoltaics

Figure 4.8: Optical setup. A supercontinuum laser (Fianium) is fiber coupled into an acousto-optical tunable filter, which has a visible output for wavelengths 400-750 nm and a near IR output for wavelengths 700-1100 nm. We use polarizing beam splitters to ensure proper polarization, after which the light is sent through a 50:50 beam splitter to a beam monitor photodetector to measure incident power and towards the integrating sphere. The light going towards the integrating sphere passes through a half-wave plate to control the polarization. The objective focuses the light on the sample inside the integrating sphere, and collects reflected light that goes towards the reflection photodetector. Light inside the integrating sphere is monitored by the integrating sphere photodetector. The sample is moved by a 3D piezo stage (Piezojena Tritor400). The incident intensity was controlled with neutral-density (ND) filters (Thorlabs, not shown in the schematic) and the AOTF RF power.

The general measurement procedure for an absorption measurement is to prepare a sample on a glass substrate (it is crucial that the substrate is non-absorbing). The integrating sphere is positioned on a stage allowing it to be moved up and lowered to accommodate sample loading. The sample itself is positioned on a piezo stage directly underneath the integrating sphere, which in turn is positioned on a mechanical stage. The sample is inserted through a narrow slit in the bottom of the sphere, to minimize exposed open aperture area in the integrating sphere. The photodetector is positioned behind a baffle to prevent direct illumination of the detector, as can be seen in Fig. 4.1(c). The absorptance of a nanostructure is then determined using the simple formula:

$$A = 1 - \frac{R_s}{R_r} - \frac{I S_s}{I S_r} - 0.04$$  \hspace{1cm} (4.2)

where $A$ is the absorptance, $R_s$ and $I S_s$ are the measured reflection and integrating sphere signals respectively on the sample, and $R_r$ and $I S_r$ are reference measurements to account for detection sensitivity. For the reflection monitor this is done by placing a mirror (Thorlabs PF10-03-P01) in the focal plane of the objective, while for the integrating sphere reference measurement the focused beam is a miss of the sample.

Because the samples are on regular microscopy glass slides the reflection from the second interface goes back into the objective, but due to the second interface being out of focus it is not collimated and hence is not detected. As a result 4%
is missing from the power balance, which is accounted for in Eq. 4.2. We have implicitly assumed here that this reflection loss is constant, but in reality it slightly decreases or increases with the amount of forward scattered and transmitted light. Hence, it is a small source of error. For example, if 20% of the incident beam is absorbed by a non-scattering particle, this will lead to a reduction of this reflection loss to 3.2%. Thus, by subtracting a constant offset, a small error in the absorptance is introduced.

**Figure 4.9: Scattering of silica nanosphere.** (a) SEM image of a silica nanosphere with a diameter of 460 nm. (b, c) Reflection and integrating sphere signal of the same nanosphere at 600 nm wavelength. (d) Maps in (b) and (c) combined to give the absorptance map, showing that only a small fraction of the scattered power is not detected. The scale bar in (a)-(d) is 1 micrometer. (e) The extinction cross section of the nanosphere (blue dots) together with the Mie theory cross section (blue line). Red dots show the measured detection losses, indicating that 95.2 ± 1.2 % of the scattered light is detected. Errors are due to variance in the measurement and uncertainty in the cross section conversion.

To verify that with integrating sphere microscopy we can indeed measure absorptance accurately, we measured the "absorptance" on silica (SiO₂) nanobeads (Fig. 4.9). Although they do not absorb, they scatter strongly, providing us with a means to determine the collection efficiency of scattered light. Fig. 4.9(a) shows an
SEM image of the silica nanosphere with a diameter of 460 nm and reflection and integrating sphere detector maps of the same nanosphere at 600 nm wavelength. (Fig. 4.9(b) and 4.9(c)) The 2% decrease in reflection is matched by an analogous increase in the integrating sphere signal, but as shown in Fig. 4.9(d) a small difference remains when reflection and integrating sphere signals are combined. The maximum of this detection loss is shown as an effective detection loss cross section for a range of wavelengths in Fig. 4.9(e). This figure also shows the scattering cross section measured on the same nanosphere (blue points, see methods) and the theoretical cross section from Mie theory for a 460 nm silica sphere in vacuum (blue line).

![Figure 4.10: Absorption cross section.](image)

(a) The absorption cross section of a zincblende InP nanowire (300 nm diameter with 50 nm SiO₂ shell) as a function of wavelength for both polarizations of light calculated with FDTD (Lumerical), compared to the converted absorption cross section from a Gaussian beam simulation (also FDTD) using Eq. 4.8. in Section 4.3.10. There is about a 5% difference between the two. (b) The experimental spot size as determined with a knife-edge measurement. (c) The wurtzite InP nanowire absorption cross section converted from the absorptance measurement using Eq. 4.8. The magnitude of the absorption cross section shows good quantitative agreement with the simulated absorption cross section for zincblende InP, but since the crystal structure is different a direct comparison is not possible. Additionally, the absorption cross section does not appear to vanish near the band gap, which is most likely due to parasitic absorption from scattered light: as absorption in nanowires decreases, scattering increases strongly.
The extinction measurements on the silica beads were performed in the typical extinction measurement setup, with a Nikon T Plan EPI SLWD 50X 0.4 NA objective as the collection objective. The extinction cross section is then retrieved using $\Delta T / T = C_{\text{ext}} / \pi w_0^2$, where $T$ is the transmitted power and $w_0$ is the beam waist. Based on the ratio of detection loss to extinction for the nanosphere we estimate that $95\pm1.2\%$ of the scattered power is collected.

Although the assumption is made that the wire is infinitely thin, agreement between this approximation and full-wave simulations is good: Fig. 4.10(a) shows a direct comparison between the absorption cross section of a zincblende InP nanowire (300 nm diameter, 50 nm SiO$_2$ shell) from a plane wave simulation and a Gaussian beam simulation using Eq. 4.8, performed with Lumerical FDTD. The Gaussian beam underestimates the real absorption cross section by about 5%. However, experimentally we did not observe a dependence of the absorption cross section on the spot size, which we checked by underfilling our objective until the spot size was increased by 60%.

The experimental spot size as determined with knife-edge measurements on the gold contact pads is shown in Fig. 4.10(b), where the error bars depict the Gaussian fitting confidence interval (66% confidence). This spot size can be used to convert the absorptance measurements on the InP nanowire to an absorption cross section, as shown in Fig. 4.10(c). Although a direct comparison with theory is not possible, because the refractive index of wurtzite InP is not known, the magnitude of the absorption cross section is in quantitative agreement with the cross section for the zincblende InP nanowire in Fig. 4.10(a). The absorption cross section does not appear to vanish near the band gap, which is most likely due to parasitic absorption from scattered light: as absorption in nanowires decreases, scattering increases strongly. This may also explain why the IQE decreases near the band gap. For measurements on the nanowire solar cell we use very low powers ($\ll 1$ nW) to achieve intensities close to 1 sun. We therefore swapped the photodetectors for integrating sphere and reflection measurements from the PDA100A detectors to the Newport 818 series, which have a much lower noise-equivalent power. The nanowire solar cell is connected to an SR830 lock-in amplifier as well, and incident power is modulated with 195 Hz, below the cut-off frequency of the nanowire device. Calibration of the incident power is done by placing one of the calibrated Newport 818-UV photodiodes in front of the objective.

### 4.3.7 Photoluminescence measurements

An integrating sphere is also commonly used to measure photoluminescence quantum yield (PLQY) quantitatively, either by connecting a spectrometer to the integrating sphere or by using a combination of long- and shortpass filters. To measure the PLQY on the nanowire we use a longpass filter in front of the integrating sphere detector (Thorlabs FELH0750). The PLQY at low intensities is not high enough to require a shortpass filter for accurate absorption measurement. The photoluminescence collection efficiency of the integrating sphere was
determined by sending monochromatic light over the wavelength range of photoluminescence into the integrating sphere, but missing the sample. The total photoluminescence detection efficiency \( \eta_{PL} \) (Coulombs/emitted photon) can then be calculated using:

\[
\eta_{PL} = \frac{\int S(\lambda) \eta(\lambda) d\lambda}{\int S(\lambda) d\lambda}
\]  

(4.3)

Here \( S(\lambda) \) is the PL spectrum (shown in the inset in Fig. 4.3(b)), and \( \eta \) is the wavelength dependent collection efficiency of the integrating sphere (also in Coulombs/photon). The PLQY is then calculated as the number of emitted photons divided by the number of absorbed photons.

The error bars shown in the figures indicate the standard deviation, which largely arises due to noise in the photodetector measurements that is insensitive to incident laser power. For the cross sections in Fig. 4.4(a) the error bar is actually dominated by the fitting of the spot size measurement, which can be improved.

### 4.3.8 Wavelengths independent PLQY

In the main text in Fig. 4.3 we have determined the photoluminescence quantum yield (PLQY) with an excitation wavelength of 600 nm. Here we verify that the PLQY is wavelength independent, which is expected for semiconductors in the linear regime (where one photon creates one electron-hole pair). The result of the excitation spectroscopy is shown in Fig. 4.11, where the PLQY is shown for a range of excitation wavelengths. While the luminescence rate will depend on wavelength due to variation in the absorption cross section, this dependence is removed by correcting for the absorptance and calculating the PLQY. The generation rate is almost 6 times higher than the highest rate shown in Fig. 4.3 and as a result the PLQY is also higher.
4.3 Supplemental information

4.3.9 Slope of the PLQY

In Fig. 4.3(b) we show the slope of the PLQY versus the generation rate, which has a linear slope. This slope can be explained by examining the ABC model for the semiconductor carrier density:

\[ G = AN + p_{\text{esc}}BN^2 + CN^3 \]  

(4.4)

Here \( N \) is the carrier density (assuming that holes and electrons have the same density, such that we are in the high injection regime), \( G \) is the generation rate of carriers, \( A \) is Shockley-Read-Hall coefficient, \( B \) is the radiative recombination coefficient, and \( C \) is the Auger coefficient. \( p_{\text{esc}} \) is the probability that a photon from a radiative recombination event actually escapes the semiconductor structure and is emitted, instead of reabsorbed. The PLQY can then be written as:

\[ \text{PLQY} = \frac{p_{\text{esc}}BN^2}{AN + p_{\text{esc}}BN^2 + CN^3} \]  

(4.5)

If Shockley-Read-Hall recombination dominates the rate equation simplifies to \( G = AN \), indicating that the carrier density now increases linearly with the generation rate. Inserting this into the expression of the PLQY, we find that:

\[ \text{PLQY} \approx \frac{p_{\text{esc}}BN^2}{AN} = p_{\text{esc}}B \frac{N}{A} \]  

(4.6)

Hence the slope of the PLQY is linear with the generation rate.

4.3.10 Determining the collection cross section

For a horizontal single nanowire device we can simplify Eq. 4.1 due to the symmetry along the nanowire length. As a result of this symmetry, the absorption cross section (which is an area, 2D) is typically expressed in absorption cross section per unit length of the nanowire, such that an effective absorption width (1D) is obtained. The total absorption cross section is then effectively obtained by multiplying by the length of the wire. Since we are interested in the collection cross section, the relevant length of the wire is given by the active length shown in Fig. 4.2(d), which leads to the integral in Eq. 4.1:

\[ \sigma_{\text{EQE}}(\lambda, \Omega) = \int \text{IQE}(\lambda, z)\sigma_{\text{abs}}^{1D}(\lambda, \Omega)dz \]  

(4.7)

where \( \sigma_{\text{abs}}^{1D} \) is the absorption width of the nanowire (indicated by the superscript 1D). The effective absorption width \( \sigma_{\text{abs}}^{1D} \) can be retrieved from the absorptance measurement using a simple formula:

\[ \sigma_{\text{abs}}^{1D}(\lambda) = Aw_0\sqrt{\pi/2} \]  

(4.8)
Here $A$ is the absorptance and $w_0$ is the beam waist (defined formally in the next paragraph). This formula can be found by considering the Gaussian intensity distribution of the focused spot:

$$I(x, z) = I_G e^{-2\left(\frac{x^2}{w_0^2} + \frac{z^2}{w_0^2}\right)} = \frac{2P_{in}}{w_0^2} e^{-2\left(\frac{x^2}{w_0^2} + \frac{z^2}{w_0^2}\right)}$$ \hspace{1cm} (4.9)

where $I_G$ is the Gaussian peak intensity and $P_{in}$ is the total power carried by the beam. The beam waist $w_0$ is defined as the radius at which the intensity is $I_G/e^2$.

When the wire is subject to inhomogeneous illumination, as with a Gaussian spot, the total absorbed power is found by integrating the intensity along the nanowire, where we assume that we can ignore the intensity gradient over the width of the nanowire (i.e. the wire is a line):

$$P_{abs} = \int \sigma_{abs}^{1D} I(x = 0, z) dz$$ \hspace{1cm} (4.10)

where for simplicity we assume that the wire is aligned along the z-axis. Combining Eq. 4.9 and 4.10 we find Eq. 4.8, where $A = P_{abs}/P_{in}$. This formula has been applied before to carbon nanotubes\cite{144}. Although the assumption is made that the wire is infinitely thin, agreement between this approximation and full-wave simulations is good (see below).

Experimentally we did not observe a dependence of the absorption cross section on the spot size, which we checked by underfilling our objective until the spot size was increased by 60%.

It is important to note that $\sigma_{EQE}$ can also be determined directly from the beam waist, the incident photon flux, and the laser-induced photocurrent: $\sigma_{EQE}(\lambda) = w_0 \sqrt{\pi/2} \int (I_L(z)/S_{in})dz$, where $I_L$ is the laser-induced photocurrent, $S_{in}$ is the total incident photon flux, and the integral again is over the nanowire length. With this approach $\sigma_{EQE}$ can be determined with any laser beam-induced current (LBIC) setup. Additionally, the experimental error will be smaller since both $I_L$ and $S_{in}$ can be determined accurately. For that reason we have determined $\sigma_{EQE}$ in Fig. 4.4 following this approach.

### 4.3.11 Collection cross section for current calculations

The highest possible open-circuit voltage is obtained for the lowest possible recombination current $I_0^{rad}$, which is normally calculated by integrating the EQE over the black-body spectrum. Hence, for a nanostructure we obtain:

$$I_0^{rad} = \int_{0}^{4\pi} \int_{300}^{925} \sigma_{EQE}^{unpol}(\lambda) \Omega(T, \lambda) \cos(\theta) d\lambda d\Omega$$ \hspace{1cm} (4.11)

Here the integration over the black-body photon flux density $\Omega(T, \lambda)$ (where $T$ is the temperature, 300K) is over all angles (taking into account a factor $n^2$ for the higher density of states when integrating over the glass hemisphere), and the $\cos(\theta)$
is the Lambertian factor. Because thermal radiation is unpolarized, we use the average $\sigma_{EQE}$ over both polarizations. We assume that between 300 and 400 nm the absorption cross section stays constant, which is a good approximation given the weakly varying nature of $\sigma_{EQE}$ at shorter wavelengths. Additionally, the fraction of the photon flux in the solar spectrum contained below 400 nm is very small. Assuming that the nanowire absorbs light isotropically, we find a minimum recombination current of $I_{rad}^0 = 3.1 \times 10^{-17} \text{pA}$, resulting in an open-circuit voltage of $V_{oc}^{rad} = 1.16 \text{V}$ in the radiative limit. To validate the negligible effect of our isotropic absorption cross section assumption, we used Lumerical FDTD to investigate the angle dependent absorption cross section. Because the refractive index of wurtzite InP is not known, we investigated two comparable materials, zincblende InP and GaAs (both also have direct band gap in the same energy range), with the same diameter and coating thickness as the nanowire we investigated. We determined the absorption cross section averaged over both polarizations ($\sigma_{abs}^{unpol}$) in a series of single wavelength 2D simulations, using a total-field scattered-field source and perfectly matched layers (PML) as boundary conditions. The results are shown in Fig. 4.12(a) for zincblende InP and in Fig. 4.12(b) for GaAs. These figures show a polar plot of the absorption cross section weighted by the black body spectrum, $\sigma_{abs,w}^{unpol}(\theta)$ where the angle $\theta$ of the incident wave vector lies in the plane perpendicular to the nanowire axis:

$$\sigma_{abs,w}^{unpol}(\theta) = \int_{300}^{\lambda_{BG}} \sigma_{abs}^{unpol}(\lambda,\theta)\Theta(T,\lambda)d\lambda$$  \hspace{1cm} (4.12)

The dashed lines show the isotropic $\sigma_{abs,w}^{unpol}(\theta = 0)$ (where the absorption cross section is equal to the absorption cross section under normal incidence for all angles), while the solid lines show the actual $\sigma_{abs,w}^{unpol}(\theta)$. To assess the difference between the isotropic assumption and the actual angle dependence, we calculate the relative difference in recombination rate:

$$\Delta R = \frac{\int_{0}^{\pi} \sigma_{abs,w}^{unpol}(\theta)n^2(\theta)d\theta}{\sigma_{abs,w}^{unpol}(\theta = 0)\int_{0}^{\pi} n^2(\theta)d\theta}$$  \hspace{1cm} (4.13)

Here $n^2(\theta)$ is the squared refractive index of the medium (glass or air) to account for the different intensity of black body radiation. Evaluating this factor for zincblende InP and GaAs we find that they are $\Delta R = 0.91$ and $\Delta R = 0.96$ respectively. Interestingly, while the angular distribution of $\sigma_{abs,w}^{unpol}$ is modified by the presence of the glass (in particular near the critical angle, where a peak is visible that is also observed for dipole emission near an interface [159]), the integrated $\sigma_{abs,w}^{unpol}$ does not change significantly. In the other plane of incidence (parallel to the nanowire axis) we observe similar behavior, and $\sigma_{EQE}^{unpol}(\lambda,\theta)$ can therefore be approximated as isotropic. The $I_{sc}$ can also be calculated using Eq. 4.11, but $\Theta(T,\lambda)$ has to be replaced by the AM1.5 spectrum and the integral is not carried out over all angles, but just over normal incidence (or the angle subtended by the sun).
4 Quantifying losses and thermodynamic limits in single InP nanowire photovoltaics

Figure 4.12: Absorption cross section versus angle of incidence. Absorption cross section in nm of a zincblende InP nanowire (a) and GaAs nanowire (b) (300 nm diameter with 50 nm SiO$_2$ shell), averaged over both polarizations and wavelengths, weighted by the blackbody spectrum. The strong lobes in the absorption cross section when incident from the glass side coincide with the critical angle in the glass, which is also observed for dipole emission near an interface [159]. These simulations were performed using Lumerical FDTD.

4.3.12 Series resistance and diode ideality factor

Based on a fitting method described in ref. [78] we have determined the diode ideality factor and the series resistance (see Fig. 4.13). The shunt resistance was too high to be able to determine accurately. The ideality factor ($n = 2.08$) and series resistance ($R_s = 0.12 \times 10^9 \Omega$) both reduce the fill factor from its highest possible value, $FF_{\text{max}} = 0.895$. The series resistance can possibly be reduced by improving contact resistivity and reducing the length of the intrinsic part of the nanowire.

Figure 4.13: Determining the series resistance from the IV curve. By fitting the IV curve we determined the series resistance and diode ideality factor, both of which contribute to the fill factor $FF = 0.76$ being below the maximum $FF = 0.895$. The uncertainty in fitted values gives the 95% confidence interval.
4.3.13 Transmission electron microscopy analysis of the wurtzite InP nanowires

Fig. 4.14 shows transmission electron microscopy (TEM) images taken of nanowires grown with the same method as the nanowire under investigation in this chapter. As mentioned in Section 4.3.1, these nanowires are grown with the selective area metal-organic vapor phase epitaxy (SAMOVPE) method. The nanowires under investigation in Fig. 4.14 are slightly thinner than the nanowire, to facilitate TEM imaging. However, we do not expect the diameter to affect the crystalline structure, as they also appear identical in SEM images. The nanowires have wurtzite crystalline structure, and only at the end segment where very high n-doping is used, do we observe stacking faults. The side facets of the wires have oxidized, resulting in a 1-2 nm thick In$_2$O$_3$ layer.

![Figure 4.14: Transmission electron microscopy analysis of wurtzite InP nanowires.](image-url)

- (a) Overview bright-field TEM image, displaying a group of nanowires, all having a mixed phase top segment of < 0.5 µm.
- (b) Overview image of a representative nanowire.
- (c) Selected area electron diffraction (SAED) pattern, acquired from a 1.3 micron long part of the stem, displaying the wurtzite crystal structure.
- (d) Bright-field TEM image of the top of the wire (boxed area in (b)), displaying a defected top part and a defect-free stem.
- (e) High resolution TEM image of the stem, again displaying the perfect wurtzite structure. The side facets of the wires have oxidized, resulting in a 1-2 nm thick In$_2$O$_3$ layer.
- (f) The Fourier transform corresponding to (e), highlighting the high and long-range crystallinity of these nanowires.
In this chapter we focus on the surface properties of the InP nanowires studied in Chapter 4. We show, that we can increase the carrier selectivity of the extended p-type part by HF etching and by applying the high work function interfacial layer MoO\textsubscript{x}. HF etches the native oxide which is known to cause Fermi level pinning. We show, that by additionally applying MoO\textsubscript{x} the charge carrier selectivity of the extended p-part can be increased even further, resulting in an increase of the open-circuit voltage by up to 335 mV, from 500 mV to 835 mV. To electrically passivate the InP surface and protect it against oxidation, we study the influence of surface sulfurization. Preliminary results indicate that sulfurization can indeed increase the open-circuit voltage by removing the native oxide and potentially even passivate the surface against reoxidation. We lay out upcoming experiments and device schemes that have the potential to reach open-circuit voltages above 1V for InP nanowires.
5 Carrier Selective Contacts for Nanowire Solar Cells

5.1 Introduction

Carrier selective contacts are an essential component of solar cells. So far, nanowire solar cells as traditional silicon solar cells mainly rely on impurity doping to create two carrier selective regions.[22] While impurity doping is widely established in the wafer-based semiconductor industry, the control becomes increasingly difficult with decreasing dimensions. The precise doping control for nanowires in the sub-μm range is very challenging and strongly affected by the exact geometry and growth conditions. As we will also show in this Chapter, the doping profile of a nanowire can change unintentionally along the diameter or along the wire length, due to strain-effects of the crystal lattice and different dopant incorporation rates during the growth.[22, 24, 25]

However, carrier selectivity of a contact can also be obtained without the addition of impurity atoms into the host crystal (see also Chapter 2 and 3). If a material with a different work function than the main absorber is brought into close proximity, the charge carriers of the two materials will respond by equilibrating their free energies at the interface. As a result, the Fermi level of the charge carriers can change vastly compared to its value in the bulk. If the semiconductor work function is much larger (smaller) than the one of the adjacent material, the semiconductor can change its conductivity into quasi-n⁻ (p⁺) type close to the surface. The semiconductor has thereby changed its carrier selectivity, even though no additional dopants have been incorporated. Metals or other high or low work function layers can be used, such as highly doped polycrystalline silicon or transparent conductive oxides.[26, 28, 89–91, 116, 117]

Besides providing carrier selectivity by impurity doping or the use of specific external layers, a high degree of surface passivation is crucial. In general, unpassivated interface defects can lead to Fermi level pinning. If those defects occur at the contact interfaces, often induced by direct contact with an adjacent metal, the efficient extraction of charge carriers with a photo-induced potential is inhibited. Importantly, the Fermi level pinning can even counteract the influence of a high or low work function material by fixing the Fermi level at a defect level, irrespective of the internal carrier concentrations.

In this chapter we show doping inhomogeneities of our studied nanowires by variations in the photoluminescence yield. Subsequently, we study the detrimental impact of the native oxide of InP on the carrier selectivity, especially for p-type InP. To that end, we conduct I-V measurements of single nanowire devices before and after HF treatment. In the next step, we apply the emerging carrier selective contact MoOₓ which mitigates negative effects due to inhomogeneous dopant incorporation. Finally, we propose the use of a molecular passivation layer, sandwiched between the unoxidized InP surface and the high work function layer MoOₓ for both decreased surface recombination and increased carrier selectivity.
5.1 Introduction

5.1.1 Doping inhomogeneities

One way to measure the doping concentration indirectly is via the collection of luminescence after initial photon absorption, that is photoluminescence. The absorption depends on the material geometry and the absorption coefficient and leads to the excitation of charge carriers. Subsequently, those carriers decay either radiatively or non-radiatively. Therefore, the photo-excited charge carrier density (determined by the absorption), the doping concentration and non-radiative recombination are essential. If structures are investigated that have the same geometric dimensions and are of the same material quality, photoluminescence can give detailed information about the doping density.[158, 160]

![Figure 5.1: Variation in photoluminescence for randomly dropcast nanowires.](image)

(a) A map of PL intensity variations between different wires, all grown under the nominal same conditions. (b) SEM image of the marked region of Fig.5.1(a). The SEM allows for localization of the broken end part and hence the orientation of the wires (white arrows in (c),(d)). Together with the knowledge of the growth recipe (p-i-n, bottom-center-top), the bright end parts of the wires in (a) can be linked to the highly n- doped region. Notably, for wires with similar diameters (\(\Delta d \pm 10\) nm), the end parts as the rest of the wires do not show homogeneous brightness. (e) Strong PL variations along the length and between two different wires. (f) PL spectra of the two marked regions in (e). The shift in wavelengths and intensity due to the different doping concentration is clearly visible (explanation see text). The spectra have been averaged over the marked area from 800 nm - 900 nm to display the maps in (a) and (e).
Fig. 5.1(a) shows variations in photoluminescence (PL) for randomly dropcast nanowires that are indicative of variations in the doping profile. Fig. 5.1(b) shows an SEM image of the marked region of Fig. 5.1(a). The SEM allows for localization of the broken bottom part and hence the orientation of the wires (white arrows in Fig. 5.1(c) and (d)). Together with the knowledge of the doping profile (p-i-n, bottom-center-top), the bright end parts of the wires in Fig. 5.1(a) can be linked to the highly n⁻-doped region. Furthermore, we conducted PL measurements before and after the contacting procedure for single nanowire devices. We employed specific contacts for the n-type (Ti/Au) and for the p-type part of the wire (Cr/Zn/Au) which allowed us to confirm our assumption about the orientation of the wire. For nanowires that have been oriented with the p-type (n-type) part towards the electron (hole) contact (connected backwards), high extraction barriers have been observed. In Fig. 4.3 in Chapter 4 we show a PL measurement of a wire after it has been contacted. Also this measurement confirms that the bright part is located next to the electron contact. As can be clearly seen in Fig. 5.1(a), the end parts, as the rest of the wires, do not show homogeneous PL brightness. Additionally, Figure 5.1(e) shows strong PL variations not only between but also along the length of two different wires. The PL variations in Fig. 5.1(a) and (e) are noteworthy. The wires have very similar geometric dimensions (Δd ± 10 nm) and hence a very similar absorption. Furthermore, detailed TEM analysis, as in Section 4.3.13 of Chapter 4, shows a high crystal quality, except for a 500 nm short section of the highly doped end part, which exhibits pronounced stacking faults. Therefore, the absorption and non-radiative recombination due to defects can be assumed to be very similar across individual nanowires. Consequently, the PL variations that we observed can be related to a largely varying doping density, even though all nanowires have been grown under the same conditions. Figure 5.1(f) shows the PL spectra of two marked regions in Figure 5.1(e). It is worth noting, that not only the intensity changes, as described above, but also a shift and a change of the PL spectra occurs. The spectrum of the middle part of the wire (green) shows two distinct peaks at around 840 nm (~1.48 eV) and 860 nm (~ 1.44 eV) which is related to a splitting of the valence band for wurtzite InP nanowires by 40 meV (see also Fig. 4.2 in Chapter 4).[149, 161] The spectrum on the end part of the wire (red) shows only one peak at 840 nm. Considering, that the end parts of the wires are supposedly highly doped, we assume that a blue shift of the spectrum occurs because of band filling of the lower band. However, given that the intensity of the end part is strongly reduced compared to the middle part, the high doping must be accompanied by a strong non-radiative decay, such as Auger recombination. The spectra have been averaged over the marked area from 800 nm - 900 nm to display the maps in 5.1(a) and 5.1(e). The strongly varying doping profiles in Figure 5.1 clearly show the difficulties in controlling the exact doping profile and homogeneity during the growth. Those results underline the importance of finding alternatives to impurity doping and the need for single nanowire studies. Instead of relying on ensemble averages of arrays, which consist of millions of different wires, isolated studies of single nanowires enable better understanding of the intricate mechanisms.
5.1 Introduction

Figure 5.2: Studied single nanowire device schemes. (a) Shows schematically the single InP nanowire device as studied in Chapter 5 with the addition of a resist window, fabricated by e-beam lithography (layers not to scale). The current flows of the photo-induced charge carriers is shown below the scheme. As can be seen, the electrons not only flow through the n-type region and to the designated electron contact but also into the p-doped region, where they can recombine. (b) Shows the same device as in (a), however after the removal of the SiO₂ capping layer and the native oxide. As a result, the Fermi level pinning is reduced and the contact selectivity increases, decreasing the electron flow towards the hole contact. (c) Shows the device after the evaporation of the high work function interfacial layer MoOₓ and a capping layer of Au. Due to the high work function, the contact selectivity increases even further, as compared to (b). (d) Optical dark field microscope image of several devices after step (c).
5.2 Results and discussion

Fig. 5.2(a) schematically shows the single InP nanowire device as studied in Chapter 4 with the addition of a resist window, fabricated by e-beam lithography. As can be seen, the nanowire consists of a long extended p-doped and a shorter n-doped part. In Chapter 4, we explained the deviation from the intended, symmetric doping profile (\( p^+ / p / i / n / n^- \), \( 1 \mu m / 3 \mu m / 4 \mu m / 3 \mu m / 1 \mu m \)) by the high diffusivity of the p-type dopant zinc, especially at high zinc concentrations and temperatures. Furthermore, we found that the limited contact selectivity causes a difference between the measured and the implied \( V_{oc} \) of about 100 mV, even for the best performing devices, grown by SA-MOVPE. Figure 5.2 depicts in a schematic way how decreased contact selectivity in the p-doped part of the nanowire can lead to an electron current into the wrong direction, i.e. away from the electron contact and towards the hole contact. Eventually, those electrons can recombine radiatively or non-radiatively (depicted by stars), decrease the sustained carrier concentration and hence lower the measured open-circuit voltage. For an efficient hole-contact, the quasi-Fermi level of the holes has to be as close to the valence band as possible. However, the native oxide of InP (InO) leads to Fermi level pinning under the conduction band. As a result, for p-type InP the conduction type of the region close to the surface is inverted to quasi-n\(^-\). The minority carriers of the bulk, that is electrons, can now flow freely towards the surface, where they rapidly recombine. For the nanowire geometry with its large surface-to-volume ratio, the surface inversion can even extend into the bulk. Thereby, it strongly affects the effective doping concentration and hence reduces the contact selectivity of the extended p-doped part, together with the described non-ideal doping concentration.

Fig. 5.2(b) schematically depicts the same device after HF treatment of an extended region on the p-doped part. The SiO\(_2\) capping layer and the native InO have been removed. As a result, the Fermi level pinning under the conduction band is reduced and the contact selectivity increased. Less electrons are flowing towards the p-doped region. Fig. 5.2(c) shows the device after evaporation of 20 nm MoO\(_x\) and a capping layer of Au. Besides the removed Fermi level pinning by the HF treatment, the high work function interfacial layer MoO\(_x\) induces hole accumulation in the p-type part and hence improves the contact selectivity substantially. As a result, electrons flow almost solely towards the electron contact, allowing for a higher carrier concentration and hence open-circuit voltage than in 5.2(a) and 5.2(b.)
5.2 Results and discussion

5.2.1 HF treatment

For the following, it is important to note that all the resist windows have been fabricated prior to the first measurements. This way any effects on the measurements by the fabrication can be excluded. Figure 5.3(a) shows the I-V curves of two devices before (dashed) and after (solid) HF treatment. The increase in \( V_{oc} \) is clearly visible. Table 5.1 shows the increases in open-circuit voltage for different devices of the two growth batches. For the nanowires of batch 1 (S1B1 - S3B1), the HF treatment improves the open-circuit voltage by about 20 - 60 mV while the wires of batch 2 (S4B2 - S9B2) improve even by 16 - 130 mV. Clearly, the HF treatment and the removal of the native oxide improved the device performance substantially. The two different batches correspond to nanowire arrays grown by the same method, SA-MOPVE, however with different pitches (In 4.3.4, p1-d3 and p2-d1, for B1 and B2 respectively). While the exact influence of the different geometries is still under investigation we speculate that the tendency of sparse nanowire arrays to show higher \( V_{oc} \)'s might be related to better Zn incorporation from the gas precursor. For dense arrays depletion effects might take place, which reduce the overall concentration of the p-dopant and hence lower the carrier selectivity. Figure 5.3(b) shows the I-V curve for one wire before the HF etching and for subsequent times after the HF etching. As can be seen, after the initial improvement due to the HF etching the native oxide grows back on the exposed part. The \( V_{oc} \) and \( I_{sc} \) decrease rapidly to the starting values. Interestingly, the response on the \( I_{sc} \) and \( FF \) is not consistent across different devices. As can be seen in Fig. 5.3(a), the \( I_{sc} \) and \( FF \) for devices S7B2 and S4B2 slightly decrease, while for S2B1 in Fig. 5.3(b) a pronounced increase, both in the \( I_{sc} \) and \( FF \) can be observed.

Figure 5.3: I-V curves before and after HF treatment. (a) The effect on the contact selectivity and hence \( V_{oc} \) is clearly visible. Dashed and solid lines show the IV curve before and after the HF etching, respectively. With the HF treatment the surface passivation and contact selectivity increase, because of the removal of the native oxide. (b) After the initial increase in performance (yellow), the native oxide slowly grows back (cyan, red, black) and thereby reduces the device performance. The vertical dashed lines are guides for the eye.
## Table 5.1: HF treatment

All $V_{oc}$ values are in mV. As can be seen the $V_{oc}$ increases for all devices directly after the HF treatment, between 20-60 mV for batch 1 (S1B1-S3B1) and between batch 2 (S4B2-S9B2).

<table>
<thead>
<tr>
<th>Sample</th>
<th>$V_{oc}^{start}$</th>
<th>$V_{oc}^{end}$</th>
<th>$\Delta$</th>
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</thead>
<tbody>
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<td>330</td>
<td>350</td>
<td>20</td>
</tr>
<tr>
<td>S2B1</td>
<td>430</td>
<td>485</td>
<td>55</td>
</tr>
<tr>
<td>S3B1</td>
<td>550</td>
<td>606</td>
<td>56</td>
</tr>
<tr>
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<td>836</td>
<td>16</td>
</tr>
<tr>
<td>S5B2</td>
<td>725</td>
<td>790</td>
<td>65</td>
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<tr>
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<td>680</td>
<td>780</td>
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</tr>
<tr>
<td>S8B2</td>
<td>370</td>
<td>500</td>
<td>130</td>
</tr>
<tr>
<td>S9B2</td>
<td>665</td>
<td>695</td>
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### 5.2.2 MoO$_x$ treatment

To prevent the regrowth of the native oxide and increase the contact selectivity, the high work function interfacial layer MoO$_x$ has been evaporated on freshly HF etched devices. The work function of MoO$_x$ has been determined to be between 5.7 eV - 6.6 eV, depending on the amount of carbon contamination (decreasing with increasing carbon content).[27] The valence band edge of zincblende InP ($E_g$ = 1.34 eV, 300K) lies at a value of around 5.8 eV. For wurtzite InP ($E_g$ = 1.43 eV, 300K)) the valence band lies around 5.75 eV.[162] Therefore MoO$_x$ should be able to completely invert the surface. While MoO$_x$ has a very high work function it does suffer from relatively poor electrical transport and should therefore only be used as an interfacial thin layer.

Fig. 5.4 shows the I-V curves of two representative devices before and after the HF etching and MoO$_x$ evaporation. The effect on the device performance is clearly visible, the open-circuit voltage increases by 334 mV for M2B1 from 454 mV to 788 mV, due to the improved contact selectivity. Furthermore, even though roughly half of the wire is covered with an opaque MoO$_x$(20 nm)/Au (100 nm) double layer, the short-circuit current of M2B1 improves, as well. The later can be ascribed to a better charge carrier extraction than in the case without surface treatments. In Chapter 4 we observed a localized photocurrent collection close the the electron contact, while the extended p-part did not show any substantial photoactivity.

With the evaporation of MoO$_x$ charge carriers in the vicinity can be extracted additionally via the MoO$_x$ reducing the potential recombination in the extended p-type part of the wire. The second wire, M5B2, only improves the $V_{oc}$ by about 35 mV from 757 mV to 792 mV. Furthermore, the $I_{sc}$ decreases by a factor of two, which points to the fact that the MoO$_x$/Au double layer shadows roughly half of the active part of the wire. Together with the observation that the open-circuit voltage was already relatively high before the treatment this indicates that the wire...
5.2 Results and discussion

Figure 5.4: I-V curves before and after HF+MoO\textsubscript{x} treatment. The effect on the contact selectivity and hence the open-circuit voltage is clearly visible. The selectivity increases substantially with HF etching and MoO\textsubscript{x} evaporation. The sample from batch 1 (M2B1) increases by 334 mV, while the sample from batch 2 (M5B2) increases by 35 mV. The vertical dashed lines are guides for the eye and indicate the open-circuit voltage.

Some of the observed I-V curves, including the ones shown in Fig. 5.4, develop an s-shape after the treatment, even though they improve their $V_{oc}$. We explain this behavior by the electrical transport properties of the MoO\textsubscript{x} thin-film. It has been observed before, that the low mobilities in MoO\textsubscript{x} lead to the development of s-shaped I-V curves due to a strong increase of the series resistance for film thicknesses exceeding $\sim 10 - 15$ nm.[27]

Table 5.2 shows the open-circuit voltage enhancement of different devices before and after the HF and MoO\textsubscript{x} treatment. As can be seen, the $V_{oc}$ improves substantially by up to 335 mV up to a value of 835 mV, a value very close to the maximum $V_{oc}$ observed for the best performing device in Chapter 4 (850 mV). Interestingly, even though the average $V_{oc}$ increased by about 100 mV compared to Chapter 4, none of the devices exceeded the maximum value of 850 mV. PLQY measurements in Chapter 4 showed that even the maximum $V_{oc}$ of 850 mV is reduced due to
non-selective contacts by 100 mV, from around 950 mV. Therefore, the upper limit for our treatments in this chapter is 950 mV, not 850 mV. Hence we assume that another recombination mechanism inside the extended p-type part of the wire, which cannot be removed by the application of MoO$_x$, is ultimately limiting the contact selectivity. Currently, we are conducting experiments to replace the extended p-type part of the nanowire altogether.

### 5.2.3 Sulfur treatment

In the previous sections we showed how the native oxide reduces the open-circuit voltage by Fermi level pinning under the conduction band at the surface (schematically shown in Fig.5.5(a)). However, we have also shown that the oxide grows back rather rapidly; a substantial reduction of the open-circuit voltage of 50 mV can already be observed after 30 min.

For the MoO$_x$ treatment we observe an increase in the open-circuit voltage of up to 334 mV (Fig.5.5(b)). Even though the MoO$_x$ has been evaporated on freshly HF etched samples, it is likely that the native oxide grew back partially, especially because of the oxygen-rich MoO$_x$ film. We have not observed a pronounced degradation for the samples with the MoO$_x$ layer. Therefore we speculate that if the MoO$_x$ indeed leads to regrowth a thin native oxide layer, this growth must happen during or shortly after the evaporation and capping of the MoO$_x$ layer. Furthermore, because the samples are laying on a substrate, the HF is unlikely to etch the native oxide homogeneously and the MoO$_x$ capping does not extend around the whole wire.

To prevent the reoxidation and enhance the impact of the MoO$_x$ coating, we propose a contact scheme that makes use of an additional thin tunnel and passivation layer, very similar to the one employed for MIS solar cells. Recently a report appeared that utilized a similar contact scheme to improve the performance of AZO - InP nanopillar heterojunction solar cells.[163] In the following we will show preliminary results about the impact of surface sulfurization on our nanowires. However, in general many other possible passivation layers are available that could

<table>
<thead>
<tr>
<th>Sample</th>
<th>$V_{oc}^{start}$</th>
<th>$V_{oc}^{end}$</th>
<th>$\Delta$</th>
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</tr>
<tr>
<td>M2B1</td>
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<td>334</td>
</tr>
<tr>
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</tr>
<tr>
<td>M4B1</td>
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</tr>
<tr>
<td>M6B2</td>
<td>700</td>
<td>760</td>
<td>60</td>
</tr>
</tbody>
</table>

Table 5.2: HF+MoO$_x$ treatment. All $V_{oc}$-values are in mV. As can be seen the $V_{oc}$ increases for all devices after the HF etching and MoO$_x$ evaporation, between 200-335 mV for batch 1 (M1B1-M4B1) and between 35-60 mV for batch 2 (M5B2-M6B2).
be studied, also those that can potentially be grown in the vapor phase, directly after the nanowire growth.

Fig. 5.6 shows preliminary results of the effect of surface sulfurization on a nanowire. The device (S2B1) is the same nanowire that was studied for the HF treatment in Fig. 5.3 After the native oxide grew back, the extended p-type part of the wire has been exposed to an ammonium sulfide ((NH₄)₂S) solution (for details see Methods section). The solution is known to etch the native oxide of InP and to passivate the surface. However, as can be seen in Fig. 5.6, the \( V_{oc} \) increases to about 550 mV, substantially above the value of 485 mV that has been observed after the HF treatment (blue curve). We speculate that the sulfurized surface protects the wire against the rapid reoxidation during the rinsing and nitrogen blow-drying steps and therefore shows superior performance compared to the HF treatment. However, even though the open-circuit voltage increases substantially, the short-circuit current stays approximately at the value before the HF treatment. This is in contrast to the HF treatment, which not only increases the open-circuit voltage but also the short-circuit current. From experiments on InP bulk wafers (zinc blende)
and InP nanowires, it is known that the surface properties after sulfurization vary largely, depending on the exact condition (concentration, time, temperature, additional solvents).[164–168] Therefore, further experiments are needed to optimize those conditions also with respect to reducing non-radiative recombination due to surface defects and to increase the number of total measured devices. We found that for resist windows that were exposing not only the nanowire, but also partly the metal contacts, all of the HF and (NH$_4$)$_2$S treatments strongly degraded the metal contacts, which reduced the yield of the first run substantially.

Besides the optimization of the initial sulfur treatment, we are currently also exploring possibilities to stabilize the sulfurized surface against degradation by employing SiO$_2$ and other capping layers. It has been shown that sulfur atoms only form relatively weak covalent bonds and can easily degrade in ambient conditions over extended periods.[169] Therefore, a capping layer is of utmost importance to improve the stability of the sulfur layer.

Finally, we propose to enhance the effect of the MoO$_x$ by realizing a coating that wraps around the whole p-type part of the wire. This way, the MoO$_x$ can effectively invert the whole nanowire interior and create a highly selective contact (Fig.5.5(c)). While this wrap-around geometry is challenging to realize for horizontally aligned single nanowires, because of limited access to the nanowire-substrate interface, it can readily be achieved for nanowire arrays. In fact, as we will show in the following application chapter by proposing a novel nanowire fabrication process, the nanowire arrays can be embedded into a polymer or glass matrix which allows the selective sulfurization and application of MoO$_x$ to the nanowire tips.
5.3 Conclusion

In this chapter we have shown how the extended p-type part of the InP nanowires studied in Chapter 4 can be improved with respect to its carrier selectivity. We show how the removal of the native oxide can improve the open-circuit voltage by up to 100 mV. The addition of the high work function interfacial layer MoO\textsubscript{x} improves the open-circuit voltage up to 335 mV. By that we show that the reduced carrier selectivity is likely due to insufficient doping concentration of the extended p-type part of the wire, either due to limited dopant incorporation or post growth diffusion. Finally, we show preliminary results on the surface sulfurization of the extended p-part of the wire. We can show that the sulfur treatment improves the carrier selectivity of our studied device, but degrades the short-circuit current by a factor of roughly 1.5. We discuss ongoing experiments that focus on the optimization of the sulfur treatment, including encapsulation and direct application to the InP and MoO\textsubscript{x} interface. This way the growth and the negative impact of the native oxide can be prevented and at the same time the properties of the high work function layer MoO\textsubscript{x} fully exploited, especially when the extrinsic layers are wrapped around the tip of the nanowire.

The results presented here give new insights into the performance of InP nanowires and pave the way towards open-circuit-voltages $> 1$V. Eventually, we envision dopant free nanowire solar cells, unaffected by decreased mobilities, increased non-radiative recombination and inhomogeneous and insufficient dopant profiles.

As we will show in the following chapter, the removal of the material specific impurity doping extends its impact beyond improved device performance. By employing novel carrier selective contacts that rely on extrinsic surface layers e.g. MoO\textsubscript{x}, their use is not limited to InP but can be extended to other materials, as well. This versatility does not only lead to a simplification but also enhances the flexibility of our proposed fabrication process.

5.4 Supplemental information

5.4.1 Fabrication and measurements

The samples were fabricated, contacted and measured as described in the supplemental information of Chapter 4, 4.3.1, 4.3.2 and 4.3.3, respectively. For the fabrication of the resist windows, a third electron beam lithography step was added. For the HF treatment, the exposed nanowire parts were etched in buffered HF (1:7, HF (49%): NH\textsubscript{4}F (40%)) for 10 s to remove the protective SiO\textsubscript{2} shell ($\approx 50$ nm) and the native oxide of the InP under the contact. For the MoO\textsubscript{x} treatment, first the HF etching has been repeated after which MoO\textsubscript{x} has been thermally evaporated at a rate of around 0.3-1 Å/s and a pressure of $2 \times 10^{-6}$ mbar. The target thickness was 15 nm, however, after a short but very high spike in the evaporation rate, the final
thickness was ~ 20 nm. For the sulfurization, the samples were immersed for 5 min in 5% (NH₄)₂S solution in water.

The photoluminescence spectra were obtained with a Witec confocal microscope (Alpha 300 SR). The samples were illuminated with a 532 nm laser, and the light was focused and collected via a 100X NA0.9 objective. A spectrometer with a 150 g/mm (BLZ= 500 nm) grating (center wavelength 760 nm) and a cooled CCD camera have been used. The integration time was 0.09 s and the scan speed 6.83 s/Line.
Valorisation: A nanowire solar cell fabrication process

In this chapter we explore application opportunities that emerge out of our insights from the preceding chapters. Our increased knowledge about the internal workings in InP nanowires, especially with respect to selective contacts, allows us to propose a novel manufacturing process for nanowire solar cells. This process exploits the intrinsic advantages that emerge out of the nanowire geometry compared to thin-films; faster growth speeds, reduced material consumption, fast mechanical peel-off and intrinsic anti-reflection properties. We perform a techno-economic analysis of our proposed fabrication process by comparing the process to an already commercialized and very similar manufacturing process for thin-film GaAs solar cells. We include different nanowire growth methods that could be utilized for our proposed process and show that they have an enormous potential to reduce the manufacturing costs compared to MOVPE thin-films. The ability to discuss different growth methods points towards another important characteristic; the process line is highly flexible and not limited to one growth method, let alone semiconductor. We argue that this can have a substantial impact on the rate of innovation in a hypothetical company invested into this process. For future portfolio expansions we envision all-nanowire tandem configurations and III-V nanowires on silicon, all realized with essentially the same fabrication process. We close by proposing a roadmap for future developments and commercialization.
6 A nanowire solar cell fabrication process

6.1 Introduction

Here, we explore valorization opportunities that emerge out of our insights from the preceding chapters. In Chapters 4 and 5, we have conducted fundamental studies on horizontally aligned and isolated single InP nanowire devices. Those fundamental studies have increased our understanding about the thermodynamic limitations and especially about prevailing loss mechanisms. We not only quantified the impact of non-ideal contacts and non-radiative recombination on the device performance; we also showed first results towards reducing those loss channels. Previously, high quality contacts in terms of selectivity and Ohmic resistance have been an unresolved challenge for p-type InP nanowires, because of limited p-type dopant concentration and Fermi level pinning at the surface.

Those findings have implications far beyond fundamental studies on the single nanowire level. For practical devices, large arrays of vertically aligned nanowires have to be employed. The intricate optical characteristics of nanowires require precise alignment and ordering of the nanowire arrays to optimize absorption and emission properties. The current record holders are arrays of GaAs (15.3%) and InP (17.8%) nanowires.[13, 14]

Those nanowire array solar cells employ a single crystalline and highly doped substrate (GaAs or InP) for the nanowire growth and to establish electrical contact to the p-type part of the wires. As a result, even though nanowires are employed that principally could reduce the required material volume due to their optics, the final solar cell utilizes nanowires in addition to a costly substrate. Furthermore, the substrate provides a high density of optical states that lead to increased light emission into the highly doped and hence recombination active region. Those substrate related drawbacks have spurred interest in ways to separate nanowires after the growth from the substrate while maintaining the highly ordered array geometry. This is especially important in view of economically feasible applications.

It has been shown that nanowire arrays can be embedded in polymers and peeled off from their substrates to make suspended flexible foils.[170–174] However, the unresolved issue of the challenging contact formation for p-type InP nanowires has created a stand still at this front.

In this thesis we have overcome this obstacle by finding ways to form highly selective contacts with a low contact resistance. Enabled by those fundamental findings, we lay out a pathway towards practical nanowire array solar cells: we propose an industrial manufacturing line.

We start by describing the fabrication process in technical detail and by discussing the expected and forecasted solar cell performance. The InP nanowires of the two preceding chapters have been obtained via selected-area metal-organic vapor phase epitaxy (SA-MOVPE). In our analysis we also discuss close space vapor transport (CSVT) and top-down etching as two alternative fabrication methods and extend our analysis to GaAs nanowires.

Starting from first principles it is challenging to estimate the technical feasibility of a large scale production and especially the future cost of a fabrication process.
Therefore, we compare our proposed fabrication process to a very similar and already commercialized one: flexible, high-efficiency thin-film GaAs solar cells (Fig. 6.1).[176] The general fabrication steps are known and allow for a sound estimate of the technical feasibility of our proposal.

To estimate the future costs of our technology, we rely on a cost model that has been developed by NREL for thin-film GaAs solar cells.[175] It allows us to conduct a techno-economic comparison to GaAs thin-films. However, the cost model by NREL has been developed under the same constraints, that is with limited knowledge about the undisclosed fabrication parameters. Therefore, we end our cost analysis with a relative cost comparison, underlining the most important cost factors (material usage, growth method and speed and peel-off speed). We are able to show that nanowire solar cells can reduce the costs relative to commercialized GaAs thin-film solar cells, even though the exact costs are unknown.

We discuss competing technologies and the emerging multi-billion dollar markets for electric vehicles and the internet of things. We forecast that those markets will be crucial for next generation solar cells, because they allow commercialization and development without forcing new companies to immediately compete against the mature silicon solar cell technology on a commodity market.

Finally, we discuss another very important feature: the process is highly flexible because it is largely independent of the exact growth process and semiconductor. This is in strong contrast to traditional solar cell fabrication processes, which are highly specific and limited to the employed semiconductor. The origin of that feature can be found in the very nature of the process. It exploits the intrinsic advantages that emerge from the nanowire geometry compared to thin-films; fast and flexible growth, reduced material consumption, fast mechanical peel-off and intrinsic anti-reflection properties. We close with a roadmap for the future.
6.2 Process overview

In the following, we sketch out the fabrication process for InP nanowire solar cells grown by SA-MOVPE as this growth method has been used to grow the high quality nanowires in the preceding chapters. The process is however very flexible and can be expanded with minor adaptations to other materials (e.g. GaAs) or other growth methods, e.g. top-down etching, as we will discuss in detail below.

Figure 6.2 shows an overview of the proposed fabrication process, which starts with a single crystalline p-type InP wafer (Fig. 6.2(a)). The wafer is coated with a SiN mask, which can be patterned on a large scale by soft imprint lithography and top-down plasma etching (Fig. 6.2(b)). This patterned high quality substrate wafer is the basis for the following steps and can be reused multiple times.

The patterned substrate is moved into a MOVPE reactor, where precursors flow into the chamber at a specific rate, temperature and pressure (Fig. 6.2(c)). For the growth of InP nanowires, trimethylindium and phosphine are used. Additionally, p-type (n-type) doping of the nanowire end parts can be achieved by flowing diethylzinc (ditertbutylsilane) into the chamber. The final nanowire geometry consists of the n-doped nanowire tip on the top, an intrinsic part in the center and the p-doped part at the bottom, in contact with the p-doped substrate wafer. As we showed in the previous chapter, new selective contacts have the potential to remove the doping step and with it the encountered difficulties for the nanowire doping.

Then, the nanowire array is moved out of the MOVPE reactor and either into a chemical bath or directly into a plasma-enhanced chemical vapor deposition (PECVD) or ALD system to coat the nanowires with sulfur-based precursors and SiO$_2$. Both steps passivate the wurtzite InP surface (Fig. 6.2(d)). In the future, we expect this step to be a purely vapor phase method, as the functionalization of the InP surface with sulfur atoms is not restricted to solution-based methods.

After the surface passivation, the nanowire arrays are coated with a flexible polymer by spin, dip or spray-coating, after which a short O$_2$ plasma etch step is used to remove residual resist on the n-doped top part of the wire (Fig. 6.2(e)).

Now the back contact can be fabricated by standard metal evaporation. To improve film stability, the metal layer can be made thicker, either in a double layer or even single layer configuration 6.2(f).

In the next step, a thick and flexible polymer or glass handle is applied which binds tightly to the metal. The embedded nanowire array is then mechanically peeled-off from the substrate 6.2(g). This process step can be very fast, as it does not require chemicals to dissolve a buffer layer, as for epitaxially grown thin-films.

The substrate is now chemically cleaned from the polymer and can be reused many times, as the actual InP base material is not attacked 6.2(g-b).

The peeled-off flexible nanowire film has to be contacted right after the peel-off step by evaporating a thin and transparent film of MoO$_x$, followed by a thicker TCO layer to facilitate the p-type contact (Fig. 6.2(h)).

This process can essentially be applied to many different semiconductor nanowires.
Figure 6.2: Process overview of nanowire solar cell fabrication. (a) P-type InP substrate wafer, (b) patterned SiN coating, (c) MOVPE growth of InP nanowire array, (d) surface passivation, (e) polymer coating and short O₂ etch, (f) n-type metal contact, (g) mechanical peel-off step and (h) transparent p-type InP TCO contact and metal contact fingers. The patterned substrate (b) can be recycled many times as it only requires a short chemical etch between (g) and (b). This envisioned process is not limited to InP, but can be extended to other semiconductors, such as GaAs or GaInP, as well.
6 A nanowire solar cell fabrication process

6.3 Technical details

6.3.1 Substrate patterning

As we discuss below, for SA-MOVPE and CSVT growth the InP wafer has to be coated with a SiN masking layer (e.g. by PECVD), and subsequently patterned by a large scale lithography process such as soft imprint or the related substrate conformal imprint lithography (SCIL).[177, 178] For soft imprint lithography a flexible stamp, which has been obtained by casting a polymer over a master, fabricated by electron beam lithography, is pressed into the resist layer. Then the resist is cured (heat or UV) and the stamp released. A short O$_2$-descum step is added to remove residual resist on the bottom of the nanoscale indentation. This technique allows for a low-cost but large scale patterning of nanoscale features with dimensions $> 100$ nm. Since the nanowires have diameters in the range of $\approx 100 – 200$ nm and the arrays pitches of $\leq 500$ nm, soft imprint lithography has a sufficient resolution.

6.3.2 Growth methods

In the following we shortly summarize competing technologies for the fabrication of nanowire array solar cells. As mentioned above, one of the great advantages of this fabrication process is its high flexibility.

Top-down etching

The first method relies on top-down plasma etching of nanowires into a substrate wafer via an etch mask. The plasma etching in research reactors can be relatively fast for inductively coupled plasma etching ($\approx 2$ $\mu$m/min).[179] As described in the cost section, the material costs for nanowires that are obtained by top-down etching into bulk wafers can be lower compared to many other growth techniques. Even though the etching consumes up to 80% of the wafer (depending on the exact geometry), the cost per unit volume is substantially cheaper than for MOVPE thin-films. While the patterning step of the etch mask needs to be repeated with every step, nanosphere lithography is a low-cost and large-scale method which can be employed for that purpose.[180, 181] An open question is the quality of the substrate wafer, especially for GaAs, which can vary largely depending on the growth method employed.[182] While liquid encapsulation Czochralski (LE-CZ) and the vertical gradient freeze (VGF) methods can provide single-crystalline wafers, the high-purity requirements for high-efficiency solar cells are more demanding. Most of the current applications of GaAs wafers have different requirements, such as a very high carbon concentration which leads to Fermi level pinning at a mid band gap defect state and hence a semi-insulating wafer (SI GaAs). The vast majority of available GaAs wafers has specifications unsuited for efficient solar cells.

InP wafers can be obtained at a desired quality, however they are more expensive due to reasons mentioned in the cost discussion.
6.3 Technical details

**CSVT**

Close-space vapor transport (CSVT) is a growth technique which uses H$_2$O vapor to etch a solid GaAs source and thereby generates the vapor-phase reactants As$_2$ and Ga$_2$O at atmospheric pressures. Those in situ generated precursors diffuse driven by a thermal gradient towards the cooler substrate and deposit as GaAs. The substrate is spaced closely (< 1 mm) from the source, which results in a high precursor utilization of up to 95% and a high growth rate of up to 1 μm/min. Additionally, the reactors can be built relatively cheaply and the growth principle allows for very fast and large batch processing.[183] In fact, the reactor design is very similar to already commercialized reactors that are employed for CdTe growth. Recent developments showed the high potential of CSVT as a viable technique for future industrial applications, with epitaxial GaAs thin-films on par with commercial single crystalline wafers and selective area epitaxy of GaAs microstructures.[183–185] So far, selected-area epitaxy of nanostructures has not been shown, but current developments are very promising.

**Figure 6.3: The MOVPE reactor.** The reactor utilizes gas precursors such as trimethylindium and phosphine to grow semiconductors inside the deposition chamber. The gases are entering the chamber via a diffuser and mixing chamber that, together with the rotating substrate wafers, guarantee a homogeneous deposition. The MOVPE reactor is highly flexible as many different precursor gases can be utilized for the growth of a wide range of semiconductors. Taken from NREL.[175]
SA-MOVPE

Selected area metal-organic vapor phase epitaxy (SA-MOVPE) growth relies on the fact that materials like InP and GaAs can be grown epitaxially along the (111) direction of a substrate wafer. To obtain nanowires the substrate is covered with a mask that only allows the nanowire growth in selected areas.[186] For research reactors, the growth rate is relatively slow (~ 0.2 μm/min), however about 5-10 times faster than the thin-film growth (~ 0.02 μm/min). Industrial reactors have shown increased growth rates for epitaxial thin-films of up to (~ 0.25 μm/min) and likely above (but undisclosed).[176] Assuming similar precursor utilization efficiency between thin-film and nanowire growth (which is commonly seen), simple conservation of matter arguments lead to a growth rate 5-10 times higher for nanowires (depending on exact nanowire diameter/pitch).

Figure 6.3 shows a schematic of a MOVPE reactor, taken from a publication by NREL [175]. As can be seen, the MOVPE reactor consists of multiple gas sources, transport lines, mass flow controllers and valves which deliver the desired gases to the growth chamber. Entering the growth chamber, the precursors are delivered into the chamber at a specific flow rate, temperature and pressure. For the growth of InP nanowires, trimethylindium and phosphine are used. Additionally, p-type (n-type) doping of the nanowire end parts can be achieved by flowing diethylzinc (ditertbutylsilane) into the chamber.

A commercial MOVPE system can hold up to 8×6” or 15×4” wafers [175] and is estimated to provide a precursor utilization of currently ~ 30% for the group III sources (Al/Ga/In) and ~ 20% for the group V sources (N/P/As/Sb).[175] Main loss sources are side wall deposition in the plumbing system and deposition chamber, as well as the venting and purging processes via the waste line.

One of the great benefits of a MOPVE reactor is its versatility; because the material is delivered via gas precursors the growth is expandable to other materials, simply by switching the precursors and substrate wafers. Among those alternatives are GaAs, GaP, InGaP and GaN.

6.3.3 Surface passivation

As also shown in Chapter 5, the surface recombination of nanowires can be lowered by specific surface treatments, even for InP with its low intrinsic surface recombination. These treatments can passivate the surface chemically or via the field-effect, that is interface charges that repel minority carriers. Therefore we include an extra passivation step in the proposed fabrication process (Fig. 6.2(d)).

6.3.4 Polymer/glass coating

The passivated nanowire arrays have to be coated with a flexible polymer (e.g. PDMS) or with a solgel matrix (SiO₂), depending on the mechanical response in the following lift-off step (Fig. 6.2(e)).
6.3 Technical details

6.3.5 The contacts

So far, nanowire array solar cells use indium tin oxide (ITO) to contact the n-type InP nanowire tips, while the p-type contact can only be established via the p-type doped substrate. This limitation has hindered the development of nanowire array solar cells towards industrial application. The unresolved problem of contacting the p-type InP part, other than via the substrate, has prevented the realization of a substrate-less InP nanowire array solar cell based on a lift-off process.

During the course of this thesis, we were able to successfully contact p-type wurtzite InP and realized record performance single nanowire solar cells. Furthermore, we showed not only that the p-type part can be contacted via a metal layer (Chapter 4), but also via MoO$_x$, a high work function interfacial layer (Chapter 5). Besides realizing a high quality contact, those two findings add flexibility: nanowires can be grown either with a p-i-n or n-i-p doping profile. In both cases the transparent or the continuous metal contact can be applied before or after the lift-off step. This is a very flexible scheme and the final fabrication process is likely to be determined by mechanical properties of the exact employed materials.

Increasing efforts are made in the development of flexible TCOs, encompassing ITO with the addition of sparse metal nanowire networks.[170, 171] Therefore, we forecast that the continuous metalization on one side will eventually be replaced by a flexible TCO in the near future. This will allow the fabrication of flexible and transparent (for $E < E_g$) nanowire array solar cells, which will be an important step towards the realization of nanowire tandem foils.

![Figure 6.4: Electron and hole contacts. A continuous metal film is deposited first, followed by a transparent contact after the mechanical peel-off step. However, due to the flexibility of the contacting and the nanowire growth the geometry can be reversed.](image)
6.3.6 Mechanical peel-off

The mechanical peel-off step as shown in Figure 6.5 allows the targeted breakage of the nanowires at the bottom, just above the substrate, and has already been used to make solar cells and LEDs[170–174] Because this step relies on mechanical breakage and the lower adhesion of the polymer to the SiN mask than to the metalization on the top, it is substantially faster than chemical lift-off steps which include a waiting time of up to several hours for the chemicals to dissolve a release layer. This leads to a strong bottleneck for fabrication processes employing chemical lift-off procedures and can be circumvented by a mechanical peel-off step for our nanowire arrays.

We stress that while the other proposed fabrication steps can employ industrially proven processes, the mechanical peel-off step needs further development. Even though the feasibility has been proven in research labs, it needs to be translated to a roll-to-roll process, optimized for nanowire array thin-film mechanics.

6.3.7 Solar cell performance

The current power conversion efficiency record for InP nanowire array solar cells is 17.8%, obtained by top-down etching into a previously grown MOVPE layer.[13] In this thesis we have already shown that higher open-circuit voltages than for the record solar cells are achievable which brings efficiencies of 20% certainly within reach, especially considering further optimizations in terms of doping profile and contact selectivity. Further improvements in reduced surface recombination
are likely to eventually move InP nanowire solar cells beyond the 26% efficiency record obtained for silicon solar cells. Considering the band gap of the material (for wurtzite InP 1.43 eV) and Auger recombination, InP nanowire solar cells are limited to an efficiency limit very close to that of GaAs ($E_G = 1.42$ eV)\[17, 161\]. However, due to the a more gradual absorption onset at the band gap (wider Urbach-tail), the actual efficiency limit is reduced slightly compared to GaAs.\[187\]

Even though GaAs nanowire solar cells have a higher theoretical efficiency limit, the record of 15.3%, obtained by the VLS growth method, is below the one for InP nanowires. This has to be ascribed to differences in the growth method and the higher intrinsic surface recombination velocity in GaAs compared to InP.\[14\] This underlines the importance of proper surface passivation layers for future efficiency increases, as discussed in Chapter 5.

Another efficiency boost related to the device architecture can be expected with the removal of the high refractive index substrate. In the radiative efficiency limit the emission towards the substrate which provides a high density of optical states ($n^2 \times R_{rad}$) is a loss channel (Fig. 6.6(a)). If the emission can be reduced by removing the substrate, the radiative $V_{oc}$ will be higher (Fig. 6.6(b)). Furthermore, if a metal back contact is used as in the current version of the proposal, an increase in the directivity of the black body emission from the cell can be expected (Fig. 6.6(c)). The metal acts as a mirror and prevents emission to the bottom.\[20\]

**Figure 6.6: Substrate influence on the efficiency.** (a) Increased light emission from the nanowire into the highly doped and recombination active InP or GaAs substrate provides a large loss channel. (b) Removal of the high-index substrate reduces the emission towards the bottom. (c) An additional mirror improves the directivity by reflecting emitted light back through the array. Eventually the light can only escape into the upper hemisphere.
6.4 A techno-economic comparison to commercial GaAs solar cells

Starting from first principles, it is challenging to estimate the technical feasibility of a high-throughput and large scale production and especially the future cost of a fabrication process. Therefore, we chose commercial GaAs thin-film solar cells (28.8%) as a cost benchmark. The choice stems from the similarity of the growth process: the films are MOVPE grown GaAs with a thickness of 1-2 μm. A release layer that has been grown before the actual device layer is etched away in a subsequent chemical lift-off step. The result are defect-free high quality GaAs thin-films.

6.4.1 Technology

As already discussed in the introduction, the fabrication processes for the proposed nanowire solar cell and the GaAs thin-film solar cell are very similar.

The MOVPE nanowires and thin-films are grown on a monocrystalline substrate wafer (GaAs or InP). The major MOVPE part in terms of material usage, time and cost (see below) is the growth of the GaAs base layer (out of trimethylgallium and arsine) and of the low to intrinsically doped part of the InP nanowires (out of trimethylindum and phosphine). The nanowire geometry provides intrinsic nanophotonic effects, such as optical cross sections that extend beyond the geometrical ones. As a result, the required material for a layer that absorbs close to all of the light is roughly reduced by a factor of 5 for the case of nanowires (assuming a nanowire diameter of 200 nm, pitch of 500 nm and a length of 2 μm).

Furthermore, the SA-MOVPE growth of nanowires allows for growth rates that are 5-10 times faster, compared to growth rates for thin-films. For the rest of the comparison we assume the lower bound, that is a factor of 5.

Lastly, the lift-off steps differ strongly. The epitaxial GaAs thin-film and the substrate wafer are separated by a thin AlAs buffer layer, which is slowly etched away during the lift-off (~ 2h). In strong contrast, the mechanical peel-off step for the nanowire arrays can be substantially faster. Fig. 6.7 shows a summary of the technical comparison.
### 6.4 A techno-economic comparison to commercial GaAs solar cells

<table>
<thead>
<tr>
<th>Technology</th>
<th>Commercial GaAs thin-film solar cells (Alta Devices/ Nanoflex)</th>
<th>Proposed nanowire solar cells</th>
</tr>
</thead>
<tbody>
<tr>
<td>Efficiency</td>
<td>28.8% realized</td>
<td>not realized yet</td>
</tr>
<tr>
<td>Material Usage</td>
<td>- reusable substrate - epi thin-film requires low volume</td>
<td>- embedding in polymer (batch), fast mechanical peel-off</td>
</tr>
<tr>
<td>Growth Process</td>
<td>MOCVD</td>
<td>SA-MOVPE/VLS</td>
</tr>
<tr>
<td>Growth Speed</td>
<td>0.25 µm/min</td>
<td>~5 times of thin film (research reactors) (batch)</td>
</tr>
<tr>
<td>Lift-Off</td>
<td>- slow chemical dissolution of buffer layer</td>
<td>CSVT (III-V nanowires not realized yet)</td>
</tr>
<tr>
<td>Contacts</td>
<td>- doped layers - backside metalization supports handling and light trapping</td>
<td>- p-type InP contact feasible (this thesis)</td>
</tr>
<tr>
<td>Tandem applicable</td>
<td>- already utilized for high-efficiency tandems (expensive) - III-V on Si</td>
<td>- novel selective contacts (this thesis)</td>
</tr>
</tbody>
</table>

**Figure 6.7: Summary of technical comparison** An overview about the technical comparison between commercial thin-film GaAs and the proposed nanowire solar cell fabrication process, including different growth methods.

**6.4.2 Economics**

While the above comparison shows the technical feasibility, the area of economics is naturally tainted with more uncertainty. We use a cost model that has been developed by NREL for GaAs thin-film solar cells and adopt it for our proposed nanowire solar cell fabrication process.[175] As a result, we can pinpoint the most important differences and their impact of the production costs.

Figure 6.8 shows a summary of the cost analysis in a bar diagram for 29% efficient GaAs thin-film solar cells (blue), taken from [175], for 15% efficient InP nanowire cells (green), 15% and 29% efficient GaAs nanowire cells (orange and red). Also included are the estimated costs for top-down etching (vertical lines) and CSVT (horizontal lines). Material costs are shown in a bright color and depreciation, labor and maintenance costs in a dark color tone. The costs for the chemical GaAs thin-film lift-off step as stated by NREL are relatively uncertain.
(red question mark), because a particularly slow process step necessitates a large process parallelization which can lead to other complications, such as a large factory footprint.

We note, that the assumed efficiencies for our cost analysis have not been achieved for the considered growth methods, yet. However, efficiencies of around 14% and 15% have been achieved for VLS grown InP and GaAs nanowires, and 17.8% for top-down etched wires (into a MOVPE grown layer).[13, 14, 23] As we have shown in this thesis, SA-MOVPE nanowires have the potential to reach efficiencies of 20 – 30%, certainly with improved surface passivation and contact selectivity.

For the reusable substrate wafers, we forecast a cycle number that is equal to, if not higher than, the estimated ones for GaAs thin-film growth (~ 500). The substrate wafer is almost completely protected by the SiN layer for SA-MOVPE or CSVT. As a result, the occurring substrate costs are not decisive in our cost comparison, except for the growth of InP nanowire by SA-MOVPE. The latter is strongly affected by the higher costs of InP wafers, as discussed in the section for top-down etching. However, one approach to reduce the costs substantially and even realize tandem solar cells in the future is the growth of III-V nanowires on silicon.[188] While the lattice mismatch of many materials makes epitaxial and dislocation-free growth of
thin-films impossible, nanowires exhibit the advantage of strain relaxation through the nanowire sidewalls. Therefore, a vast expansion of the material space allows not only to vary the material of the nanowire itself, but also of the substrate.

While our cost calculation includes all the different growth steps, we focus in the following on the decisive cost factor: the absorber growth. The detailed information about the raw materials, substrate wafers, the lift-off and the contacts can be found in the supplemental information.

**Growth: MOVPE**

GaAs thin-films and SA-MOVPE nanowires rely on the same growth method, which is dominated by two major cost factors. The first one is related to the expensive reactors, which provide a highly homogeneous and controlled growth environment. The depreciation and labor costs associated with the MOVPE reactor are among the highest of the whole fabrication process. These costs have been obtained for a growth rate of $0.25 \mu m/min for GaAs thin-films. As mentioned above, we assume that the nanowire growth is approximately five time faster, based on comparisons for research reactors. Therefore, for a constant process output, up to five times less equipment is needed (neglecting reactor pumping, purging and venting times). This in turn leads to a substantial reduction in forecasted depreciation and labor costs of the MOVPE reactors for the nanowire growth compared to the GaAs thin-film growth.

Besides comparing the depreciation and labor costs, the material costs for the precursors have to be considered. Assuming the same precursor utilizations of 30% and 20% for the III-source (Ga/In) and the V-source (As/P), the required amounts of material will be reduced by a factor of 5 for the nanowire arrays. However, trimethylindium is about 10 times more expensive than trimethylgallium. The reason can mainly be found in the lower demand and could therefore substantially be reduced if demand would pick up, as is the case for the substrate wafers and the raw metals above. In contrast, arsine and phosphine are very similar (and low $\sim 0.04$$/W) in price.

Accounting for the different efficiencies (29% for the GaAs thin-film and 15% of the InP nanowire array), the lower depreciation and labor and higher material costs, we estimate the cost for the MOVPE step for the InP nanowire arrays to be $\sim 2.21$/W compared to $\sim 2.45$/W for GaAs thin-films. Assuming a drop in price for trimethylindium towards that of trimethylgallium the price will be as low $\sim 0.7$/W. Those costs are expected for 15% efficient GaAs nanowire solar cells.

**Growth: top-down etching**

For top-down etching, the estimated nanowire fabrication costs are calculated in a straightforward way. We assume a nanowire length of 2 $\mu m$ and another 1 $\mu m$ due to plasma damage of underlying substrate and the polishing steps. The 1 $\mu m$ buffer layer has to be etched away before the next patterning and growth step. Therefore,
3 $\mu$m of the initially 600 $\mu$m thick substrate wafer are consumed per nanowire array, that is 200 arrays can be obtained from one wafer. The 6” GaAs wafer can be cut into pseudo-square shape with a 133 cm$^2$ area (27% loss).[175] Taking into account the different conversion efficiencies and the illumination intensity of 100 mW/cm$^2$, the costs in $/W can be calculated. The InP wafers are currently a factor of four more expensive than GaAs wafers.[189] There are three main reasons for this difference, taking into account that the raw material prices of Ga and In are similar in price: (1) growing InP wafers requires higher pressures and temperatures than GaAs, (2) InP wafers are more brittle and hence lead to more accidental breakage during the handling and most importantly, (3) there is no commodity market for InP so far.[190] This is in strong contrast to GaAs, which is used in several applications, e.g. in power amplifiers of cell phones, and can therefore benefit from economies of scale and more developed and specialized process equipment. Obviously, increasing InP demand would drive the cost down in the long run, eventually substantially narrowing the price gap to GaAs. However, for top-down etching of GaAs nanowires, the cost estimates are rather optimistic, because we assumed the same prices for the substrate wafers as in the case of the epitaxial growth. While the wafers have a high crystalline quality, the impurity content for most available GaAs wafers is completely unsuited for the use as photovoltaic absorber (see also 6.3.2). Therefore, a substantial increase in price can be expected.

Another issue is the use of one homogeneously doped bulk wafer for the fabrication of hundreds of nanowire arrays. Unless selective contact layers or doping via post-growth annealing are employed, no practical solar cell can be fabricated. Keeping those uncertainties in mind, the cost of the etch process for a hypothetical 29% GaAs nanowire solar cell are around 0.25 $/W and around 2 $/W for 15% InP nanowire solar cells, due to the lower efficiency and higher substrate costs. The costs of the etch step itself are rather low. Plasma etching is an industrially proven technology, e.g. for the edge isolation of silicon solar cells. Therefore, the cost for the equipment are estimated to be small, at 0.02 $/W for the 29% GaAs nanowire array.[191]

**Growth: CSVT**

CSVT has been developed in 1963, but its potential has only recently been demonstrated.[185, 192, 193] Therefore, the potential costs of industrial fabrication can only be roughly estimated. The major difference for CSVT growth compared to the other methods are the material and the reactor costs. Instead of using expensive (and toxic) precursors, such as trimethylgallium (\(\sim 2.5 \$/g\)) and arsine (\(\sim 0.4 \$/g\)), CSVT can directly utilize high purity gallium (\(\sim 0.5 \$/g\)) and arsenic (\(\sim 0.1 \$/g\)). Additionally, a CSVT reactor is very similar to reactors employed for the fabrication of CdTe solar cells. Especially the close space sublimation (CSS) and the vapor transport deposition methods have strong similarities to CSVT. Considering that the growth is only a fraction of the module manufacturing process, the costs for the CdTe deposition method are at about 0.06 $/W for an efficiency of 16%.[194]
6.5 Markets and competitors for nanowire photovoltaics

If the assumption holds, that CSVT nanowire solar cells can be grown directly out of Ga and As with a very similar process as employed for current CdTe manufacturing, the overall costs for the growth step are around 0.2 $/W for a hypothetical 15% efficient nanowire solar cell and only 0.1 $/W for a 29% cell.

Overall absolute and relative costs

Adding up all the costs, including final edge isolation, testing and sorting (~ 0.05 $/W) the 29% efficient GaAs thin-film can be produced at about ~ 3.3 $/W. [175] Compared to reference [175] we assume the same costs for the front and the back side metalization. For the scenario a 500 MWp U.S. facility with a 95% yield and 5 year equipment depreciation time have been considered (mid-term single-junction case in[175]). For a nanowire solar cell facility with the same assumption, a 29% efficient SA-MOVPE GaAs nanowire solar cell could be produced at a price of about ~ 0.88 $/W. For a SA-MOVPE InP nanowire solar cell with an efficiency of 15%, the total cost would add up to about ~ 4.95 $/W, strongly affected by the high wafer and precursor prices compared to GaAs.

For top-down etching, the 15% InP nanowire solar cell could be produced at ~ 3.43 $/W and the 29% GaAs nanowire solar cell at ~ 0.78 $/W.

For CSVT, the 15% GaAs nanowire solar cell could be produced at ~ 1 $/W and the 29% GaAs nanowire solar cell at only ~ 0.5 $/W.

The absolute cost estimates have a high uncertainty, due to undisclosed information. As Alta Devices has developed their fabrication process over several years, it is almost certain that lower costs are reached. Therefore, we show in Figure 6.9 the relative costs of the MOVPE nanowire solar cell to the thin-film GaAs fabrication. The cost difference between the different GaAs technologies is largely due to the large differences for the MOVPE process step, with nanowires using roughly 5 times less material and a having a growth rate that is about 5 times higher than for thin-films. For InP the high costs for wafers and precursors relative to GaAs are a high obstacle for an economic production, but could be reduced substantially if demand would pick up. We conclude that the nanowire solar cell fabrication is not only technically but also economically a highly promising proposal.

6.5 Markets and competitors for nanowire photovoltaics

6.5.1 The perseverance of the silicon module

Flexible InP or GaAs nanowire solar cells are likely to exceed the efficiency records of silicon solar cells due to their higher Shockley-Queisser efficiency limits and intrinsic nanophotonic effects in the future. Furthermore, they have the added benefit of being light weight and potentially flexible, important points when it comes to shipping and installation.
However, the maturity of the established production processes and the economies of scale of the wafer-based silicon solar cell technology create large obstacles for new technologies to enter the market. Currently, solar module prices are as low as 0.57$/Wp with further substantial cost reductions expected in the upcoming years. Improvements on the module efficiency level, optimized processes and further economies of scale are the main driver of this continuing decrease of solar panel productions costs over the years. As a result, the cost of solar energy for fully installed systems is predicted to fall below 1 $/W by 2020 and down to 0.3–0.7 $/W by 2050.[16] As a comparison, in Chapter 6.4.2 we have argued that the MOVPE step alone, will initially be more expensive than the whole silicon solar cell fabrication and installation together, even for a GaAs nanowire geometry. This clearly shows that in the initial development stages and without economies of scale, such new technologies are unable to compete on the same market as the established silicon solar module. Unless a new solar cell technology is developed that can be fabricated with substantially cheaper processes, such as solely with chemical batch processes, the predominance of the silicon solar cell module is to be expected in the near and midterm future.

Nevertheless, new technologies can successfully be commercialized if they do not compete, at least initially, on the same market as the silicon solar module.

### 6.5.2 Flexibility, light-weight and efficiency

Unmanned, lightweight systems, such as aerial drones, consumer devices, such as smart phones, computers, clothes, watches, and cars are providing a large market for new technologies where $/W is not the most important figure of merit.
6.5 Markets and competitors for nanowire photovoltaics

Figure 6.10: Applications for light-weight solar cells. One of the largest emerging markets for efficient, flexible and light-weight solar cells is the one of e-mobility.[195]

Other numerous applications emerge via the upcoming internet of things (IOT), a term that describes the increasing connectivity of a wide range of devices to the internet.[196] The IOT are forecasted to become a multi-billion dollar market in the near future, mainly driven by the continuous decreasing costs of computer chips and data storage and transmission costs. The same holds for the market of e-mobility, with recently almost all major car companies announcing major developments and even upcoming product introductions.[197] This is in stark contrast to even ten years ago, where light weight and flexible solar cells were only envisioned for small and sometimes exotic "niche" markets, such as for remote power supply of weather stations. If the current economic forecasts hold, we are just at the beginning of the emergence of two multi-billion dollar markets.

If weight, flexibility and high-efficiencies are the major requirements for applications, great opportunities are arising for new solar cell technologies, that can provide those functionalities. In the long term, such technologies can then try to compete against the existing silicon solar cell when maturity of processes and economies of scale can impact the $/W figure substantially.

6.5.3 Competitors

Flexible and especially light-weight solar cells are not a new concept per se. The advantages of such a technology in terms of transport, installation, module costs and application space have spurred continuous interest in this promising device architecture. So far, flexible and light-weight solar cells have been realized for organic and amorphous silicon solar cells (~10%), CdTe (~16%), CIGS (~23%) and GaAs thin-films (~29%)[17, 198, 199].

Commercial organic solar cells can be produced very cheaply via solution-based methods but are currently limited in efficiency and stability. For amorphous
6 A nanowire solar cell fabrication process

Flexible CdTe and CIGS solar cells can provide a stable performance in the low to mid-efficiency range and are therefore main competitors to our proposed solar cell technology in the initial stages. For flexible CdTe films, a safe and leakage-free containment of the material has to be found, especially if the technology is to be employed in close proximity to the end-user.

Alta Devices thin-film GaAs solar cells are the most efficient (28.8%) single-junction solar cells available on the market and they have the benefit of being lightweight and flexible. Even though they provide all those benefits, they are currently too expensive to compete against the silicon solar cell module for large scale primary electricity production, as discussed above.

As for the proposed nanowire solar cells, one has to distinguish between the current status as in our proposal and future opportunities. Material developments are likely to increase the conversion efficiencies towards the values achieved for GaAs thin-films and process optimizations and economies of scale we lead to substantial cost reduction. Furthermore, full flexibility and even high transparency (for $E < E_g$) through the developments of new flexible TCOs are going to be important milestones for this technology.

Therefore, the targeted markets for CIGS, CdTe and GaAs thin-films solar cells are similar to the proposed nanowire solar cell technology. We envision nanowire solar cells that can be produced cheaper but are at least initially lower in performance (20% vs. 28%) than GaAs thin-film solar cells. As a result, we see a large market that can be accessed by nanowire solar cells, simplified, whenever lightweight and mid-range efficiency are more important than a high-end performance. Therefore, nanowire solar cells will at least initially compete against CIGS and CdTe modules about the same market share.

In the following we will argue that our flexible fabrication process allows to develop nanowire tandem solar cells to eventually reach substantially higher conversion efficiencies and thereby larger market shares.

6.6 Innovation by flexibility

6.6.1 A traditional fabrication process

Traditional mono- and multicrystalline silicon, amorphous silicon, CIGS and CdTe solar cells have all a very common characteristic, in fact it is so common that it is barely discussed; they all rely on fabrication processes that are highly specialized for the employed semiconductors. The specific semiconductor growth process and the resulting geometry impose strong limitations on the whole fabrication process. The reason for that can be found in the large variety of material properties and hence requirements in terms of crystal growth, required semiconductor thickness, bulk- and surface defect passivation, electrical contacting and many more. This
setup adds to the unavoidable dilemma for traditional solar cell manufacturers.

Initially, for a newly commercialized solar cell technology, many companies can advance their products in terms of technical performance improvements (e.g. improving the efficiency or stability of their solar cells). Usually, technical know-how about certain details is even the main driving-force for technology start-up companies. However, after some time, fundamental physical limitations especially in terms of efficiency (e.g. Shockley-Queisser-Limit) and practical material limitations (e.g. limited carrier mobilities) change the rate and hence increase the costs at which improvements can be obtained. This fact becomes evident in Fig. 1.1 in Chapter 1, which shows the efficiency improvements of different solar cell technologies over time. The characteristic logarithmic trend of many mature solar cell technologies is pronounced. Notably, for mono- and multicrystalline silicon solar cells, which make up over 90% of all fabricated and installed solar cells, hardly any substantial efficiency improvements have been obtained over the last 20 years on the cell level (average module efficiencies increased substantially). At such developmental stages, a company that would aim to mainly improve the efficiency of their solar cells would have to invest enormous amounts of money in their R&D department. Taking into account the nature of research, that is the large uncertainty that comes with it, a silicon solar cell company is better advised to conduct its main efforts in other areas. This is why even technology companies focus with increasing maturity mainly on cost reductions driven by economies of scale and process improvements (speed, reliability, material consumption aso.). Consequently, the reason why the fabrication costs for silicon solar modules continued to drop in the past, even though the single cell efficiency barely improved, can mainly be attributed to economies of scale, more optimized process equipment and optimizations on the module level (leading to lower efficiency losses between cell and module). In other words: solar cell companies have installed a large amount of highly specialized equipment in ever increasing factory sizes. Neglecting internationally different environmental protection standards, labor rights and standards of living, silicon solar cell fabrication today is more efficient in terms of resources (energy, materials, labor) than 20 years ago. Without those developments the whole solar energy sector would still be in its infancy.

While it seems of utmost importance, if not a necessity, for a new technology to reach this stage of development, there comes a fundamental downside with it. Companies become less flexible and less likely to achieve breakthrough innovations the larger and older they get. It has been observed that companies increase the rate of patenting with age, however those patents are highly focused on a specific area of expertise and show a strong declining rate of external citations. In other words, companies show an increasing divergence between organizational competence and current environmental demands with age.[201] To maintain oversight and productivity, large companies have to rely on more bureaucracy and management layers per capita, standardizing internal procedures and specializing on a specific area of expertise. Thereby, they inevitably create barriers for breakthrough approaches.
However, not only the work force and its organization, but also the large amounts of equipment become highly specialized and optimized for the current manufacturing process. This in turn reduces the rate of innovation, as the existing fixed fabrication process does not allow for ground-breaking innovation. The technical improvements are only incremental. Single process steps can sometimes be replaced by more material, labor, time or energy efficient versions, but the end product stays effectively the same, e.g. a single junction silicon solar cell. Often the only way for large companies to stay truly innovative is to completely replace their product line, that is to sell or outsource the current technology and acquire new expertise and equipment through acquisitions and mergers.

To summarize, companies have to deal with large costs of a highly specialized workforce which is inflexible due to bureaucratic barriers and organizational structures. Additionally, the current technological setup strongly limits their phase space of explorations. Much attention is currently spend on ways to improve innovation and flexibility in a large work force by means of new organizational structures and incentives. In contrast, the impact of the nature of a specific fabrication processes on future innovations is not often discussed, especially not in the field of solar energy.

In the following, we will argue that our proposed fabrication process for nanowire solar cells is of very different nature, allowing a hypothetical company to stay more agile and innovative even if process maturity and large scale installations of manufacturing lines are realized.

### 6.6.2 A flexible fabrication process

Our proposed fabrication process is inherently different from the traditional manufacturing lines, as shown in Figure 6.11. It is highly adaptable and flexible and not limited to one specific semiconductor. It allows not only for the fabrication of nanowire arrays made out of InP, but also the fabrication of nanowire and even microwire arrays out of many other materials, such as GaAs, GaP, GaInP, GaN and many more. In fact, even LED panels can be envisioned as product portfolio extensions. To reach such a high level of flexibility for a solar cell fabrication process, three basic properties have to be provided by the process equipment:

**Flexible growth, flexible handling and flexible contacting of the semiconductor.**

For our process those features emerge because it exploits the intrinsic advantages of nanowires compared to thin-films; fast and flexible growth, reduced material consumption, fast mechanical peel-off and intrinsic anti-reflection properties.

The flexible growth is initially provided by the MOVPE growth system and the fact that nanowires have less stringent requirements for epitaxial growth than traditional thin-films. Together with a large range of available substrates many different semiconductors can be grown, as discussed in Chapter 6.3.2. However, the whole process is even more flexible in that it allows to replace the MOVPE growth steps with other methods, as discussed above. If CSVT growth of nanowires reaches maturity, the more expensive MOPVE equipment can be replaced, while the rest
of the process line only needs smaller adjustments. The mechanical peel-off, subsequent handling and the final module assembly are all largely indifferent to the exact semiconductor used. Since the nanowires are embedded in a polymer or glass matrix, the mechanics are largely determined by the latter.

Last but not least, the deposition equipment used to deposit the TCOs and the metal contact fingers can be used for a large range of materials. The ongoing development of flexible and high and low work function TCOs for carrier selective contacts, adds further simplicity and flexibility to the fabrication process.

Obviously, with every material change, the different fabrication processes have to be fine tuned, especially the growth step. However, the fact that different semiconductor solar cells can be grown at all with the same process line and that the specific growth method can even be switched out if cheaper alternatives are available (e.g. CSVT), allows a company to stay highly flexible. This is of prime importance, especially for a solar cell company.

Compared to many other fields, with unknown or less well-defined limitations, the well-known and well-defined physical limitations for solar cells create inevitable performance boundaries. The Shockley-Queisser and other material related limits, do not allow the continuous development in terms of higher conversion efficiencies with a set, given semiconductor. A company that can break through this limitation by e.g. developing a tandem solar cell, in parallel to the
fabrication of single-junction solar cells, has a tremendous advantage.

We want to stress that we do not underestimate the importance of organizational structures, bureaucracy and other workforce related factors on the rate of innovation. As the innovative process starts on the human level, organizational structures that allow and incentivize the exploration of new approaches are the first step towards enabling breakthrough innovation. However, without technical abilities to turn those ideas into physical realities, innovation inevitable has to cease.

6.7 Conclusion and a technological roadmap

We have shown that the nanowire fabrication process is not only technologically but also economically feasible. The crucial fabrication steps are the utilization of a reuseable substrate, coupled to an epitaxial MOVPE growth and mechanical peel-off step. The proposed fabrication process is very similar to the ones employed for thin-film GaAs solar cells, with the major differences being a faster and more material efficient MOVPE growth and a faster mechanical peel-off step. However, we do not limit ourselves to the MOVPE growth method, but include other nanowire fabrication methods, too. Besides the technical aspects of the fabrication process, we also compare the economical ones with commercial thin-film GaAs solar cells. We are able to show that nanowire solar cells can potentially be fabricated cheaper. Based on our techno-economic analysis we are able discuss future market opportunities and competitors.

Besides this positive outlook for commercial nanowire solar cells, we arrive at another important insight; the proposed fabrication process for nanowire solar cells is highly flexible. Figure 6.12 shows a simplified roadmap for the technological developments and future markets of the respective technologies. As a result of the

Roadmap of nanowire solar cells

![Figure 6.12: A Technological roadmap for nanowire solar cells.](image-url)
flexibility of the manufacturing line, large synergies are created with each subsequent portfolio extension. GaAs nanowire solar cells would benefit from the prior realized substrate recycling, the peel-off process and the contacting and handling steps for InP nanowires. As a result, GaAs nanowire solar cells could enter commercialization after improvements in surface passivation and selective contacts, skipping phase 1-3. Eventually, further process optimizations and economies of scale could make an all nanowire or nanowire-on-silicon tandem solar cell feasible, which could directly compete against the existing silicon module.

6.8 Supplemental information to cost comparison

Raw materials

Between the years 2011 - 2015, the annual average prices for gallium ranged between 300 - 700 $/kg and for indium between 540 - 700 $/kg. The fact that gallium and indium can only be found in trace amounts as gallium and indium compounds in bauxite and zinc ores explains the tendencies towards higher prices. Further adding volatility to the prices, gallium and indium extraction are heavily dependent on aluminum, zinc and lead extraction and demand, because of the small amounts present in the deposits. For comparison, silicon is extracted from highly abundant SiO\textsubscript{2} which resulted in average annual prices for metallurgical-grade silicon of 2.6 - 3.5 $/kg in the years 2011-2015. Even though the prices are similar, the demand for indium, which does not have its own commodity market, is substantially lower than for gallium. As an example, while the US economy completely relies on imports for its Ga and In demand, it imported around 32,000 kg Ga compared to only 145 kg In in the year of 2015. Therefore, if In demand picks up in the future and a commodity market could be established, the prices of In will almost certainly go down.

Reusable substrate wafer

For MOVPE growth of thin-films and nanowires, as well as the CSVT growth and the top-down etching approach, the growth of the III-V substrate wafer has to be considered in the cost comparison. To purify the respective materials and grow single crystalline wafers the VGF or LE-CZ growth method can be employed (6.3.2).

As mentioned and explained above, InP wafers are currently a factor of four more expensive than GaAs wafers.[189] Adding to the costs for the substrate wafer are the costs for the SiN coating and the patterning step for SA-MOVPE and CSVT. However, we forecast a cycle number that is equal to, if not higher than, the estimated ones for GaAs thin-film growth (~ 500). The substrate wafer is almost completely protected by the SiN layer. After the peel-off a small amount of material that has been grown by MOVPE but not been removed can be etched away. Therefore, if the etching time is adjusted carefully, no additional material is removed from the substrate wafer. Therefore, the additional costs are not substantial.
Accounting for the differences in efficiency (29% for the GaAs thin-film and 15% of the InP nanowire array), and the factor of four in material costs of InP compared to GaAs wafers, we estimate a substrate cost of ~1.09 $/W for MOVPE and CSVT InP nanowires. For GaAs thin-films (~29%) and GaAs nanowires (~29%), either grown by SA-MOVPE or CSVT, the costs are ~0.16 $/W. The costs for the top-down etching approach are discussed in growth section 6.4.2.

**Chemical vs. mechanical peel-off**

The mechanical lift-off step does not contain material but only depreciation, labor and maintenance costs associated with the equipment. The mechanical lift-off tool would be similar in terms of mechanics than the lift-off tool for the GaAs thin-films, however without chemical baths and much faster process speed. Therefore, we assume the same costs for the equipment, adjusted for the initially lower efficiency of the first generation of InP nanowire solar cells.

**Contacts**

The costs for the back side and front side metalization are the same for GaAs thin-film solar cells and the nanowire solar cells and only need to be adjusted for the different efficiencies.[175] In the case of the nanowires solar cells, additional costs occur because of the need for a TCO on the front side. The material and deposition costs for a standard TCO amount to about 10 $/m$^2$, which translates to about 0.05 $/W for a 20% efficient solar cell.[202]

In the costs for the contacts we also included the costs of the MOVPE growth of the doped regions, contacting and buffer layers for the front and the back contacts. Those amount to 0.16 $/W and 0.25 $/W for the thin-film, respectively. For the nanowires we only included the growth of the BSF and emitter steps which amounts to in total 0.2 $/W for the 15% GaAs nanowire array (and respectively for the other efficiencies). For the GaAs thin-films additional costs arise due to the contact layer etch step, that is 0.06 $/W. In total the contacting costs for the GaAs thin-film solar cells amount to about 0.67 $/W and to 0.52 $/W for the 15% GaAs nanowire solar cells (and respectively for the other efficiencies). We assumed roughly the same costs for back and front side metalization for GaAs thin-films (compared to [175]).

The MOVPE contacting steps would have to be replaced for CSVT or top-down etching. For both, CSVT and top-down etching we assume the contacting costs to be essentially determined by the ITO deposition and metalization, in total 0.34 $/W ($\eta = 15\%$) for both sides. The growth steps of the doped layers are negligible for CSVT, because the growth of the main absorber is already very low. The profound cost difference of the technologies occurs because of the absorber growth steps, as shown in Fig. 6.8 (and the substrate for InP nanowires).
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Summary

This thesis deals with material interfaces in nanoscale photovoltaics. Interfaces between the absorbing semiconductor and the ambient, a dielectric, metal, metal oxide or another semiconductor are all of utmost importance for an efficient solar cell. While the optical properties are largely unaffected by a few nanometer thin layer, the electronic properties can change tremendously: electrical passivation of surface defects or establishing contact selectivity can turn a piece of black rock with two metal leads into a highly efficient solar cell.

When moving from macro- to nanoscale semiconductors, highly useful properties emerge compared to wafer-based or even thin-film semiconductors. Most importantly, not only directly incident but also adjacent light can be absorbed by the single nanoscale constituents. As a result, the same amount of light can be absorbed with an array of single nanoscale structures with much empty space in between, as with a continuous thin-film. This effect leads to largely reduced material consumption and, depending on the growth methods, even to a faster growth process for a fully absorbing layer. The empty space in between the nanoscale elements can be filled with a flexible glass or polymer layer, that allows to mechanically peel off the structures from their growth template. Additionally, the nanostructured semiconductor elements do not need any additional anti-reflection coating, as do wafer-based or thin-film solar cells. While those properties are enormously beneficial for photovoltaics, another feature creates a tremendous challenge: by nanostructuring semiconductors, the surface-to-volume ratio becomes much larger compared to thin-film or wafer-based solar cells. As a result, the influence of surface and interface properties on the overall performance of the nanoscale photovoltaic elements increases substantially. In this thesis, nanowires are therefore chosen as a highly sensitive platform to study the impact of those interface properties on the overall photovoltaic performance. Based on our findings we to propose device designs for more efficient practical nanowire array solar cells.

In Chapter 2, we study the photovoltaic performance of metal-semiconductor core-shell nanowires. This type of nanowire has theoretically been predicted to
provide outstanding optical absorption in the semiconductor shell and a short required minority carrier diffusion length, with the added benefit of direct carrier extraction via the metal core, potentially reducing the series resistance of the device as compared to core-shell geometries that only consist of semiconductor nanowires. We show that even though the semiconductor shell grows epitaxially of the metal core, that is the interface is highly ordered, charge carrier extraction barriers and enhanced interfacial recombination can be observed.

In **Chapter 3**, we study a metal-insulator-semiconductor solar cell, that mitigates the direct and detrimental contact between a metal and a semiconductor by utilizing a thin passivating and insulating interlayer. We show highly homogenous charge carrier extraction and are able to fabricate devices with a power conversion efficiency of 11% (after correction, $V_{oc} = 560$ mV, $J_{sc} = 33$ mA/cm$^2$). For a metal-insulator-semiconductor solar cell, the $V_{oc}$ depends strongly on the work function difference between the metal and the semiconductor. We argue that the presence of a charge-neutrality-level at the metal-dielectric interface is likely to lower the metal work function from its vacuum value and hence negatively impacts the measured $V_{oc}$. Furthermore, we introduce a novel structure, nanopyramids integrated in between the metal nanowire network, that allow to substantially reduce reflection and potentially increase the short-circuit current densities.

In **Chapter 4**, we focus on single InP nanowires. Those nanoscale structures have a higher optical than geometrical absorption cross section and while this property can be of great use, as outlined above, it complicates the characterization of single nanoscale devices. A priori the absorption cross section is unknown and additionally changing with wavelength, hence it is unclear how much of the incident light directly interacts with the single nanoscale device. This prevents quantification of the different conversion steps and hence loss mechanisms, but also the quantification of the absolute radiative limit $V_{oc}^{rad}$. For this thesis it is of great importance to quantify non-radiative recombination and non-ideal contacts. To that end, we introduce a new measurement technique, integrating sphere microscopy, to accurately quantify the remaining loss mechanisms. We measure the internal quantum efficiency (IQE), the photoluminescence quantum yield (PLQY) and the nanoscale equivalent of the EQE (external quantum efficiency) of a single record nanowire device for the first time. With those measurements we are able to quantify the impact of non-ideal contacts and non-radiative recombination and understand how much can be gained by reducing those loss mechanisms.

In **Chapter 5**, we focus on the interface properties of those InP nanowires. We study the device performance of contacted and masked single nanowire devices before and after HF, MoO$_x$ and sulfur treatment. We show improved surface passivation and improved carrier selectivity for the different treatments and in particular pay attention to the effect of Fermi-level pinning on those properties. By introducing the interfacial layer MoO$_x$ to nanowire solar cells, we can increase the open-circuit voltage by up to 335 mV, from 500 mV to 835 mV.

In **Chapter 6**, we explore valorization opportunities that emerge from our insights of the preceding chapters. In the previous chapters we have shown how to
contact single p-type InP nanowires and how to increase their contact selectivity to make highly performing devices, which has been an unsolved issue in the past. Translating those insights to array solar cells allows us to propose a manufacturing line which exploits the intrinsic advantages that emerge from the nanowire geometry compared to thin-films; faster growth speeds, reduced material consumption, fast mechanical peel-off and intrinsic anti-reflection properties. We perform a techno-economic analysis on our proposed fabrication process by comparing the technology to already existing and very similar manufacturing lines for thin-film GaAs solar cells. Furthermore, we underline the highly flexibility of the process line which is not limited to one growth method, let alone semiconductor. We argue that this can have a substantial impact on the rate of innovation in a hypothetical company invested into this process.

So far nanowire solar cells are limited to efficiencies < 20%. Improvements in the past have mainly been achieved by improving the optics, that is the absorption has been enhanced due to an optimized array design (width, length, tapering and array pitch), and because of improved nanowire fabrication methods (crystal growth, etching). This thesis turns the attention towards the electronics, in particular novel selective contacts and passivation layers. With those two major contributions nanowire solar cells have the chance to finally close the gap between their practical and thermodynamic efficiency limits and to finally become a technological and economical reality.
Samenvatting

Dit proefschrift betreft grensvlakken tussen materialen in zonnecellen op nano-schaal. Grensvlakken tussen de absorberende halfgeleider en bijvoorbeeld lucht, een diëlektricum, een metaal, een metaaloxide, of een andere halfgeleider, zijn van groot belang voor efficiënte zonnecellen. Hoewel de optische eigenschappen van een zonnecel nauwelijks veranderen door een laag van een paar nanometer, kunnen de elektronische eigenschappen juist sterk beïnvloed worden. Het passiveren van oppervlaktedefecten of het creëren van selectieve contacten maakt het verschil: wat in feite een zwarte steen met metalen contacten was, verandert zo in een erg efficiënte zonnecel.

In halfgeleiders op nanoschaal zijn er zeer bruikbare optische fenomenen, die in macroscopische halfgeleiders niet voorkomen. Het meest bijzondere voorbeeld is dat nanostructuren meer licht kunnen absorberen dan dat ze direct raakt. Als een direct gevolg kan een periodieke structuur van nanodeeltjes, met veel lege ruimte daartussenin, evenveel licht absorberen als een continue laag. Daardoor kunnen zonnecellen gefabriceerd worden van veel minder halfgeleider, en, afhankelijk van de methode, ook sneller. De lege ruimte tussen de nanodeeltjes kan gevuld worden met een flexibele glassoort of een polymeer, waarmee de laag met nanodeeltjes van het originele substraat gepeld kan worden. Daarnaast is voor zonnecellen gebaseerd op dit soort nanodeeltjes geen extra antireflectieve laag nodig, in tegenstelling tot voor normale zonnecellen. Nanostructuren bieden dus enorme voordelen voor zonnecellen, maar er zijn ook grote uitdagingen. De verhouding van oppervlakte tot volume is met name veel groter dan in vergelijkbare zonnecellen gemaakt van dunne films of wafers, en als gevolg spelen oppervlaktes en grensvlakken dus een veel grotere rol. In dit proefschrift gebruiken wij nanodraden als een hoogst sensitief platform om de rol van oppervlaktes en grensvlakken in zonnecellen op nanoschaal te onderzoeken. Op basis van onze vondsten stellen wij ook ontwerpen voor die kunnen leiden tot nanodraadzonnecellen met hogere efficiëntie.

In hoofdstuk 2 onderzoeken we de fotovoltaïsche eigenschappen van nanodraden met een kern van metaal en een schil van halfgeleider. Het is eerder theoretisch aangetoond dat deze metaal-halfgeleider nanodraden licht zeer
sterk kunnen absorberen in een heel dunne schil van halfgeleider. Doordat de metalen kern ook als elektrode kan fungeren, is daardoor maar een hele korte diffusielengte nodig, en kan ook de serieweerstand stukken lager zijn dan in nanodraden die helemaal van halfgeleider zijn gemaakt. We laten zien dat, hoewel de halfgeleiderschil zich als een epitaxiale laag op de metalen kern, er toch extractiebarrières voor de ladingsdragers zijn. Er vindt daardoor verhoogde recombinatie plaats.

In hoofdstuk 3 onderzoeken we een metaal-isolator-halfgeleider zonnecel, waarin het nadelige directe contact tussen het metaal en de halfgeleider vermeden wordt door een dunne isolerende en passiverende laag tussen beiden te plaatsen. Als contactgeometrie gebruiken wij een netwerk van metalen nanodraden. We demonstreren een zeer homogene extractie van ladingsdragers, en hebben een zonnecel gemaakt met een efficiëntie van 11%. Na correctie had deze zonnecel een $V_{oc} = 560$ mV en een $J_{sc} = 33$ mA/cm$^2$.

In metaal-isolator-halfgeleider zonnecellen hangt de $V_{oc}$ sterk af van het verschil in uittreearbeid tussen het metaal en de halfgeleider. Hoewel het directe contact tussen het metaal en de halfgeleider nu vermeden is, ondervinden wij dat de $V_{oc}$ nu negatief beïnvloed wordt door een ladingsneutraliteitsniveau. Daarnaast laten wij zijn dat ons nanodraadnetwerk gecombineerd kan worden geïnverteerde pyramides tussen de contactvingers, wat leidt tot sterk gereduceerde reflectie en daarom mogelijk tot hogere stroomdichtheden.

In hoofdstuk 4 richten we ons op individuele InP nanodraadzonnecellen. Deze nanodraden kunnen een grotere absorptiedoorsnede hebben dan hun geometrische doorsneden, zoals hierboven al genoemd. Hoewel deze eigenschap dus erg nuttig kan zijn, maakt het karakterisatie van zulke zonnecellen een stuk gecompliceerder. A priori is de absorptiedoorsnede onbekend en afhankelijk van de golfveldweergave van het licht, en het is dus onduidelijk hoeveel van het inkomende licht direct reageert met de nanodraad zonnecel. Dit maakt het kwantificeren van de efficiëntie van de verschillende stappen in het conversieproces onmogelijk, en dus ook van de verliesmechanismes. Daarnaast kan de ultieme thermodynamische limiet voor het voltage, $V_{oc}^{rad}$, niet bepaald worden, en in deze dissertatie spelen al deze factoren juist een zeer belangrijke rol. Daartoe introduceren wij een nieuwe meettechniek, integrerende bol microscopie, waarmee we de verschillende verliesmechanismes in kaart kunnen brengen. We meten de interne kwantum efficiëntie en fotoluminescentie kwantum efficiëntie voor de eerste keer, en definiëren en bepalen een equivalent voor de externe kwantum efficiëntie op nanoschaal. Met behulp van deze metingen kunnen we kwantificeren wat het effect is van de contactkwaliteit en niet-stralende recombinatie, en krijgen we inzicht in hoeveel deze nanodraadzonnecel verbeterd kan worden door deze verliesmechanismes te elimineren.

In hoofdstuk 5 onderzoeken we de grensvlakteigenschappen van deze InP nanodraden nader. We bestuderen het gedrag van deze zonnecellen voor en na behandeling met HF, MoO$_3$ en zwavel. We demonstreren verbeterde grensvlakpassivatie en ladingsdragerselectiviteit door deze verschillende behandelingen, en laten in
het bijzonder op hoe deze behandelingen het Fermi-niveau vastleggen, en hoe dat de eigenschappen van de zonnecel beinvloedt. Door een grensvlaklaag van MoO$_x$ toe te voegen kunnen we de $V_{oc}$ met 335 mV verhogen, van 500 mV naar 835 mV.

In hoofdstuk 6 verkennen wij valorisatiekansen die voortkomen uit inzichten verkregen op basis van de voorgaande hoofdstukken. In die hoofdstukken hebben wij laten zien hoe elektrodes gevormd kunnen worden op individuele positief gedoteerde InP nanodraden, en hoe de selectiviteit van die elektrodes verbeterd kan worden. Dit was een onopgelost probleem, en als gevolg kunnen nu hoogefficiënte nanodraad zonnecellen gemaakt worden. Door deze nieuwe inzichten te vertalen naar periodieke roosters van nanodraadzonnecellen, kunnen we een nieuwe fabricageproces voorstellen. Dit proces benut de intrinsieke voordelen die de nanodraadgeometrie met zich meebrengt ten opzichte van dunne films: kortere depositietijden, verminderde materiaalconsumptie, snel mechanisch afpellen van de laag met nanodraden en bijna ideale antireflectie-eigenschappen. We onderne- men een techno-economische analyse van ons fabricageproces door de methode te vergelijken met bestaande en vergelijkbare technieken voor GaAs zonnecellen. We benadrukken de flexibiliteit van de methode, die niet tot een enkele depositionsmethode gelimiteerd is, laat staan tot één halfgeleider. Onze voorgestelde methode kan grote invloed hebben op bedrijven in deze sector.

Tot dusver zijn efficiënties van nanodraadzonnecellen gelimiteerd tot <20%. Verbeteringen in het verleden hebben vooral te maken gehad met optica, door bijvoorbeeld verbeterde absorptie van licht, of door verbeteringen in fabricagemethoden (zoals kristallisatie en etsen). In dit proefschrift richten wij ons op de elektronische eigenschappen, met nadruk op vernieuwende selectieve elektrodes en passiverende lagen. Door deze twee belangrijke bijdragen hebben nanodraadzonnecellen de kans om het gat te dichten tussen de praktische en limiterende efficiën- ties, en om eindelijk een technologische en economische realiteit te worden.
List of publications

This thesis is based on the following publications:

- **Au-Cu₂O core-shell nanowire photovoltaics**
  S.Z. Oener, S.A. Mann, B. Sciacca, C. Sfiligoj, J. Hoang, E.C. Garnett,

- **Metal-insulator-semiconductor nanowire network solar cells**
  S.Z. Oener, J. van de Groep, B. Macco, P.C.P. Bronsveld, W.M.M. Kessels,

- **Quantifying losses and thermodynamic limits in nanophotonic solar cells**
  S.A. Mann,* S.Z. Oener,* A. Cavalli, J.E.M. Haverkort, E.P.A.M. Bakkers, E.C.
  *equal contribution. (Chapter 4)

- **Carrier selective contacts for nanowire solar cells**
  preparation). (Chapter 5)

- **A techno-economic case study for nanowire solar cells**

Other publications by the author:

- **Infrared birefringence imaging of residual stress and bulk defects in multicrys-
  talline silicon**
  V. Ganapati, S. Schoenfelder, S. Castellanos, S. Oener, R. Koepge, A. Sampson,
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Sebastian was born on the 1st of November, 1985, in Berlin, Germany. After finishing his high school degree as valedictorian and his community service in a Kindergarten, he moved to the south of the country, to the beautiful city of Konstanz. There, during his physics studies, Sebastian developed his strong interest in renewable energy technologies. This led him to join the photovoltaics community early on as a student researcher and to pursue a 6 month research internship with Prof. Dr. Tonio Buonassisi at MIT, USA. In 2012, he graduated with a 1.0 (A+) from the University of Konstanz under the supervision of Prof. Dr. Giso Hahn and Prof. Dr. Thomas Dekorsy with a thesis on defect characterization in multi-crystalline silicon solar cells.

In the same year, he joined the LMPV team, lead by Prof. Dr. Albert Polman, at AMOLF, Amsterdam. Supervised by Dr. Erik Garnett he conducted his research in the Nanoscale Solar Cells group. The results of this four year period are presented in this thesis.

After defending his thesis, Sebastian will work on sustainable long-term energy storage as a postdoctoral researcher.
The work described in this thesis was performed at the FOM-Institute AMOLF, Science Park 104, 1098 XG Amsterdam, The Netherlands.